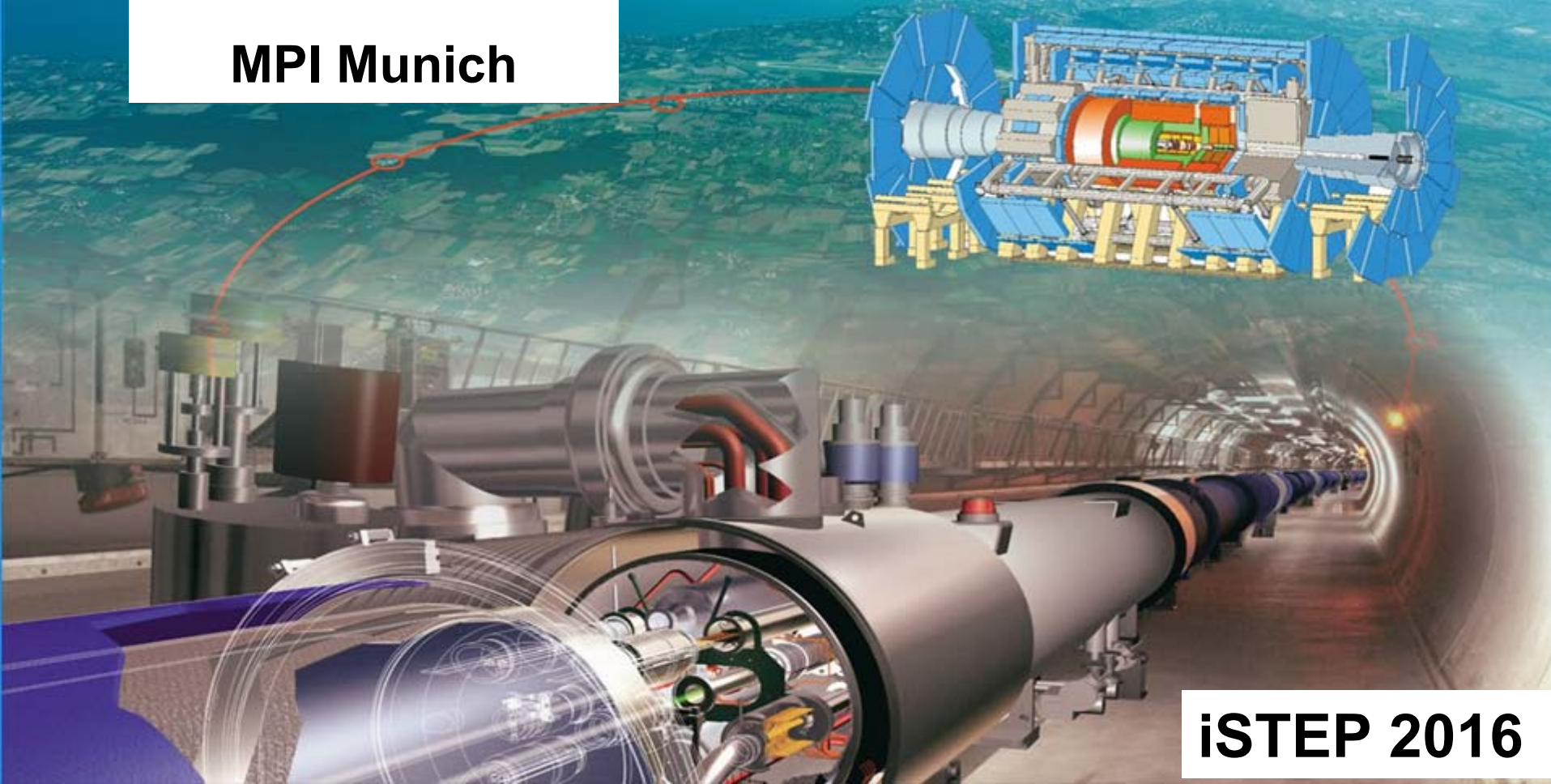


# Tracking Detectors for Collider Experiments

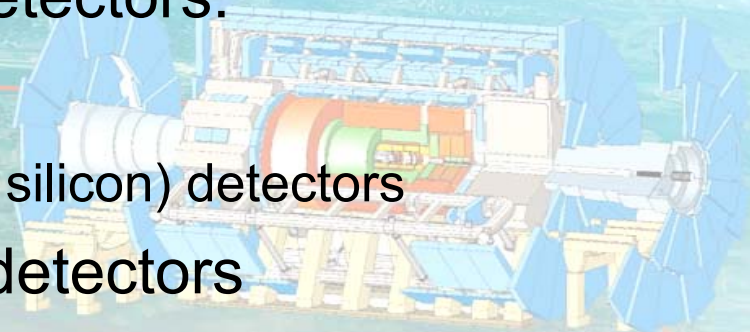
Hubert Kroha  
MPI Munich



iSTEP 2016

# Overview

- Detector concepts and systems at  $e^+e^-$  and  $pp$  colliders of the past 30 years and for the future.
- Charged particle inner tracking detectors:
  - Gaseous detectors
  - Solid state semiconductor (crystalline silicon) detectors
- Outer muon tracking and trigger detectors
  - Gaseous detectors
- Challenges in detector technology at the Large Hadron Collider (LHC)
- Challenges for future high-luminosity & high-energy colliders

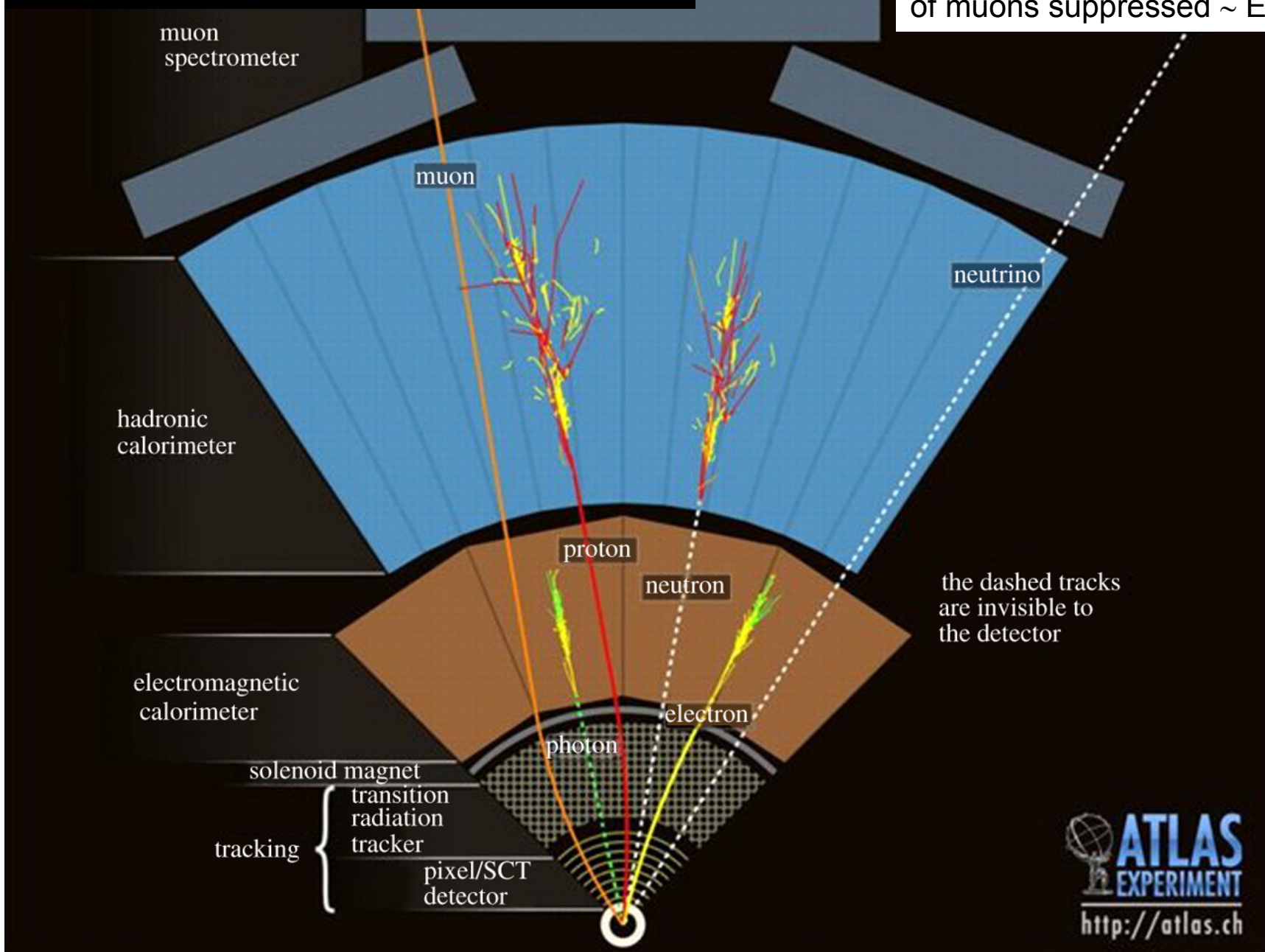


# Collider Detector Concepts and Systems

- Hermetic detectors, coverage of almost the full solid angle around the interaction point.
- Concentric cylindrical detector layers in the central “barrel” part, closed by endcap wheels (disks) in the forward/backward directions.
- Detectors at high-energy  $e^+ e^-$  colliders: LEP and beyond.
- Detectors at hadron colliders:  
Tevatron (pp), LHC and high-luminosity (HL)-LHC (pp),  
future pp colliders.

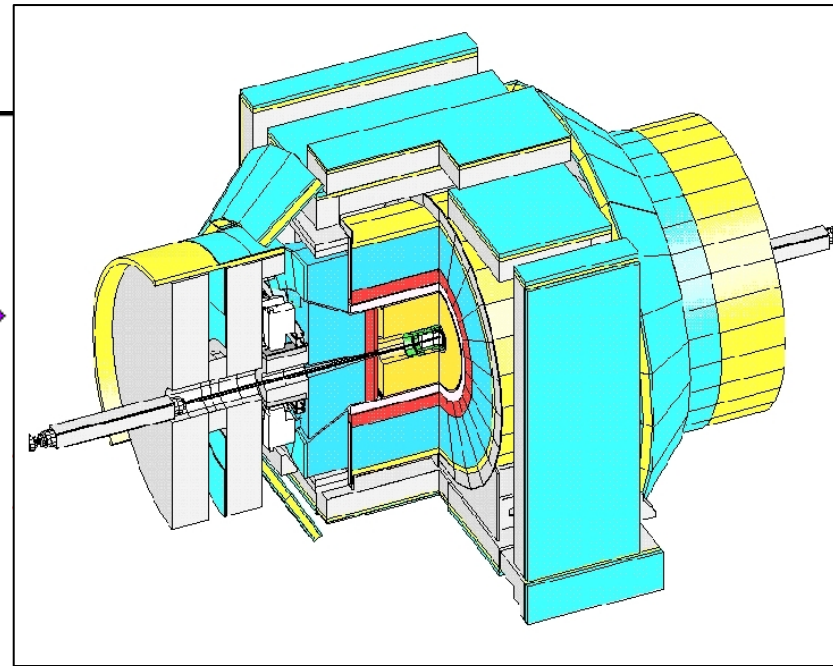
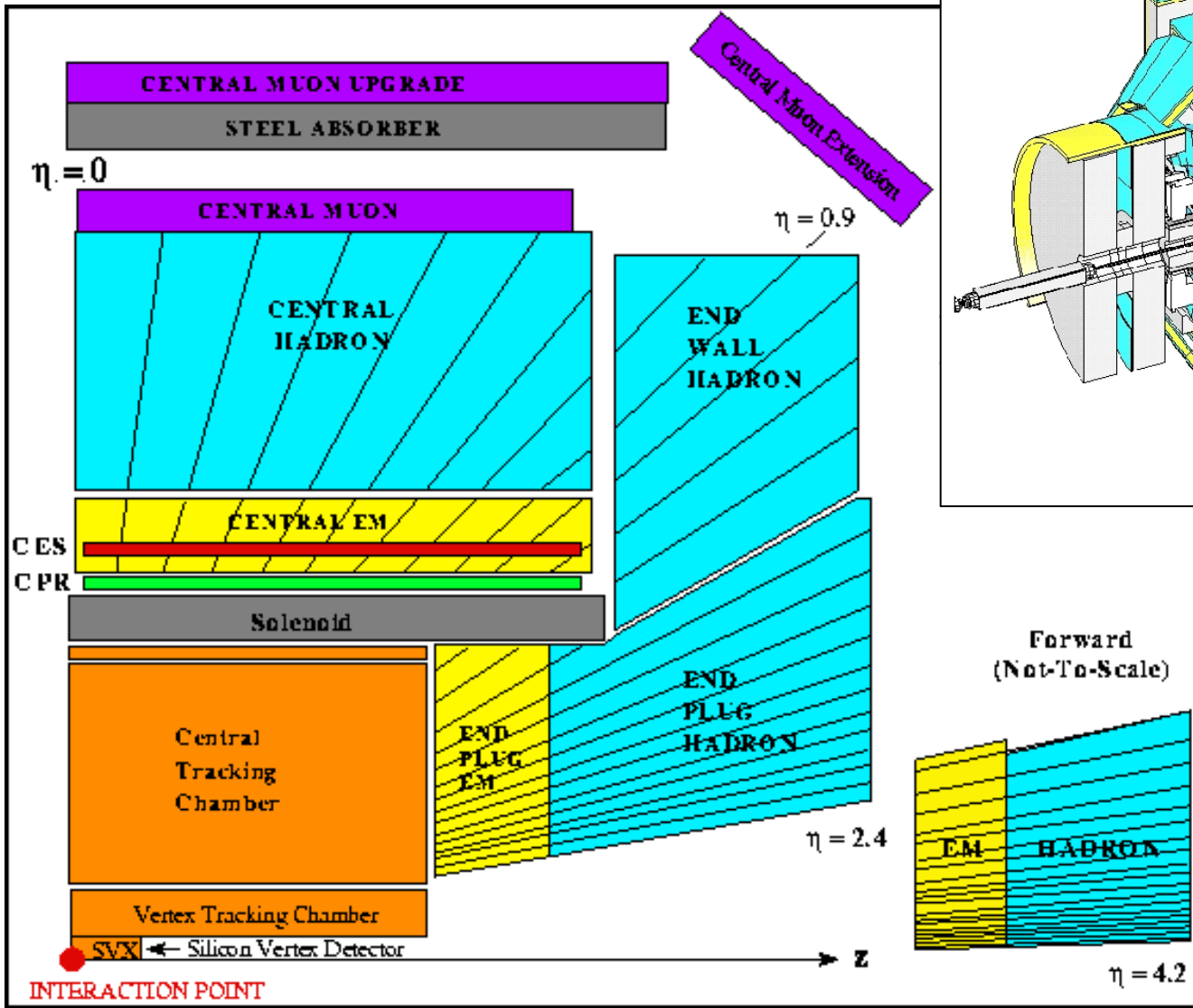
# Collider Detector Schematics

Bremsstrahlung energy loss of muons suppressed  $\sim E/m^2$



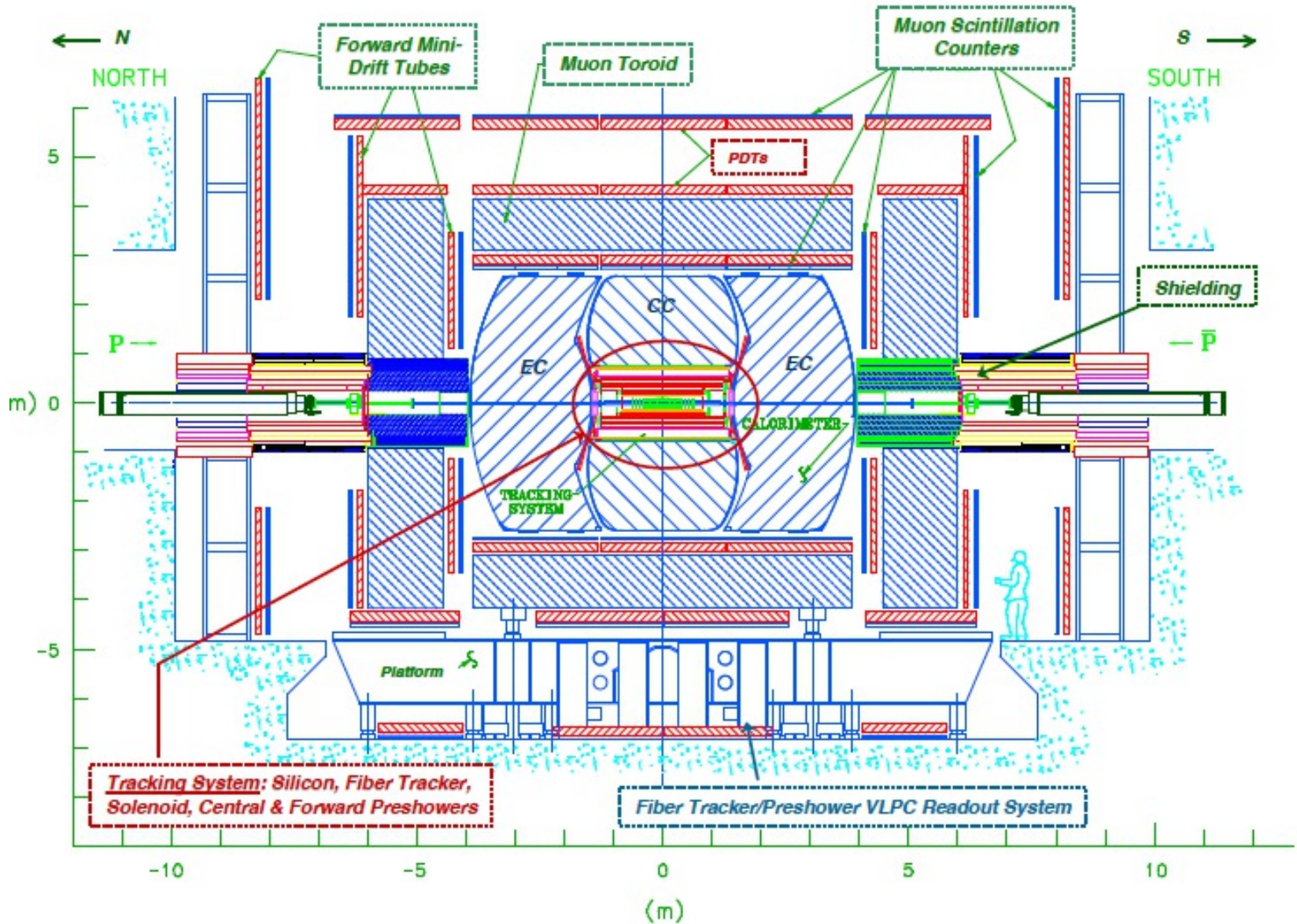
# Collider Detector Schematics

$$\eta = -\ln \left[ \tan \left( \frac{\theta}{2} \right) \right]$$



The CDF Detector at the Tevatron

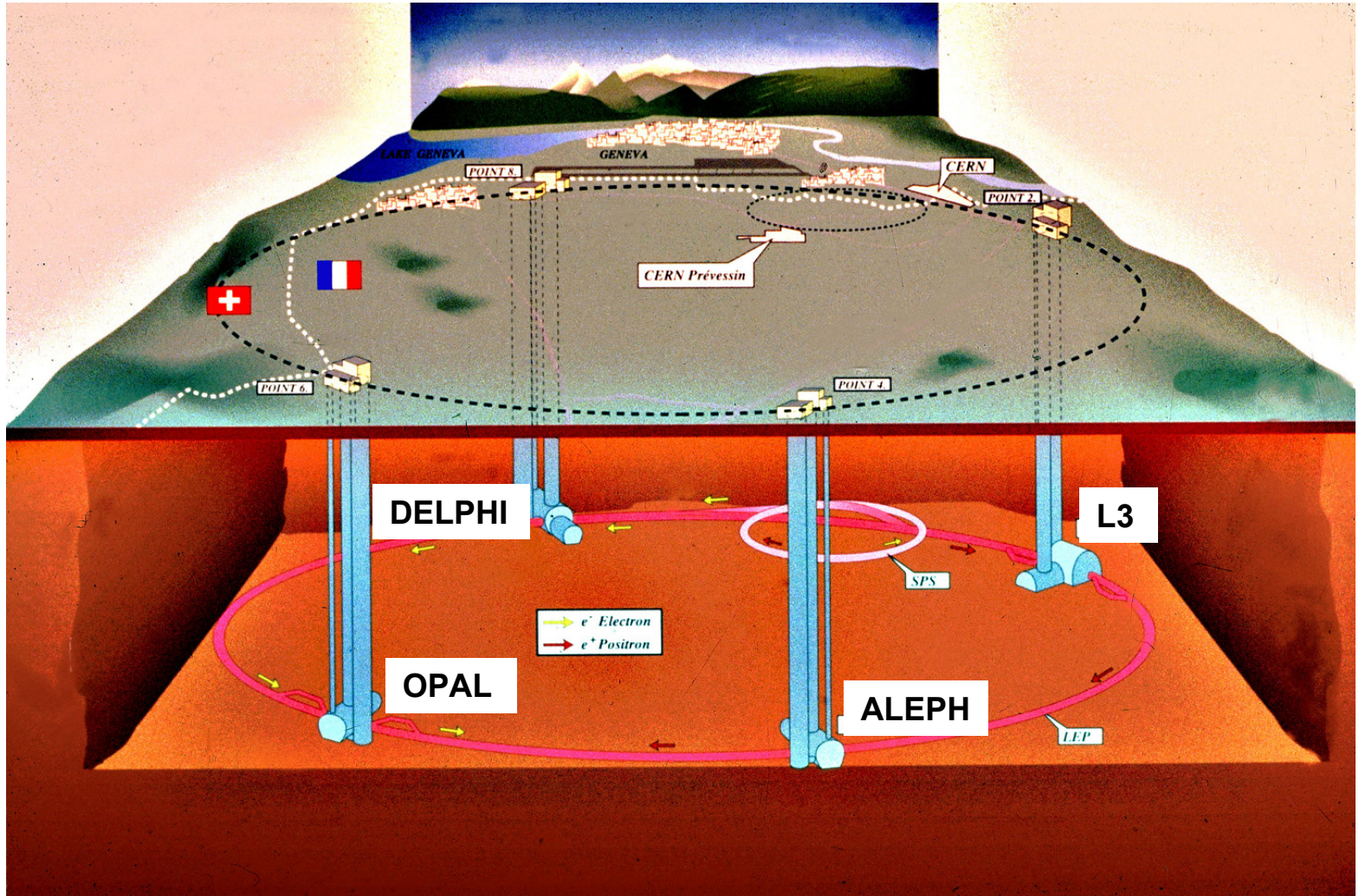
# The D0 Detector at the Tevatron



# Examples: Electron-Positron Colliders

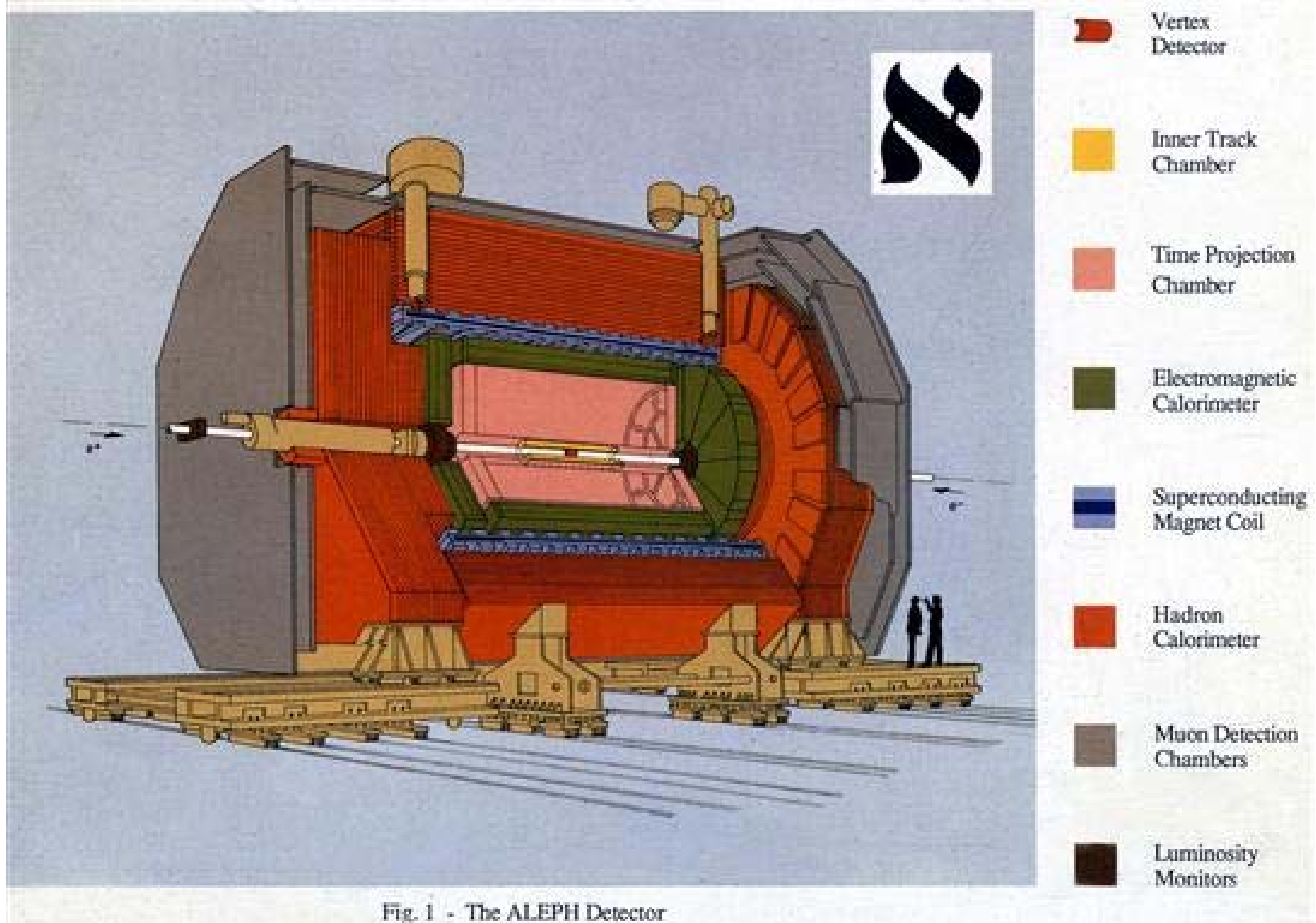
LEP at CERN, the largest so far, 27 km circumference, 1989-2000.

Electroweak precision measurements at the Z resonance, and above up to 208 GeV.



LEP detectors: first collider experiments with full solid angle coverage

## A typical LEP experiment: **The ALEPH Detector**





# Other e<sup>+</sup>e<sup>-</sup> Colliders and Experiments:

Highest center-of-mass energies at their time, before LEP and SLC

(search for the top quark):

**PEP at SLAC** (1979-90): Mark II (first central multi-wire drift chamber, first Si VTX detector), PEP-4 (first TPC) detectors, **max.  $E_{\text{cms}} = 29 \text{ GeV}$** .

**PETRA at DESY** (1978-86): Cello, Jade, Mark-J, Pluto, Tasso detectors, **max.  $E_{\text{cms}} = 45 \text{ GeV}$** , “discovery of the gluon” (3-jet events).

**TRISTAN at KEK** (1986-95): VENUS, SHIP, TOPAZ, AMY detectors, **max.  $E_{\text{cms}} = 64 \text{ GeV}$** .

**B meson physics experiments at the  $\Upsilon(4S)$  resonance,  $E_{\text{cms}} = 10.58 \text{ GeV}$ :**

**DORIS at DESY** (1974-93): Pluto (first superconducting solenoid), ARGUS detectors ( $B\bar{B}$  mixing).

**CESR at Cornell Univ.** (1979-2008): CUSB, CLEO I, II and CLEO-c detectors.

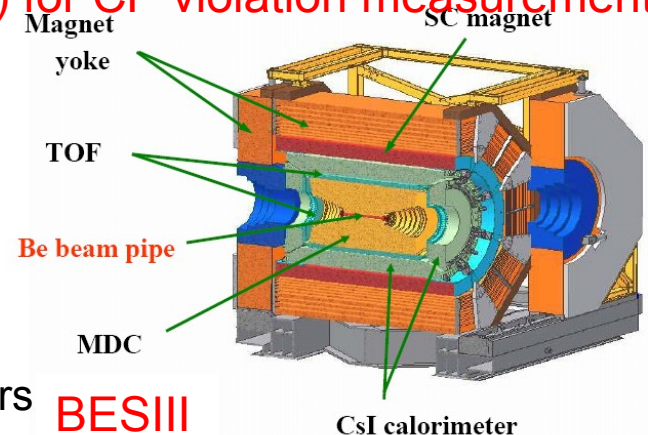
**“B factories” with asymmetric beam energies at  $\Upsilon(4S)$  for CP violation measurement:**

**PEP-II at SLAC** (1999-2008): BaBar detector

**KEKB at KEK** (since 1999): Belle I, II detectors  
(highest e<sup>+</sup>e<sup>-</sup> luminosity → SuperKEKB).

**Charm,  $\tau$  physics at  $E_{\text{cms}} = 2.0 - 4.2 \text{ GeV}$ :**

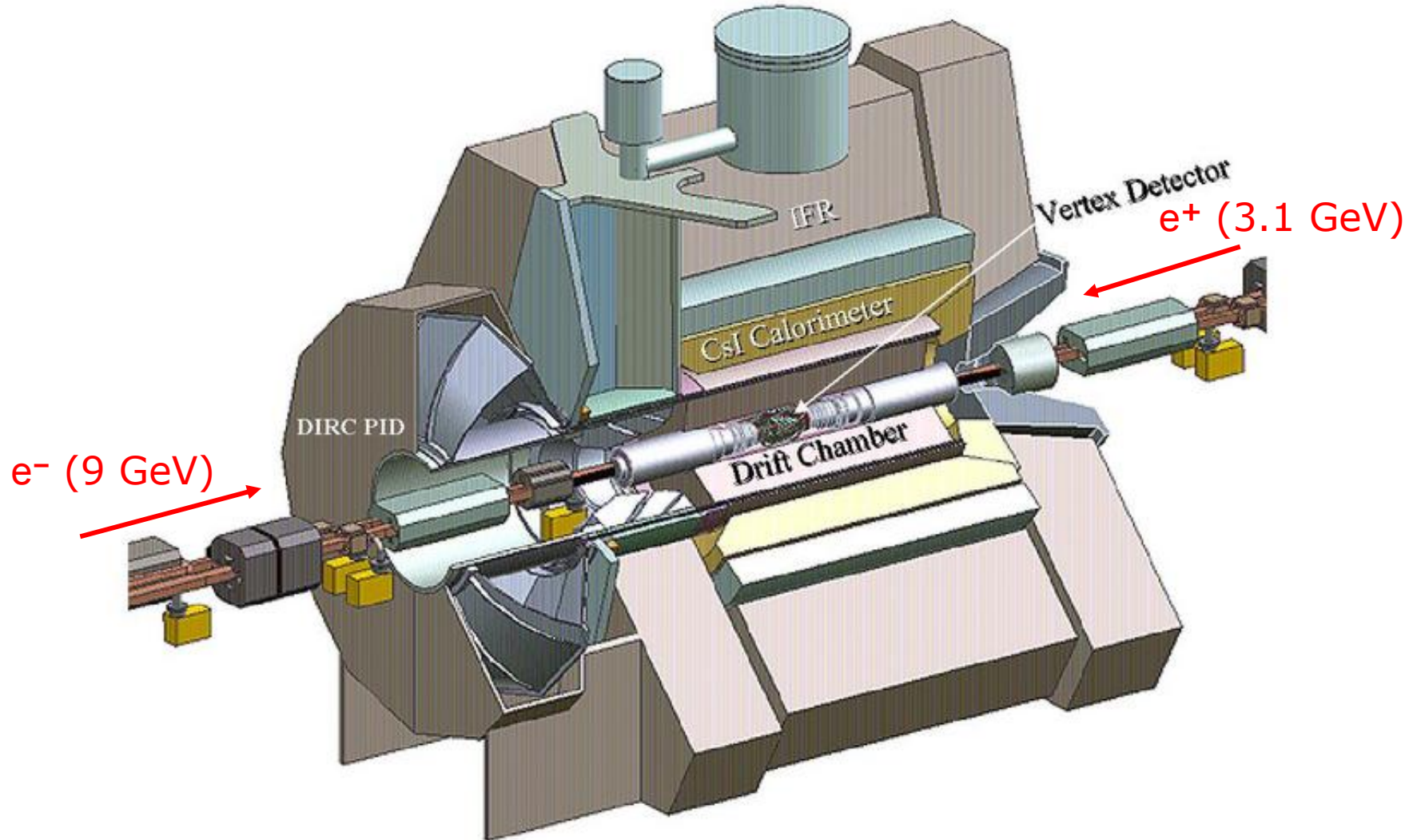
**BEPC at IHEP Beijing** (since 1988): BES I, II, III detectors



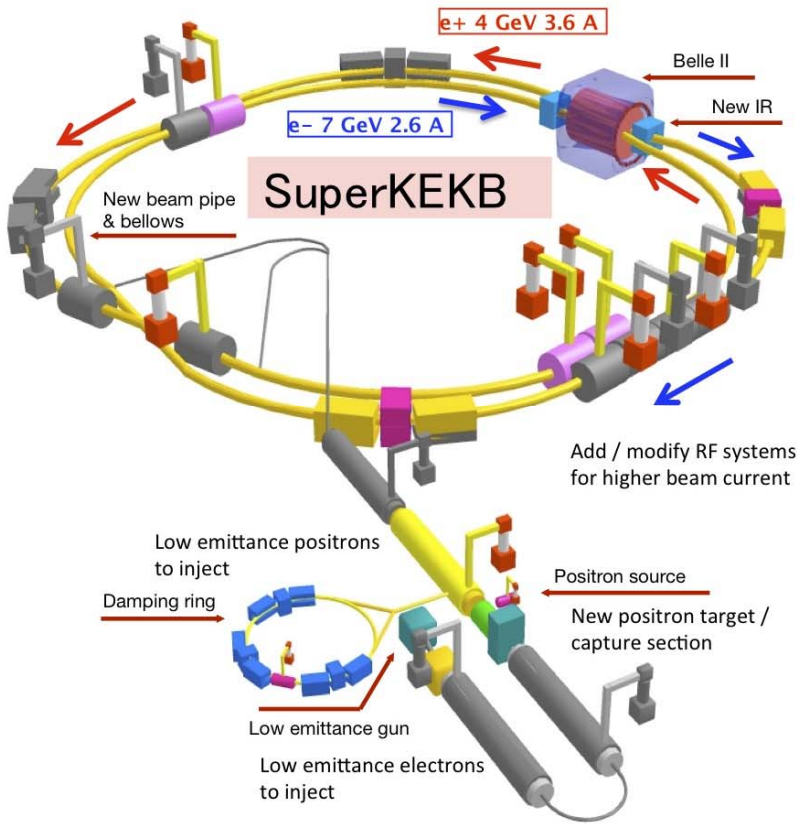
# Babar Detector at the SLAC Asymmetric B Factory

Y(4S) system boosted in electron beam direction.

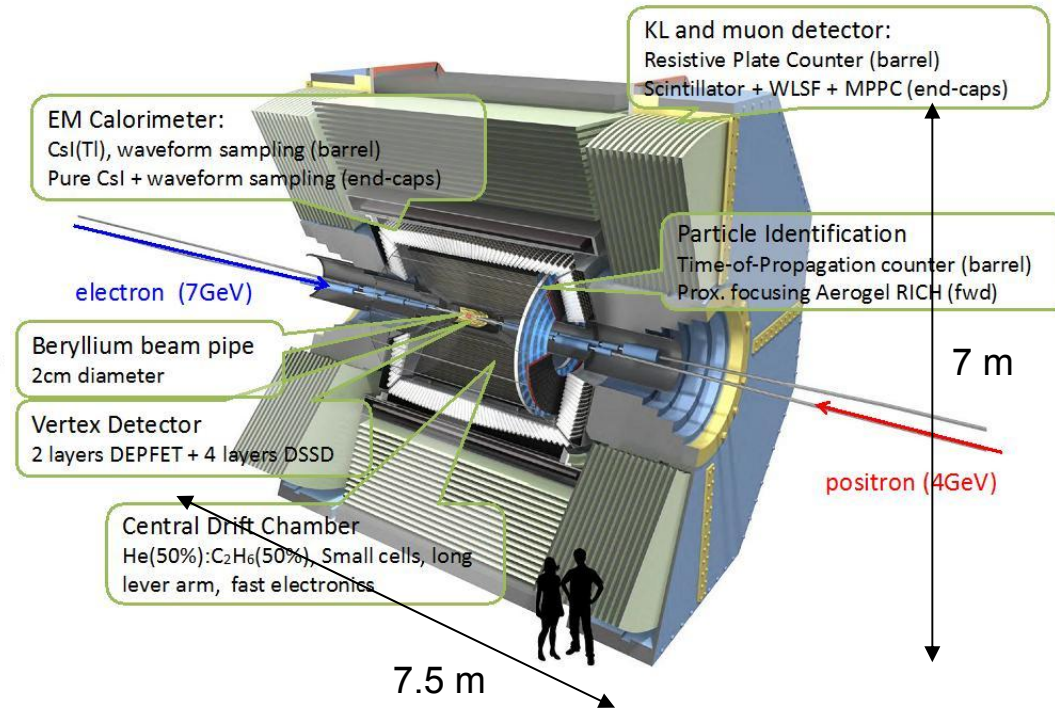
Asymmetric detector coverage hermetic in forward direction.



# B Meson Factory Experiments: Belle II at SuperKEKB



## Belle II Detector

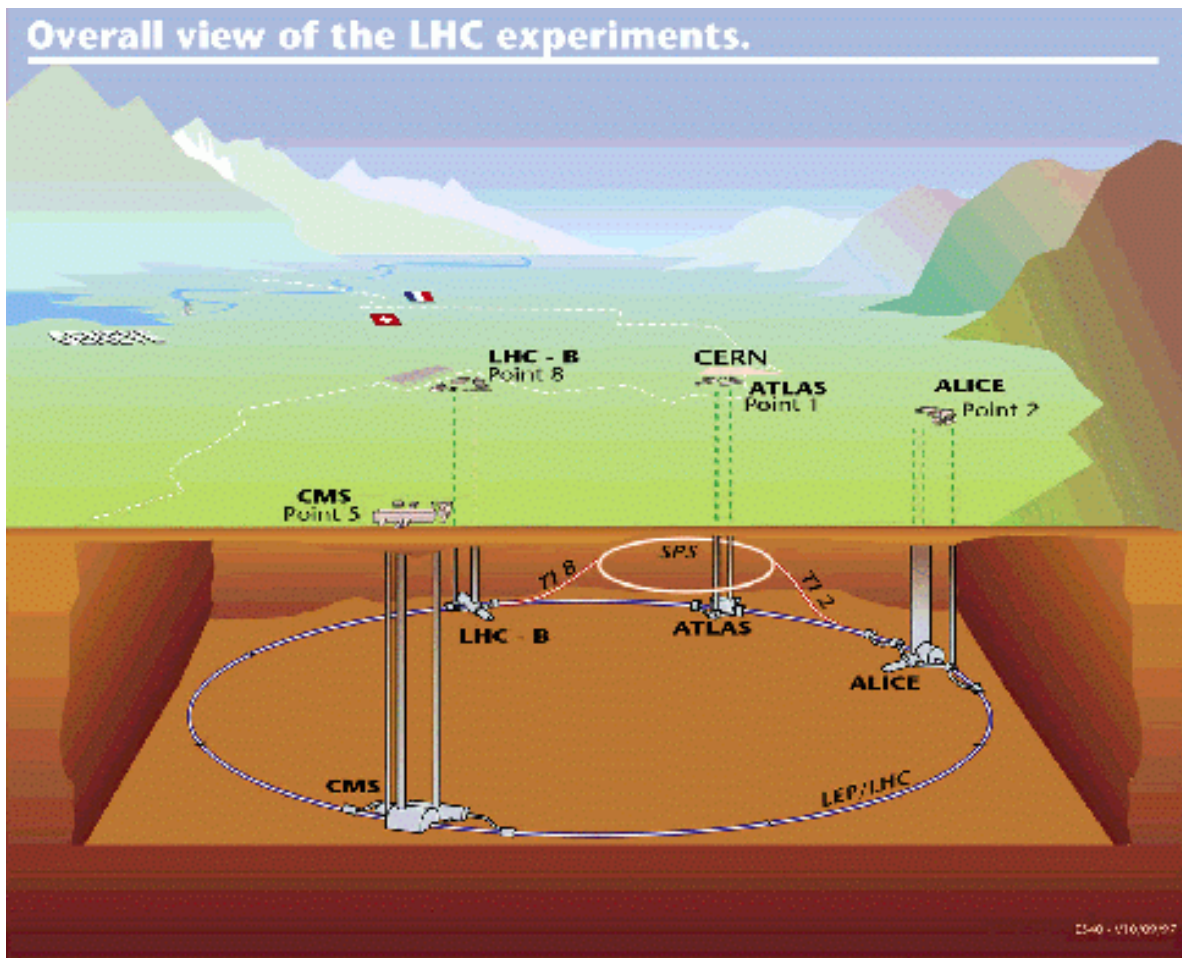


# Examples: Hadron Colliders

The **Large Hadron Collider LHC**, successor of LEP in the tunnel since 2009, with the highest pp energies,  $E_{\text{cms}} = 7, 8, 13, 14$  TeV, and luminosities.

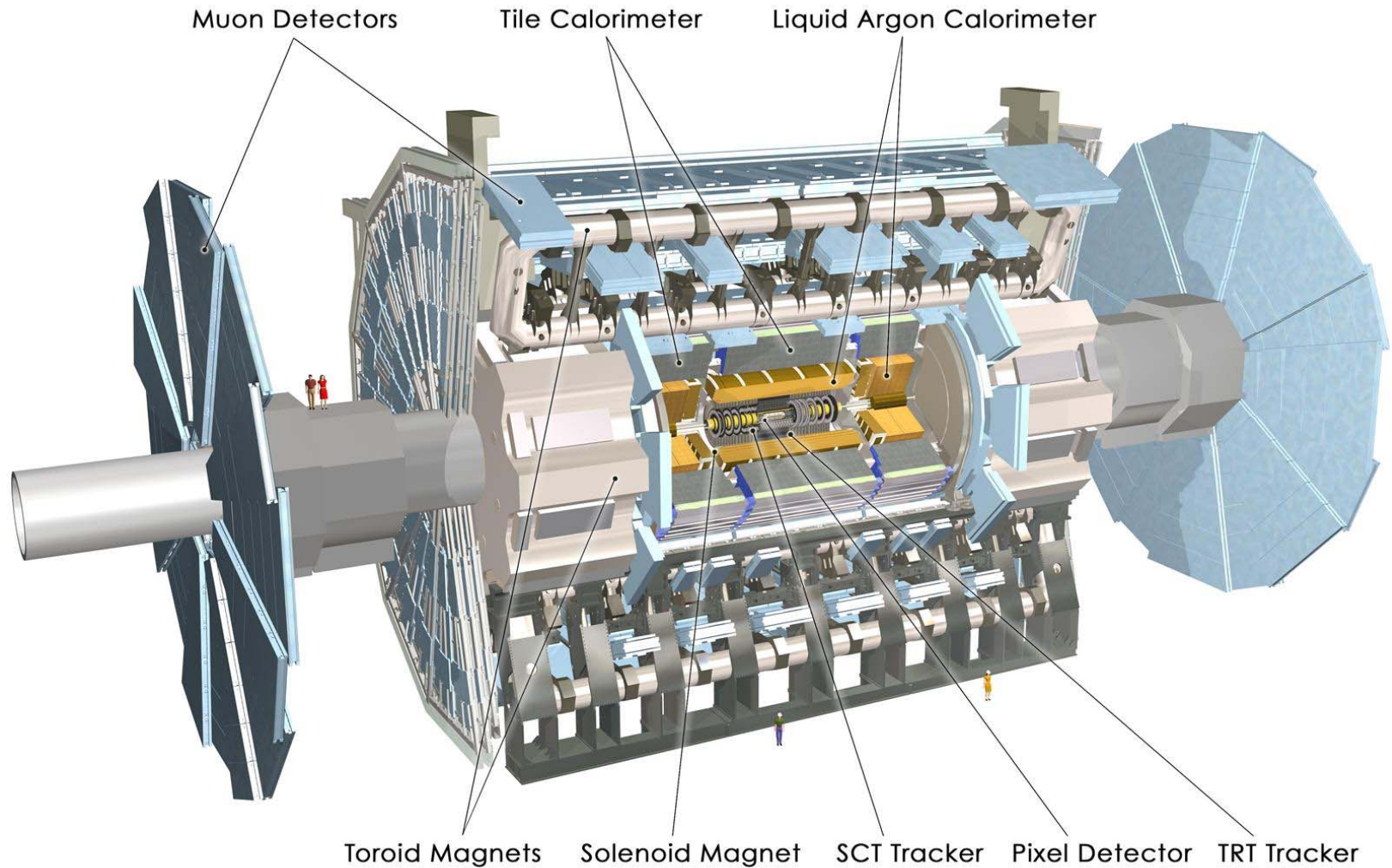
1200 superconducting dipole magnets. First hermetic proton collider experiments: **ATLAS and CMS**.

Discovery of the Higgs boson 2012 and search for physics beyond the Standard Model.



# The ATLAS Detector at the LHC with large Muon Spectrometer and SC Toroid Magnets

Standalone muon momentum measurements in the world's largest air-core magnet for the first time in a collider detector.



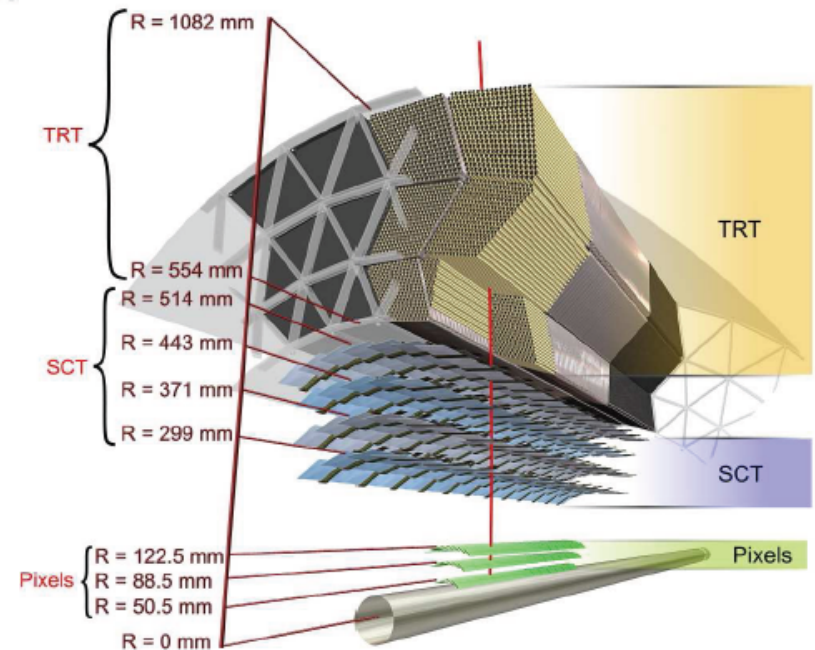
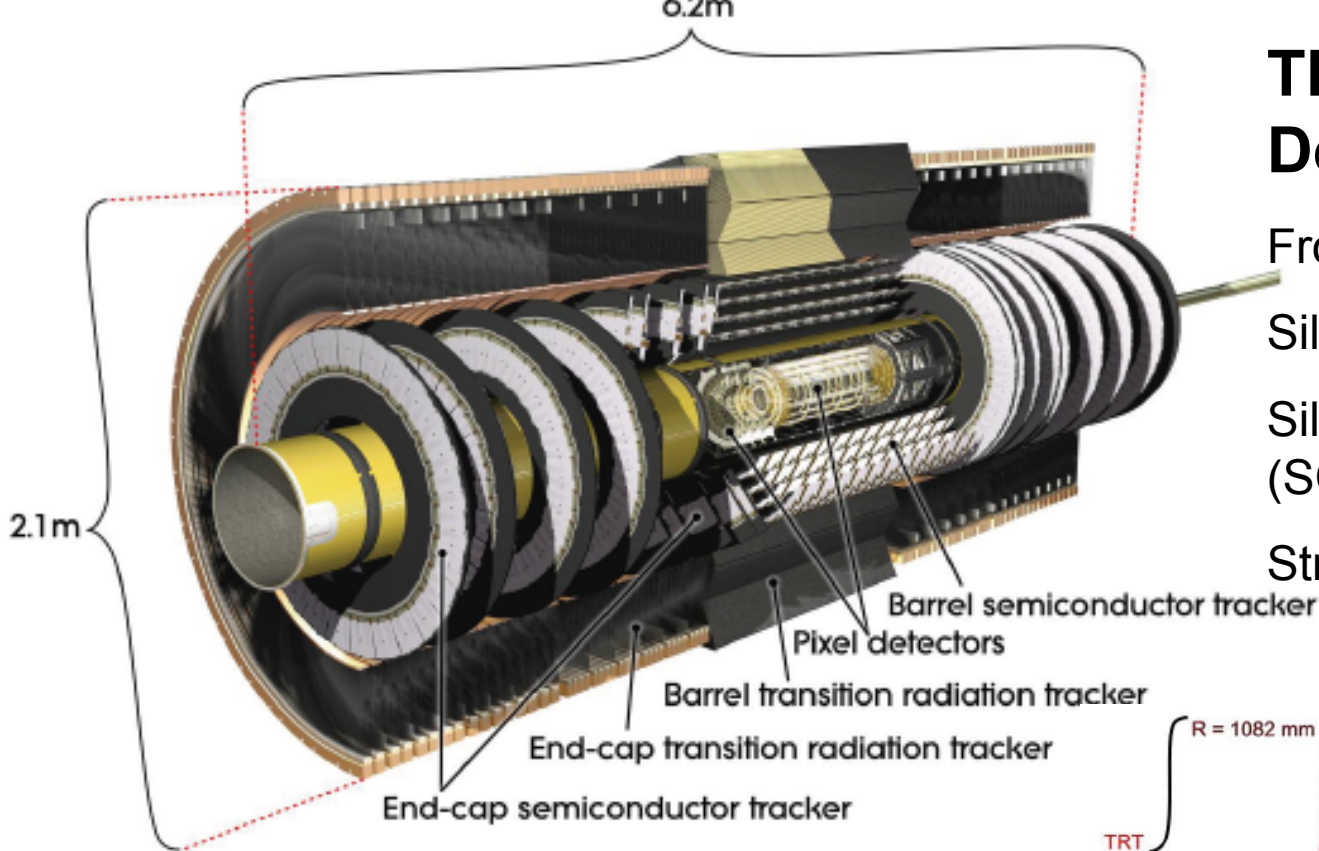
# The Inner Tracking Detector of ATLAS

From the beam pipe outwards:

Silicon pixel detector (Pixels)

Silicon microstrip detector (SCT)

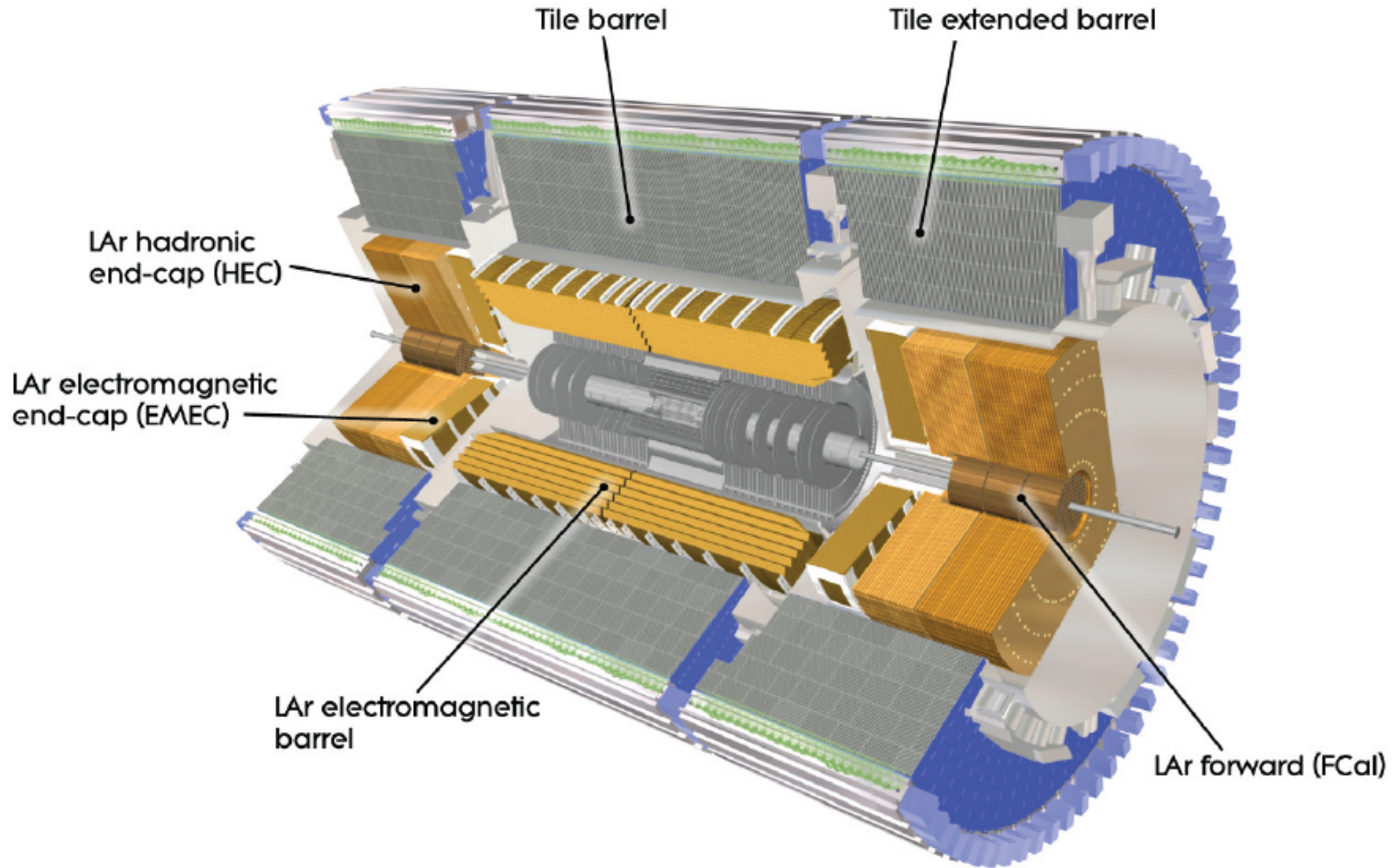
Straw drift tube tracker (TRT)



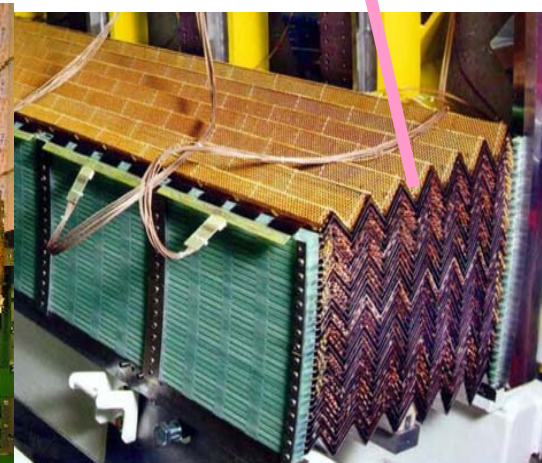
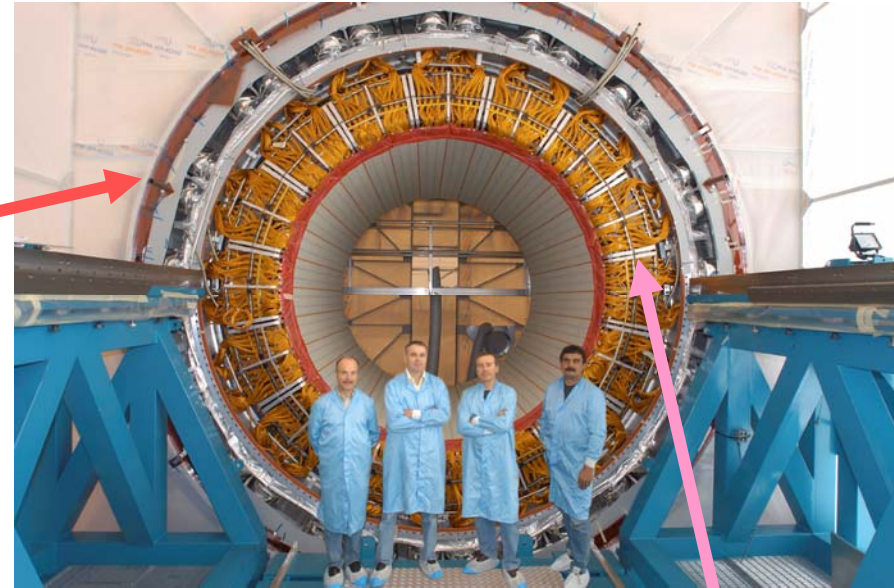
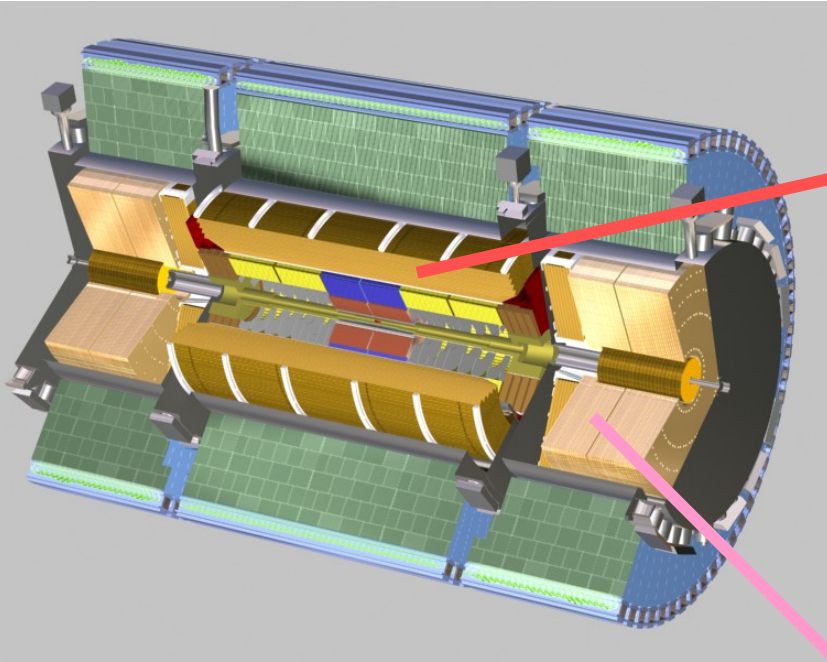
# ATLAS Calorimeter System

Electromagnetic calorimeter: liquid argon (active)-copper (absorber) sampling.

Hadron calorimeters: scintillating tile (active)-steel (absorber) and LAr-copper/ tungsten sampling



# ATLAS Calorimeter System



Accordeon shaped interleaved absorber plates and readout boards in liquid argon

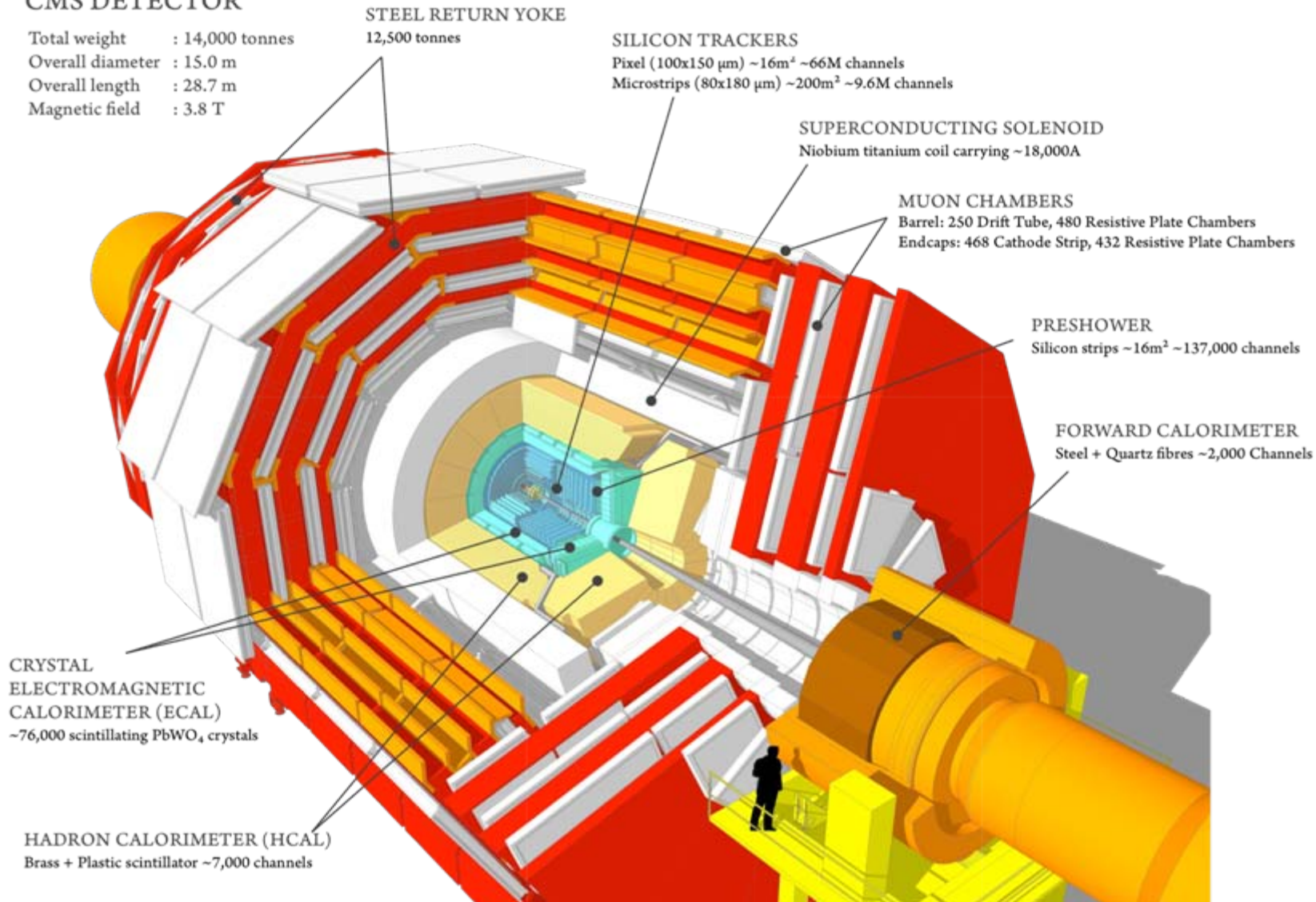
- Electromagnetic liquid-argon (LAr) sampling calorimeter.
- Fine segmentation in  $\eta$ - $\phi$  and also in depth.
- Large solid angle coverage.
- Hadron calorimeters: absorb all remaining particles except muons



# The CMS Detector at the LHC

## CMS DETECTOR

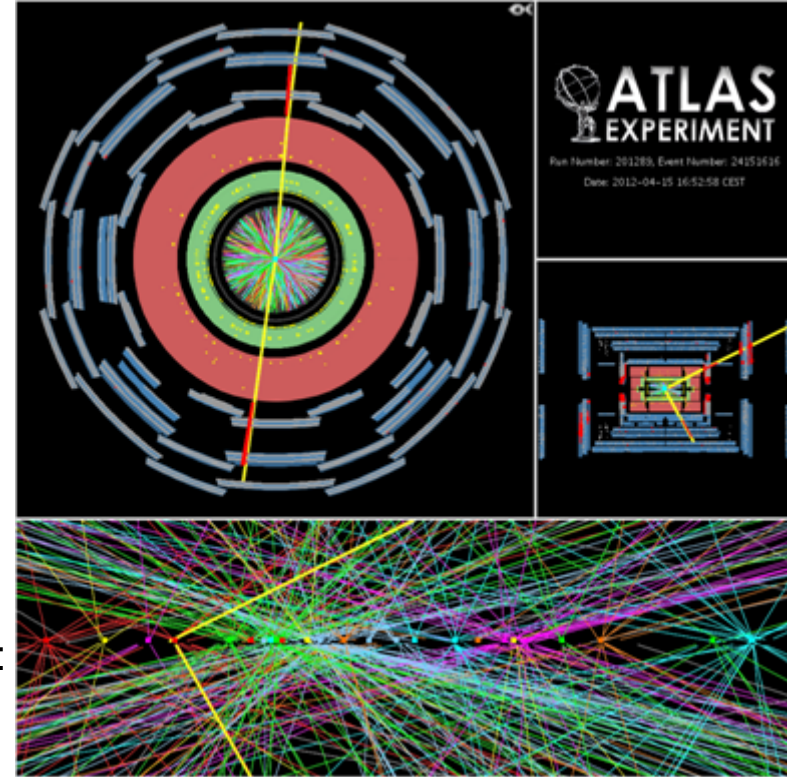
Total weight : 14,000 tonnes  
Overall diameter : 15.0 m  
Overall length : 28.7 m  
Magnetic field : 3.8 T



# Challenges for LHC Detectors

Highest beam energy and highest luminosity in proton collisions:

- **Proton bunch crossings every 25 ns**  
⇒ very fast detectors and readout electronics.
- **High proton density per bunch:**
  - More than 20 pp reactions per bunch crossing (event pile-up).
  - $\mathcal{O}(1000)$  particles produced per crossing.⇒ high detector granularity.
- **Unprecedented irradiation doses** from interaction of collision products with detector, shielding, cavern walls:
  - Inner tracking detectors  $> 10^{14}$  protons/cm<sup>2</sup>
  - Outer muon detectors  $> 10^{11}$  neutrons and  $\gamma$ -rays/cm<sup>2</sup>⇒ radiation hard detectors and electronics.
- Very high data rates  $> 300$  Mbyte/s.



$Z \rightarrow \mu\mu$  event with 25 reconstructed interaction vertices already in Run 1

Required dedicated R&D program over many years. Challenge 10 x higher for HL-LHC!

# Previous Hadron Colliders and Experiments:

Highest center-of-mass energies for discoveries:

**ISR  $p\bar{p}$  at CERN** (1971-84): first hadron collider,  $\text{max. } E_{\text{cms}} = 62 \text{ GeV}$ , still non-hermetic detectors.

**SppS  $p\bar{p}$  at CERN** (1981-93): UA1 and UA2 experiments,  $E_{\text{cms}} = 630\text{--}900 \text{ GeV}$ , discovery of the W and Z bosons.

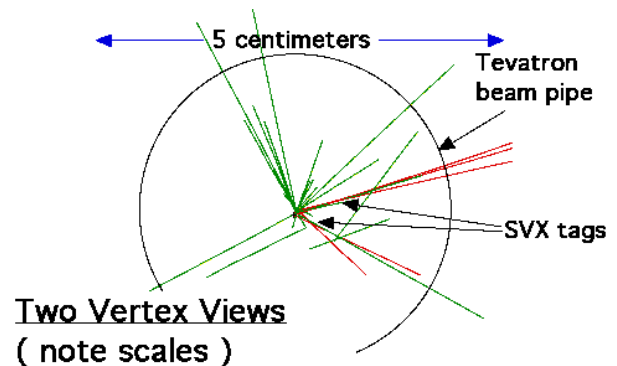
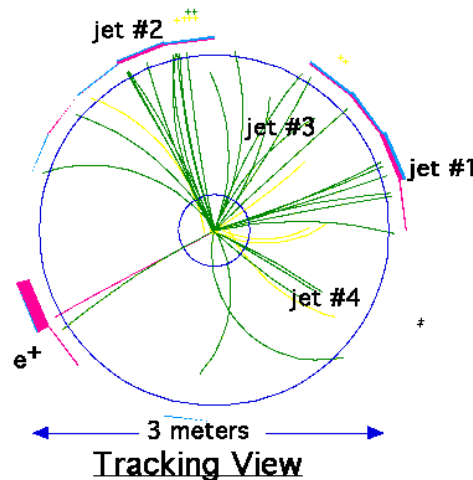
**Tevatron  $p\bar{p}$  at FNAL** (1983-2011): CDF and D0 experiments,  $E_{\text{cms}} = 1.8\text{--}1.96 \text{ TeV}$ , discovery of the top quark 1995, superconducting dipole magnets.

**RHIC at BNL** (since 2000): Au-Au collisions, STAR and PHENIX experiments.

# Charged Particle Tracking Detectors

- Track reconstruction and charged particle identification close to the interaction point (“Inner Detector”).
- Inside (homogeneous solenoidal) magnetic field for track curvature and momentum measurement.
  - Minimum scattering material in tracker.
- Reconstruction of primary interaction point(s) (up to ~60 at LHC!).
- Reconstruction of displaced decay vertices.
- Jet and b quark jet identification.

Top quark pair event in the CDF tracking detector with top decays into b jets containing long-lived B mesons and  $W \rightarrow l\nu$  and  $qq$



# Types of Tracking Detectors

## Gaseous detectors:

Energy deposition of charged particles by ionisation of gas atoms.

Evolution with increasing granularity and intrinsic resolution:

- Multi-wire proportional detectors
- Multi-wire drift chambers
- Micro-pattern gas detectors: GEM, Micromegas detectors

## Solid state detectors:

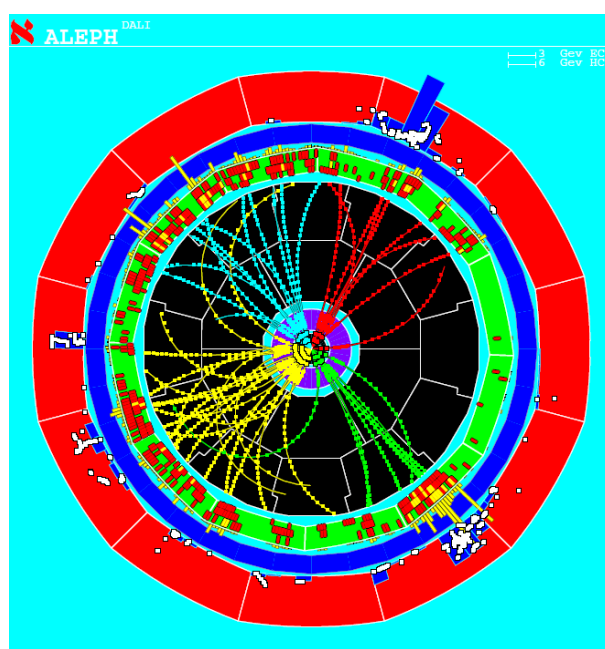
Energy deposition by creation of electron-hole pairs in the crystal

- Silicon micro-strip detectors
- Silicon pixel detectors

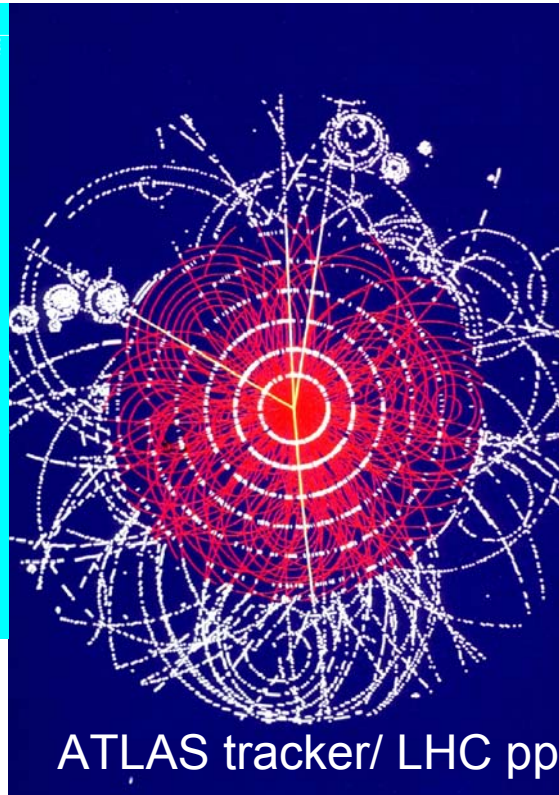
Large areas vs. high granularity (no. of electronics channels),  
radiation resistance and rate capability

# Gaseous Central Tracking Detectors

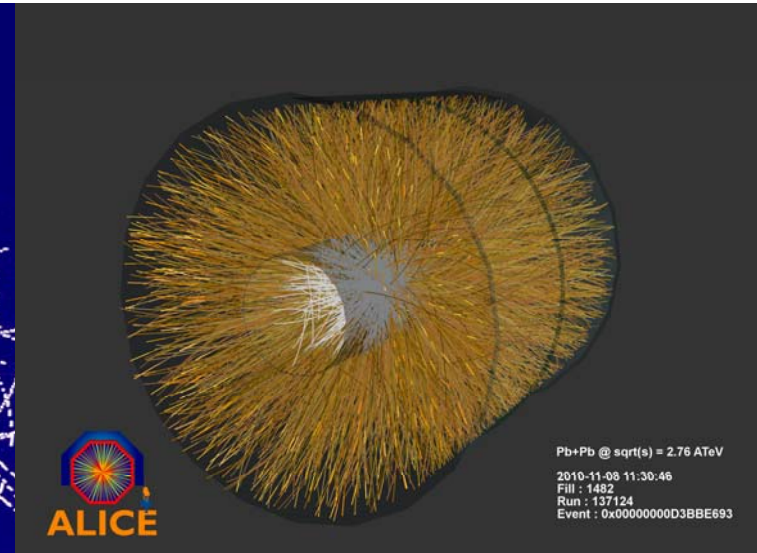
- Track pattern recognition in multi-particle/ multi-jet final states.
- Precise track and momentum measurement in (solenoidal) magnetic field.
- Low-mass detectors, minimise multiple scattering.



ALEPH TPC/ LEP  $e^+e^-$



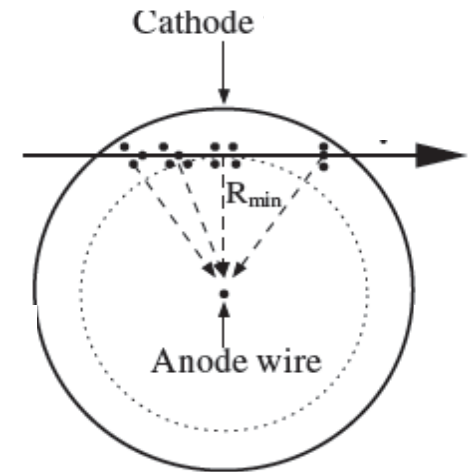
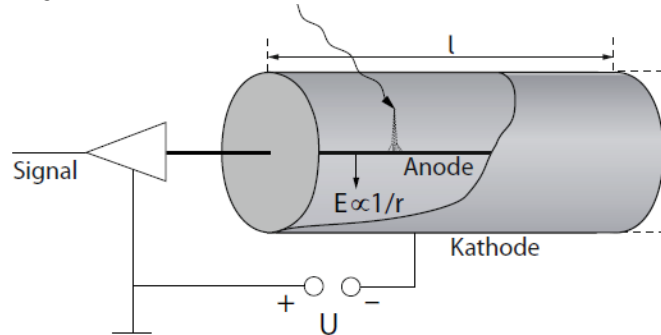
ATLAS tracker/ LHC pp



ALICE TPC/ LHC Pb-Pb

# Wire Tracking Detectors

- **Detection principle:** ionisation of gas atoms by charged particles along the track.
- **Argon:** low ionisation energy and relatively cheap, most frequently used as ionisable medium (also Xenon, Krypton) together with other admixtures.
- Apply electric field to collect primary ionisation electrons on anode sense wires while positively charged argon ions drift more slowly to the cathode:  
**wire chambers.**
- High electric field near the wires  $\sim 1/r$  accelerates the drifting electrons leading to avalanche of secondary ionisation of the argon atoms by the electrons: **gas amplification** (in proportional mode  $\sim$  primary ionisation).
- Charge signal at the wire is electronically amplified.

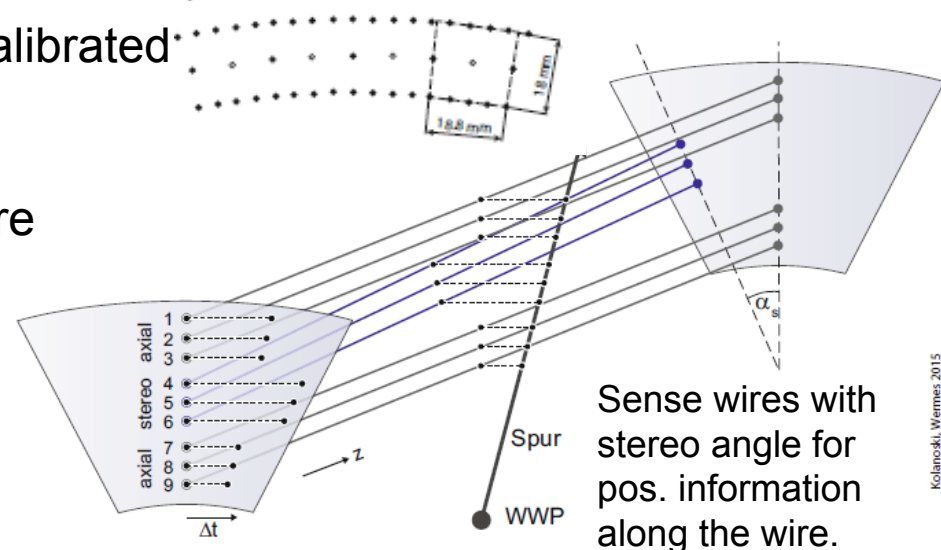
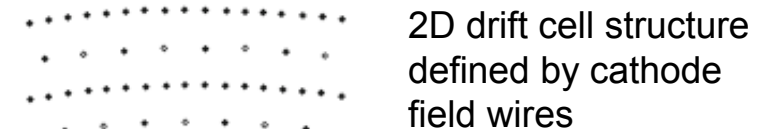
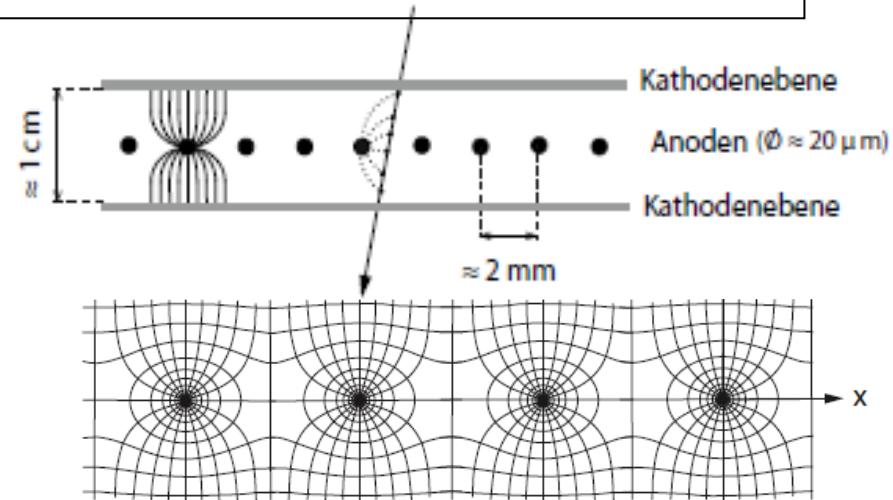


# Multi-Wire Drift Chambers

- Track position detection by closest wire in **multi-wire gas detectors (MWPC)**.
- Higher precision with fewer wires (and electronics channels) by measuring the drift time of the primary ionisation electrons to the anode wires: **drift chambers**.
- The drift time is converted into the closest distance of the wire to the track via the calibrated **space-to-drift time (r-t) relation**.

Drift velocity  $v$  depends on the gas mixture and operating parameters.

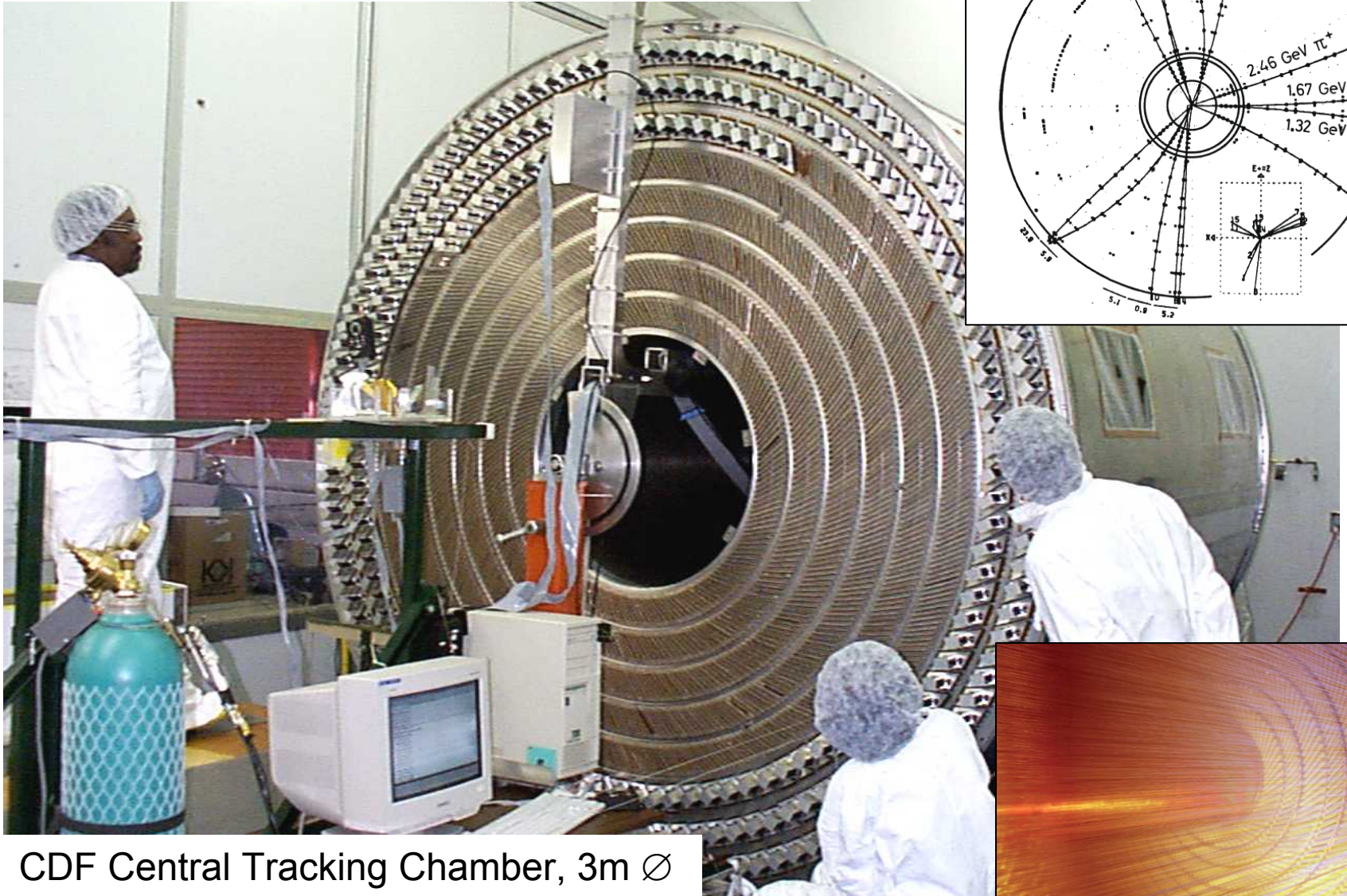
Non-linear  $r-t$  relation if  $v$  is dependent on the local electric drift field strength.



Sense wires with stereo angle for pos. information along the wire.



# Large cylindrical multi-wire drift chambers for central tracking of collider detectors

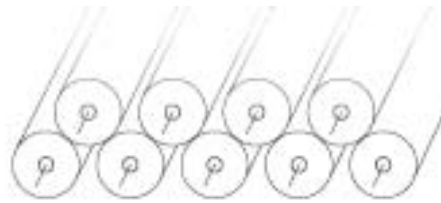
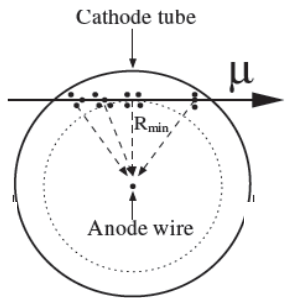


CDF Central Tracking Chamber, 3m  $\varnothing$

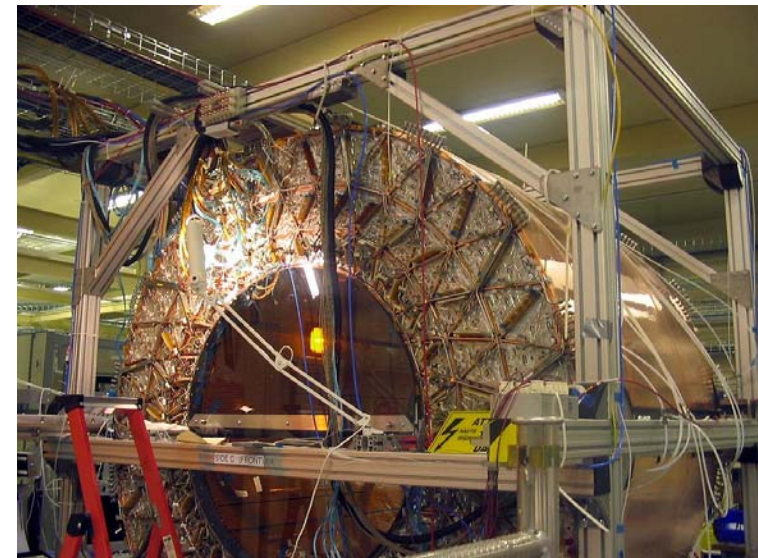
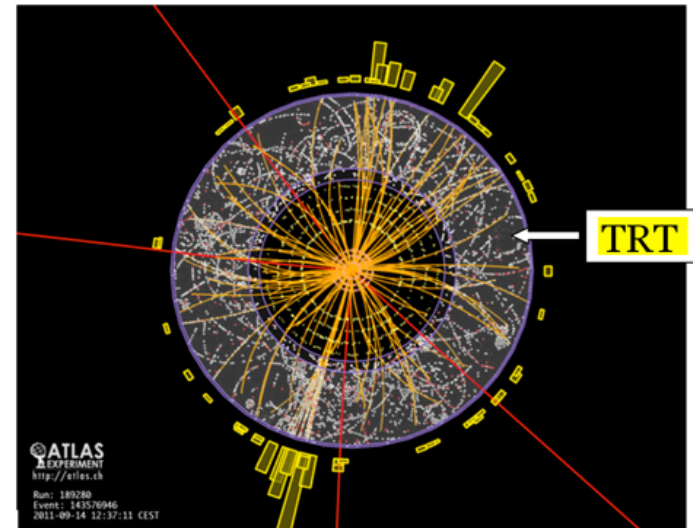
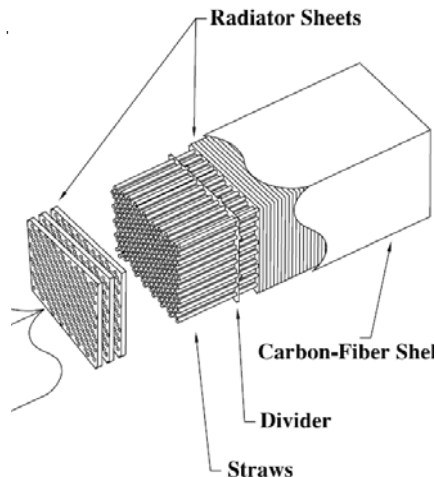
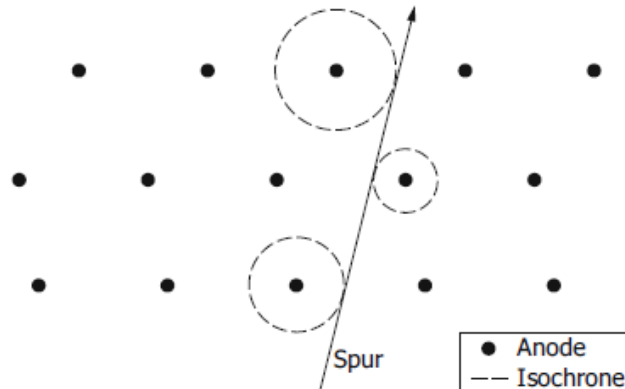
# Drift Tube Detectors

## ATLAS “Straw” Drift Tube Tracker, TRT:

- 50000 kapton drift tubes of 4 mm  $\varnothing$  and 0.7 m wire length in 35 cylindrical layers
- Xe:CO<sub>2</sub>:O<sub>2</sub> (70:27:3) gas mixture (prevent aging!)
- Occupancy above 30% at LHC design luminosity



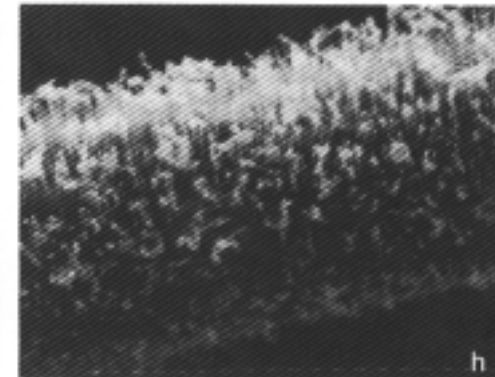
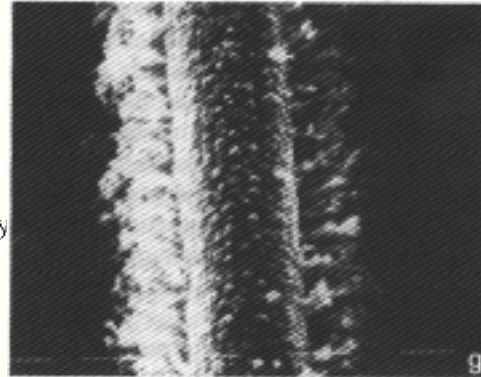
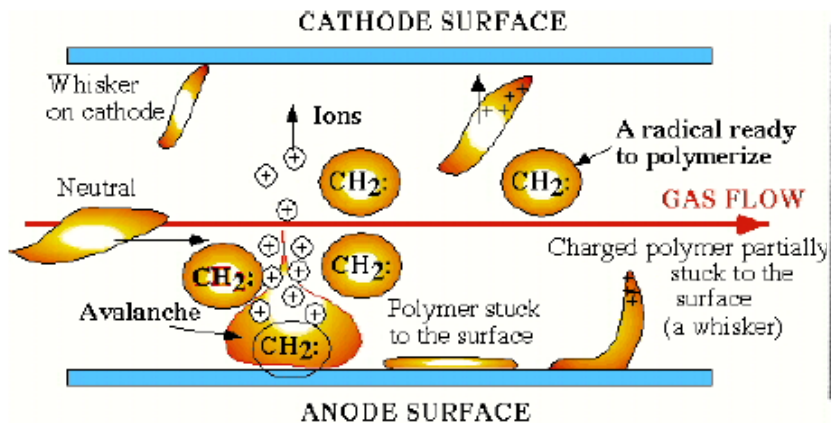
## Track reconstruction



# Wire Chamber Aging

## Phenomenon of wire chambers under irradiation:

- Hydro-carbon and silicate radicals of drift gas molecules or contaminants created in the plasma of the avalanche near the wire polymerise (plasma chemistry) and form deposits on the sense wire which eventually make it inefficient.



- In particular at very high irradiation rates like at LHC:

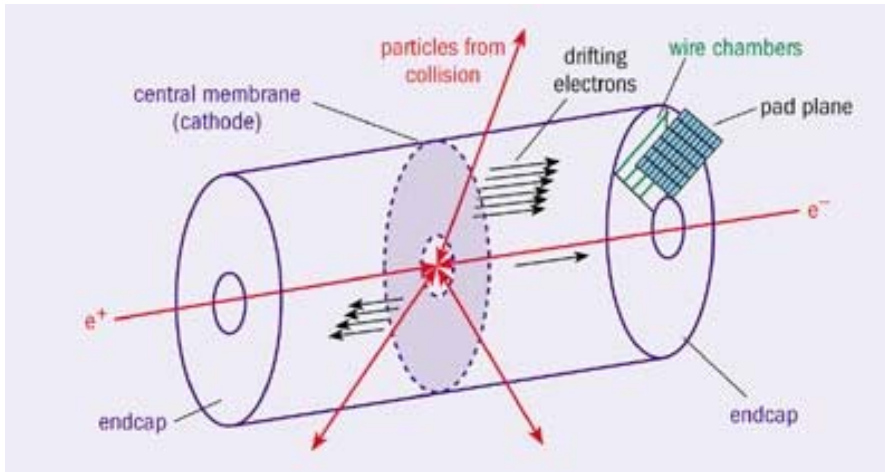
**avoid hydro-carbons and any contamination in the gas to prevent aging,**  
even in the outer muon detectors.

“Standard gases” now: Ar(Xe):CO<sub>2</sub> (CO<sub>2</sub> admixture for quenching of avalanches).

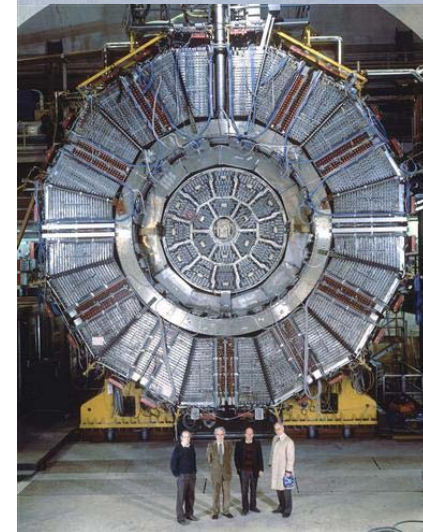
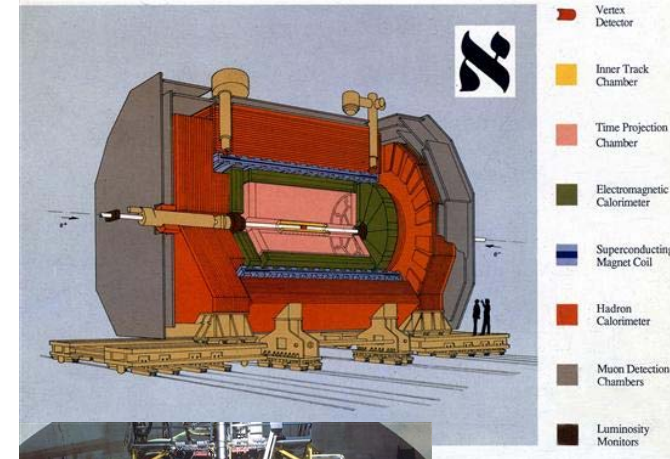
So far successful at LHC.

# Drift detectors without wires: Time Projection Chambers (TPC)

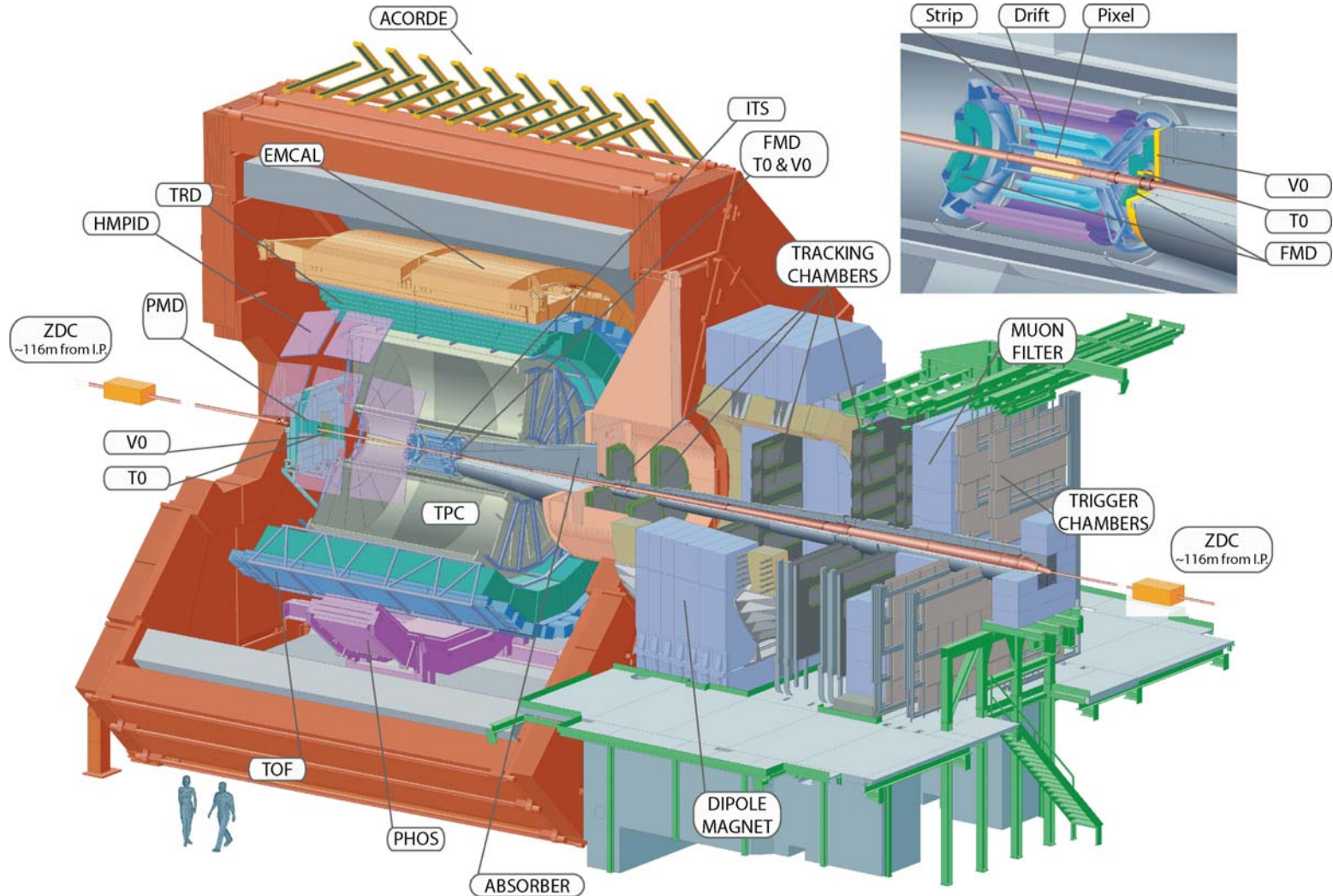
Large drift volume with electric field parallel the solenoidal magnet field.  
Ionisation electrons drift towards the endplates where they are detected by MWPCs  
(and nowadays GEM and Micromegas detectors).



- First employed in the PEP-4 experiment at SLAC.
- Used by the LEP detectors ALEPH and DELPHI.
- Now used in heavy ion collision experiments with very high track densities like STAR at RHIC and ALICE at LHC, and proposed for detectors at future high-energy  $e^+e^-$  colliders like ILC.

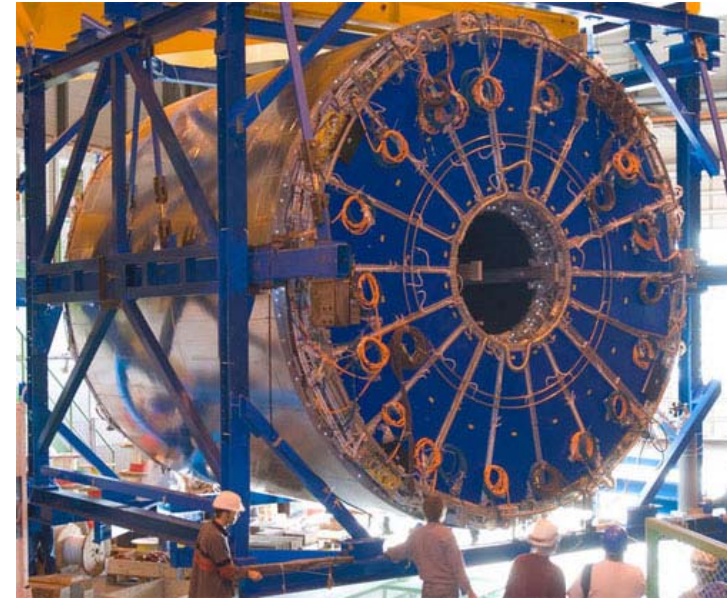
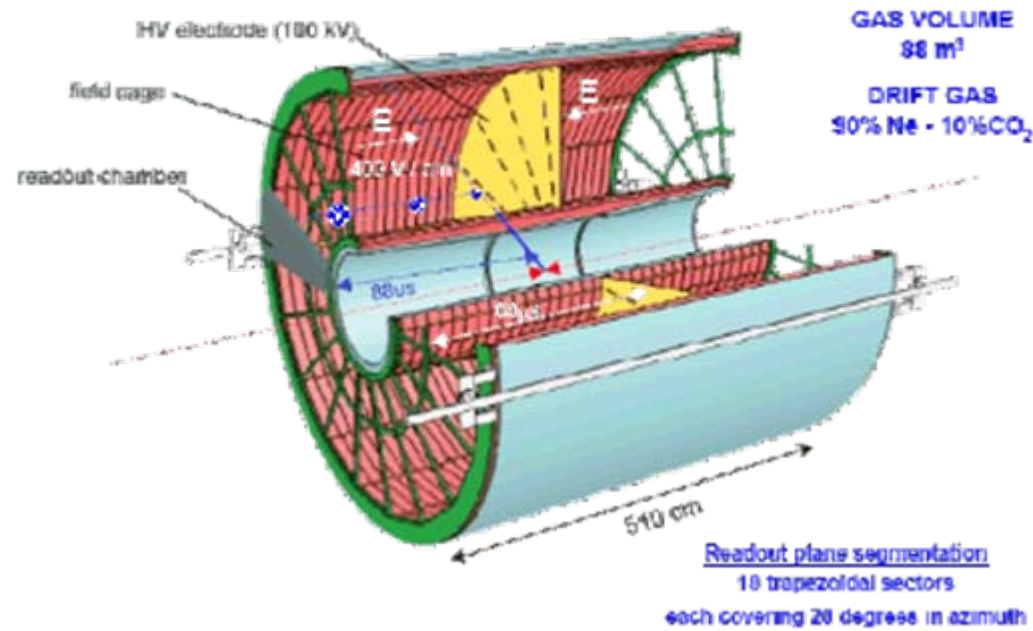


# ALICE detector for study of heavy ion collisions at the LHC

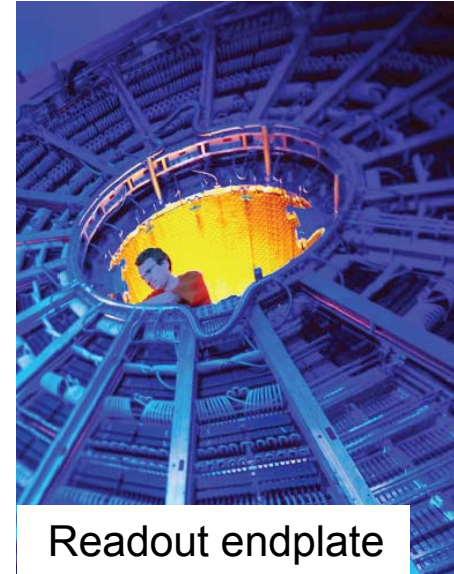


# The TPC of the ALICE detector at the LHC

The largest TPC so far



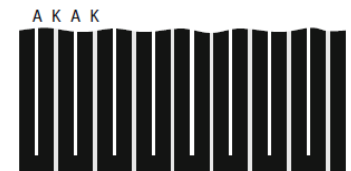
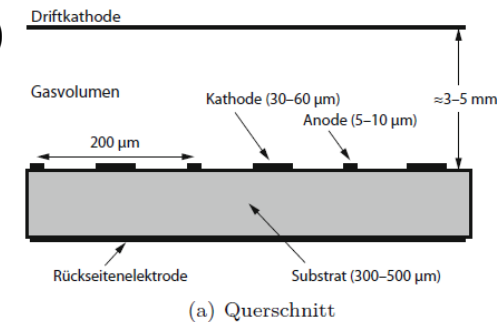
Field cage



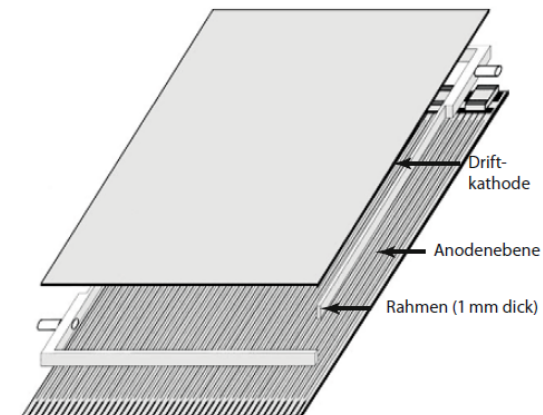
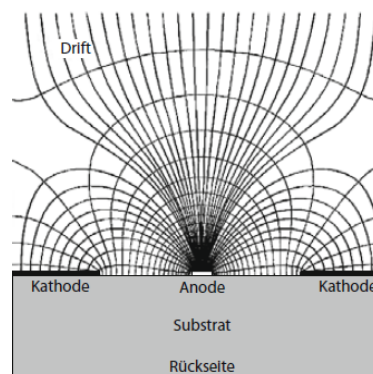
Readout endplate

# New Trend: Micro-Pattern Gas Detectors

- Development started in the late 1980s with **Micro-strip Gas Chambers (MSGCs)**.
- Thin (few mm) planar detectors using printed circuit boards (PCB) with alternating cathode and anode strips.
- **High granularity and spatial resolution.** Electronics/cost similar to silicon detectors.
- **Far higher rate capability** ( $> 1 \text{ MHz/cm}^2$ ) than MWPC. Short drift distances.
- **2D position information** (crossed strip planes or pad readout).
- **Plagued by discharges** and gain instabilities due to high field strengths and high gas gain.
- **Single detector area limited** by PCB manufacturing capabilities.

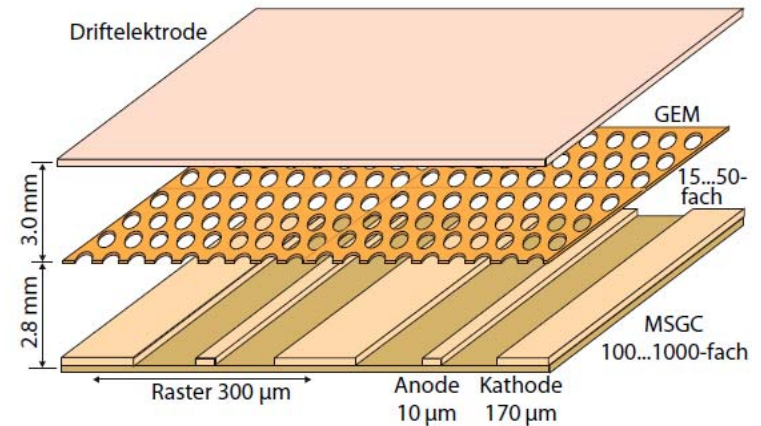
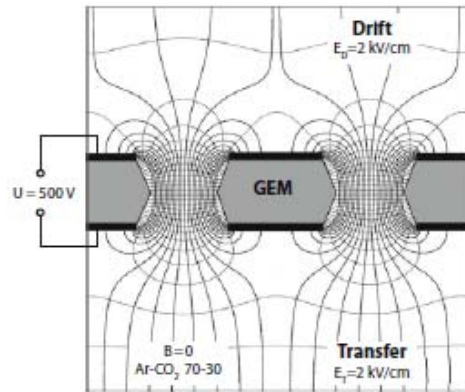
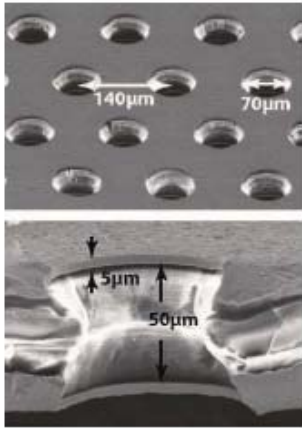


**MSGC layout**



# Gas Electron Multiplier (GEM) Detectors

Ionisation charge amplification in high fields in holes of **GEM foil** (made mostly in the CERN PCB workshop) allows for reduction of gas gain near readout electrodes and of risk of discharges (F. Sauli 1997).

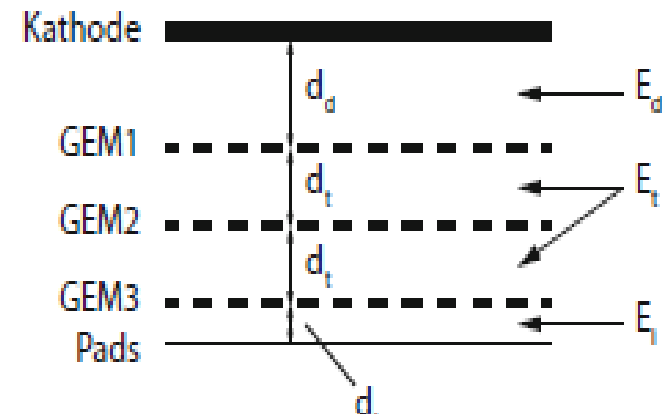


Standard today: **several GEM foils**, allow for optimisation of all operating parameters.

Such detectors presently used for

- fixed target tracking detectors (e.g. COMPASS),
- readout chambers of modern TPCs (ALICE, ILC), prevent ion backflow into drift volume,
- muon detectors for high rates (ATLAS, CMS),

challenge: large detection areas (RD51 collaboration at CERN).





# Micro-mesh Gas Detectors (Micromegas)

Similar principle as GEM detectors.

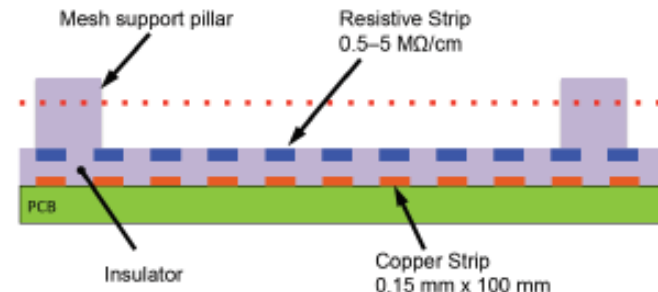
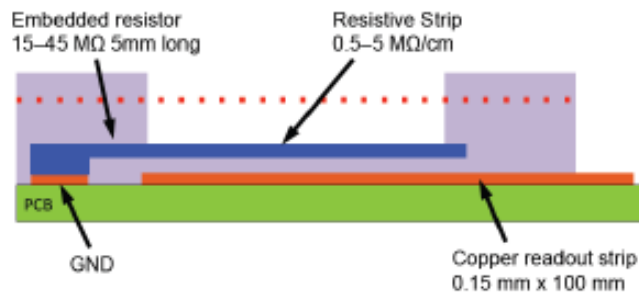
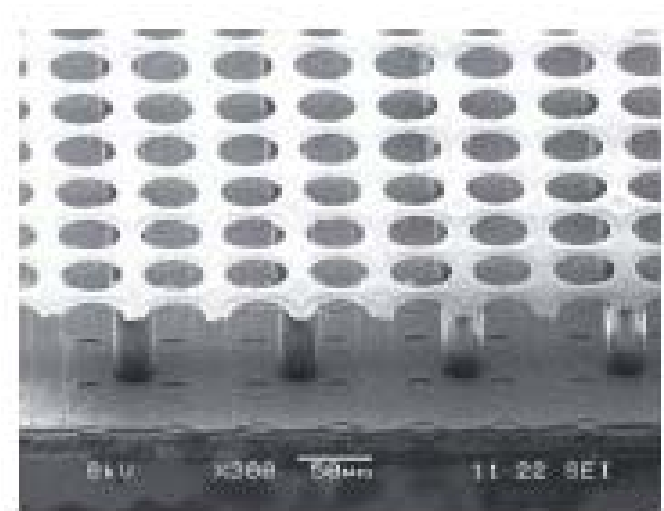
Industrially manufactured micro-mesh stretched and mounted on insulating pillars close to the readout board.

Separates thin amplification volume from drift region.

Highest rate capability.

Intermittent sparking occurs, esp. at the passage of strongly ionising particles.

Effects of sparks on lifetime and efficiency moderated by use of resistive readout strip coating developed for ATLAS muon tracking detectors in the inner endcap layer of the muon spectrometer

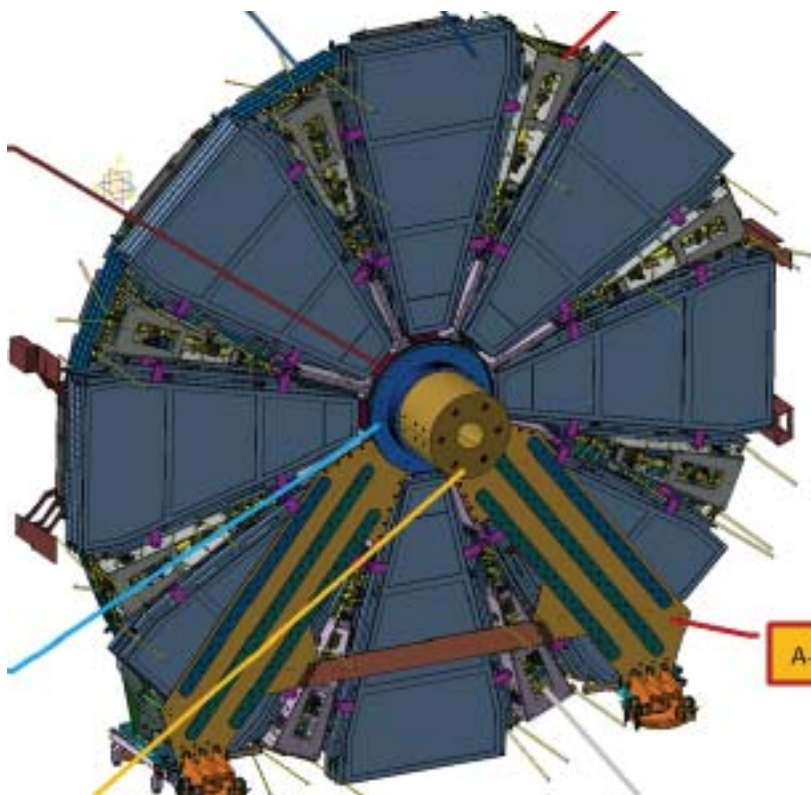


# ATLAS Inner Endcap Wheel of the Muon Spectrometer

First large-scale application of large-area (up to  $\sim 2 \text{ m}^2$ ) Micromegas detectors.

Very high background rates of neutrons and  $\gamma$ -rays make replacement of current muon drift-tube (MDT) chambers necessary at high LHC luminosity.

Installation in long LHC shutdown 2019/20.

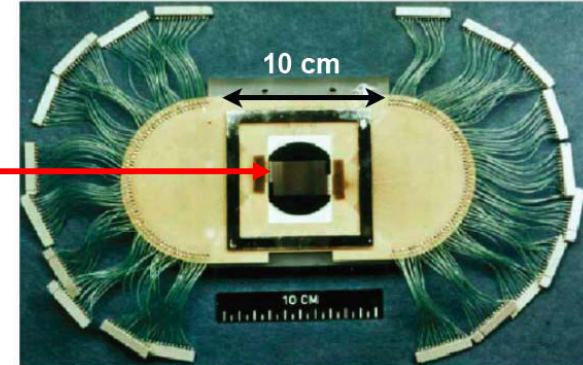


Stretching of Micromegas mesh for a large detector



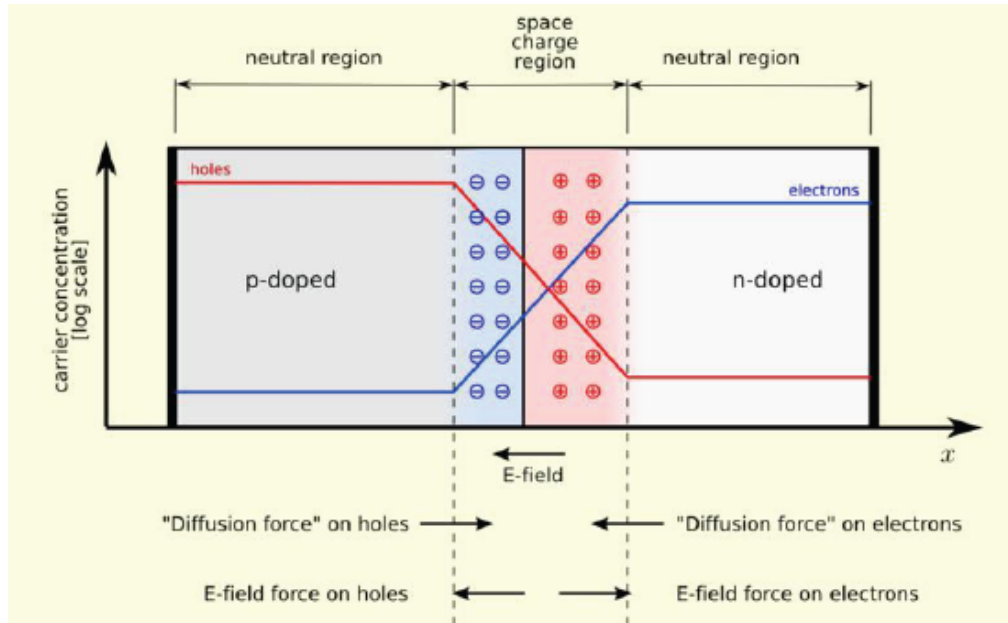
# Silicon Tracking Detectors

- **Position sensitive silicon micro-strip detectors** first developed in the 1980s based on photo-lithographic surface structuring and ion implantation techniques for VLSI chips from the **micro-electronics industry** (J. Kemmer, TU Munich, 1979).
  - Advantage of silicon detector technology until today.
- First application in particle physics for charm quark lifetime measurement in the NA11-NA32 fixed target experiments at the SPS at CERN (1981-94).
  - **B meson decay vertex reconstruction and b-jet tagging.**  
Discoveries of **t-dependent BB oscillations, top quark and CP violation in B decays.**
- Use in larger scale for **vertex detectors** (SiVTX) in  $e^+e^-$  collider experiments, first MARKII at PEP (1990), LEP detectors (1991-2000), and B factories (1999-...), then HERA ep collider experiments H1 and ZEUS at DESY (1992-2007)  
Finally at the Tevatron pp collider experiments CDF and D0 (1992/99-2012).
  - **B meson decay vertex reconstruction and b-jet tagging.**  
Discoveries of **t-dependent BB oscillations, top quark and CP violation in B decays.**
- Revolution for **radiation hard tracking detectors at hadron colliders.**  
First silicon central tracking detectors in ATLAS, CMS, ALICE, (LHCb) at the LHC.



# Silicon Position Detector Principle

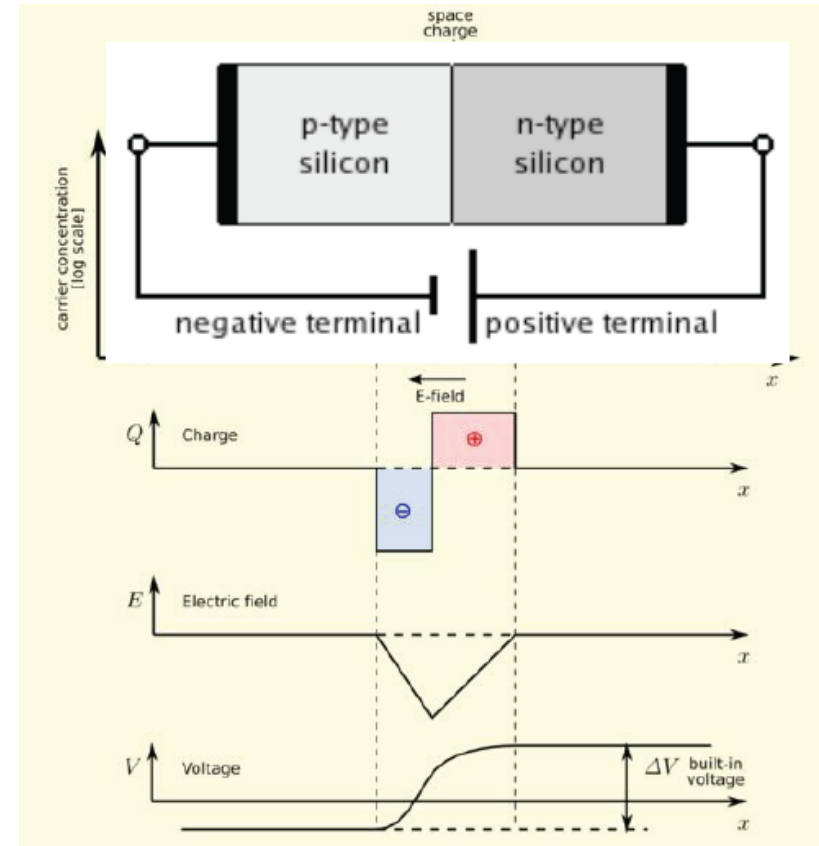
Principle: p-i-n transitions as in photodiodes.



p-i-n transition with no external voltage applied.

Space charge region of fixed ions depleted of charge carriers (electrons, holes).

Intrinsic electric field removes charge carriers.



External voltage increases depletion region sensitive for collection of electrons and holes created in pairs by ionising radiation.

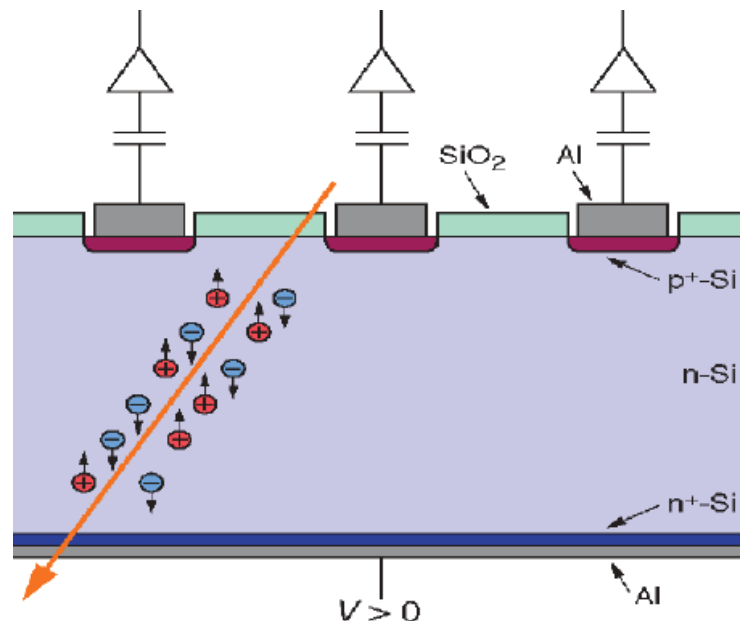
# Silicon Strip Detector Principle

Many strip-like diodes implanted on the surface of thin silicon wafers, e.g. most commonly  $p^+$  doped strips in  $n$  doped bulk material.

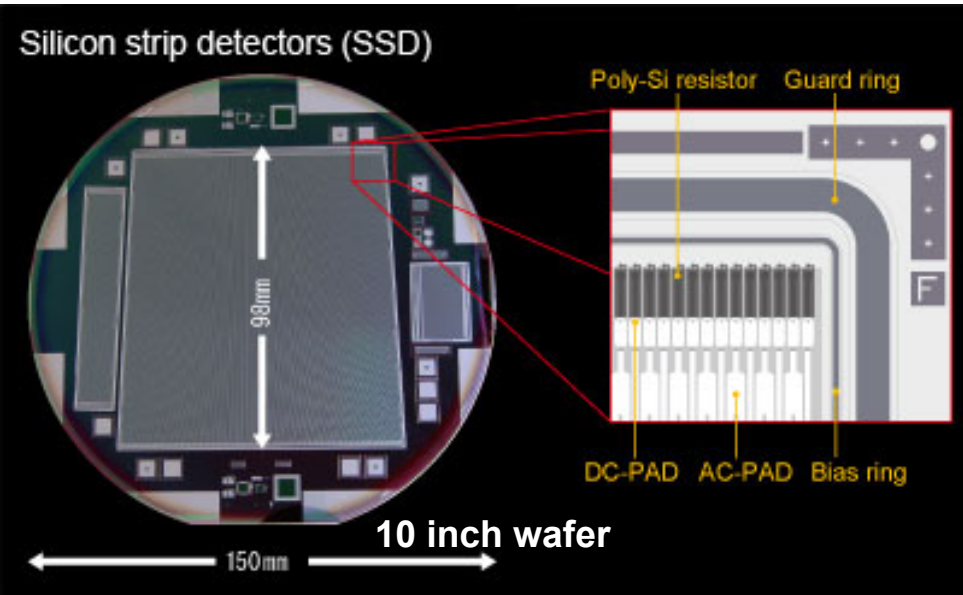
Bulk material fully depleted by external voltage between strips and back-side electrode to maximise the sensitivity to traversing charged particles.

Electron-hole pairs created along particle track are separated in the electric field in the depleted bulk.

Holes are collected on the  $p^+$  strips.



# Silicon Detector Modules



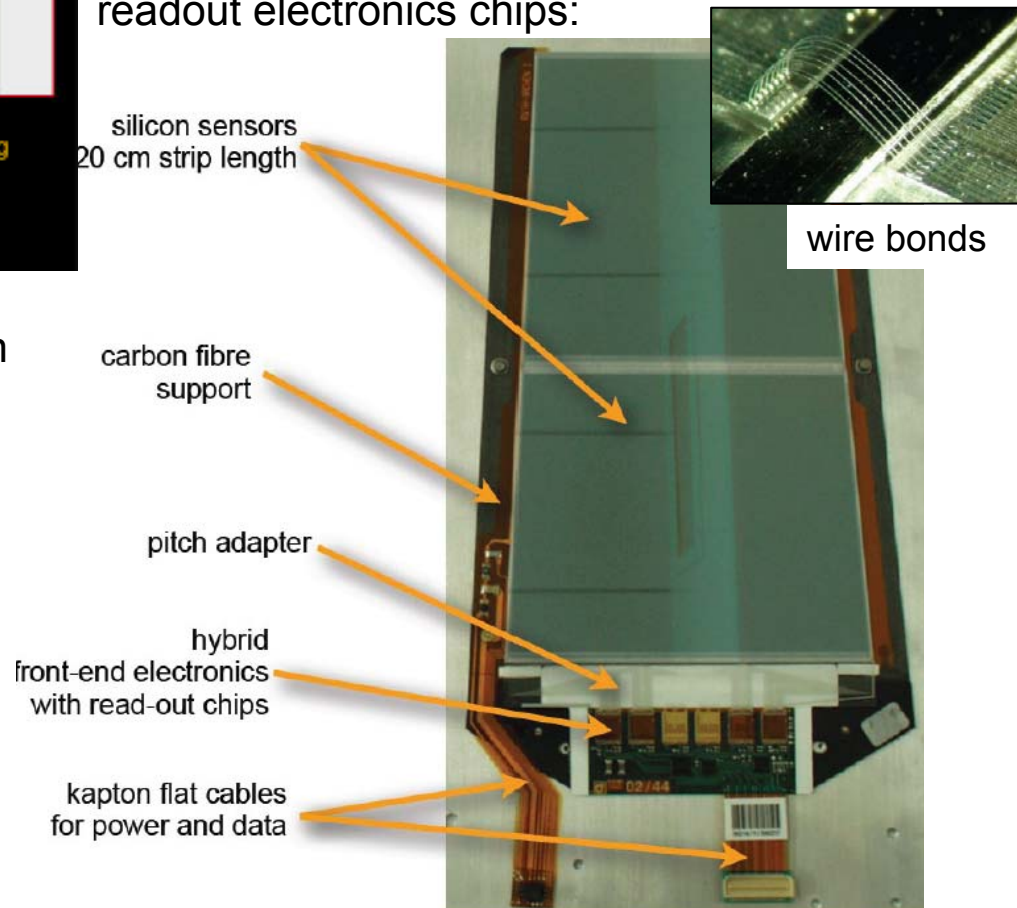
Several strip sensors ganged together along the strips (limitation: detector capacitance and assoc. noise) and glued back to back under stereo angle to provide 2D position information.

Strips connected at the ends to integrated readout electronics chips:

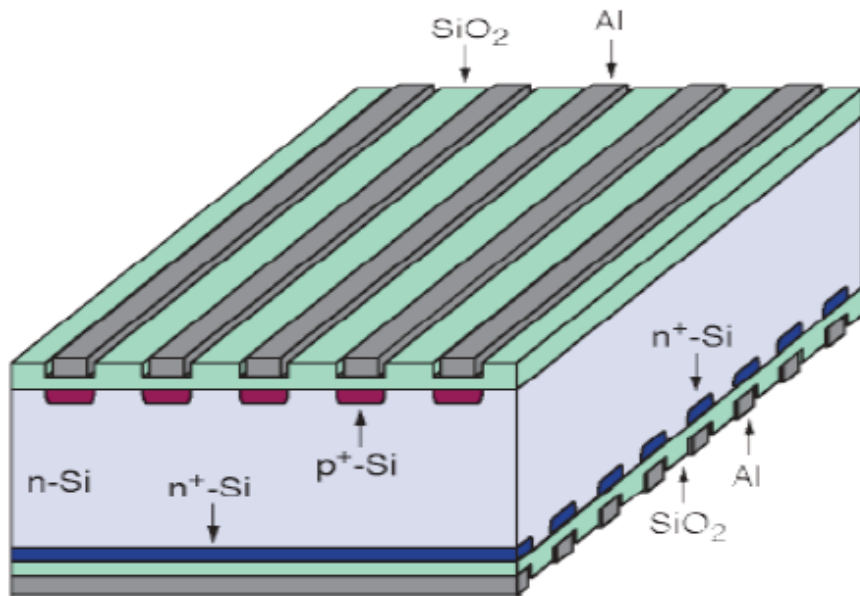
About 1200 strips with typically 50 $\mu$ m pitch on a single sensor occupying a full 10 x 10 cm<sup>2</sup> silicon wafer.

Today larger wafers are industry standard.

High density of strips and readout channels requires use of ASIC readout chips to be developed together with the sensors.



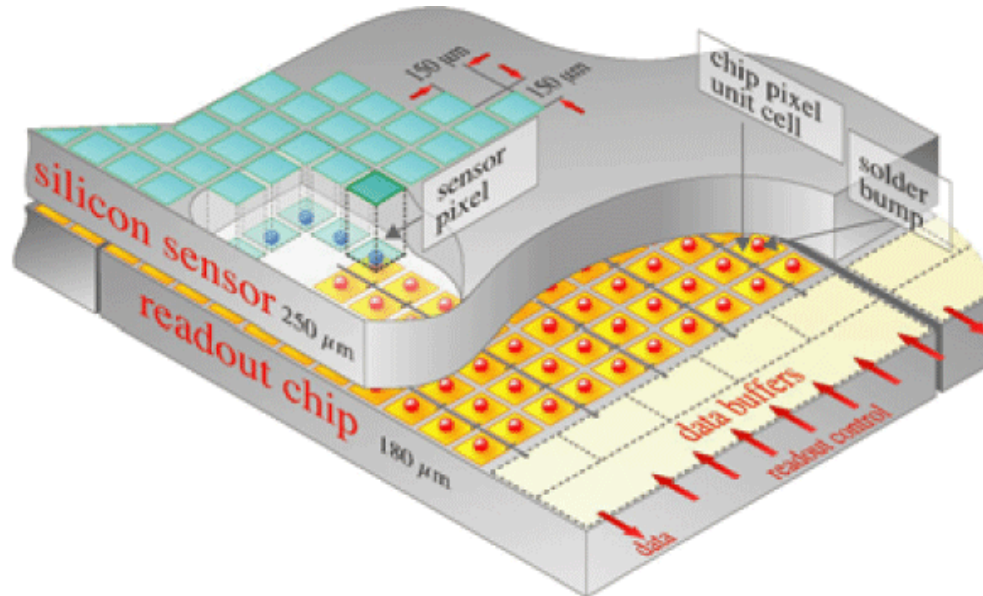
# Double-Sided Silicon Strip Sensors



- More compact design, saves material
- n<sup>+</sup> strips in n bulk would be shorted due electron accumulation underneath positively charged silicon oxide layer. Insulation with additional p implants necessary.
- Double sided processing more expensive.
- Used in LEP and B factory detectors, also in the ALICE experiment at LHC.

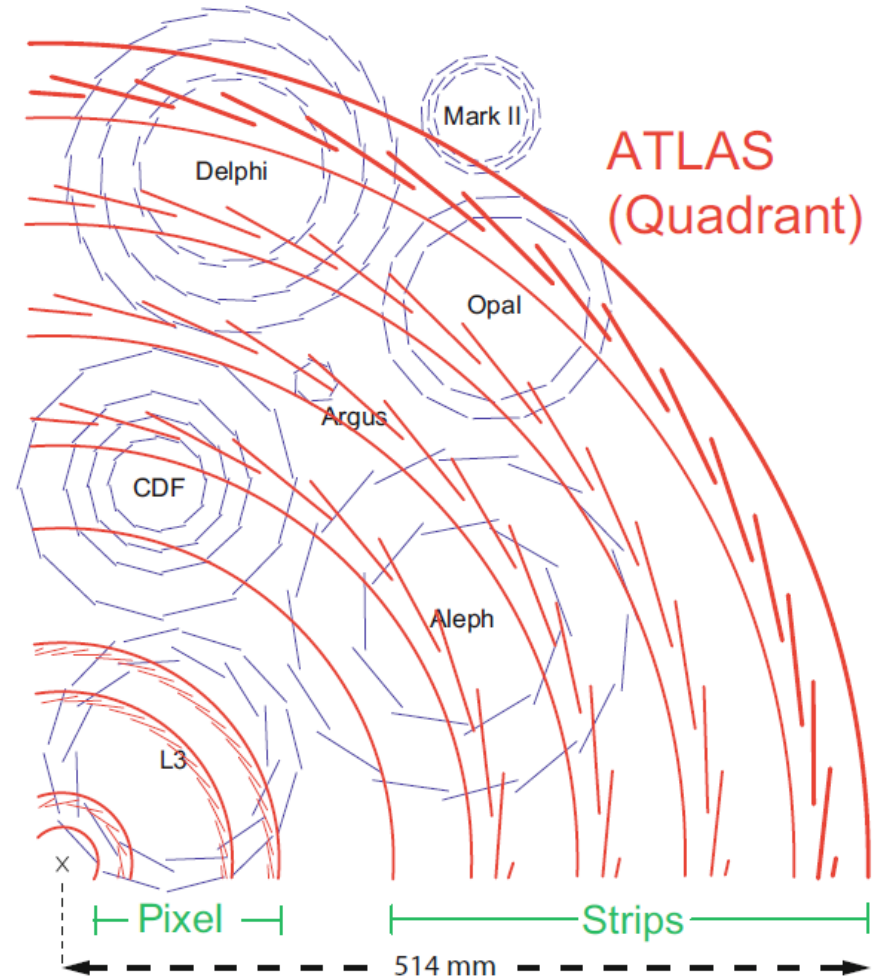
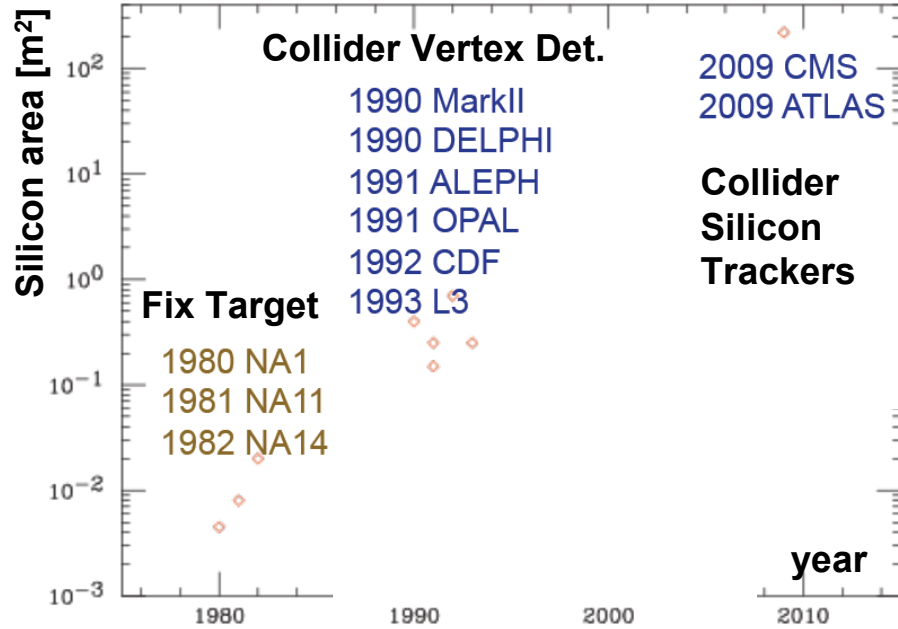
# Silicon Pixel Detectors

- Highest granularity and 2D spatial resolution closest to the interaction region.  
→ Inner part of the silicon tracking detectors of the LHC experiments.  
Highest radiation hardness required.
- Pixel density i.g. not as high as in digital cameras, but much faster readout.
- Hybrid pixel sensors for the LHC era:  
bump bonding of readout chips to sensors pixel by pixel.





# Silicon Detectors at Colliders



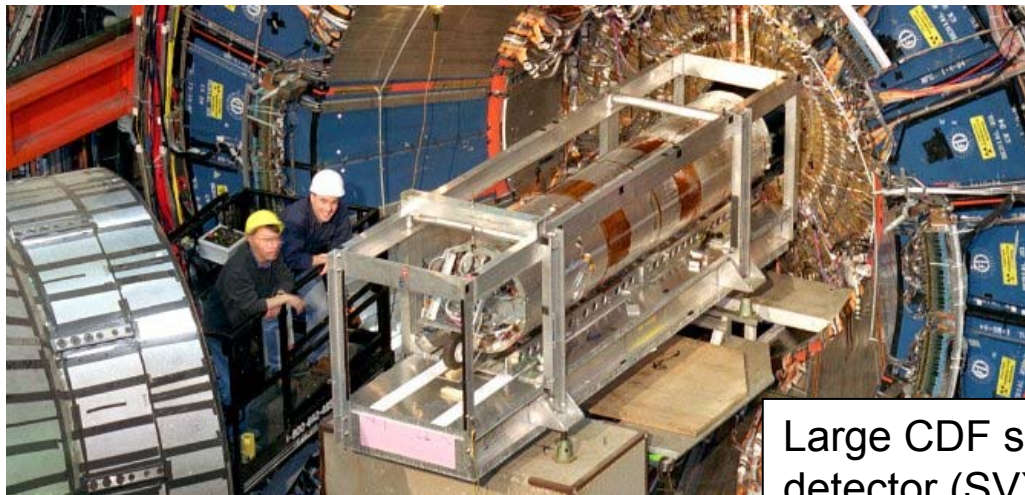
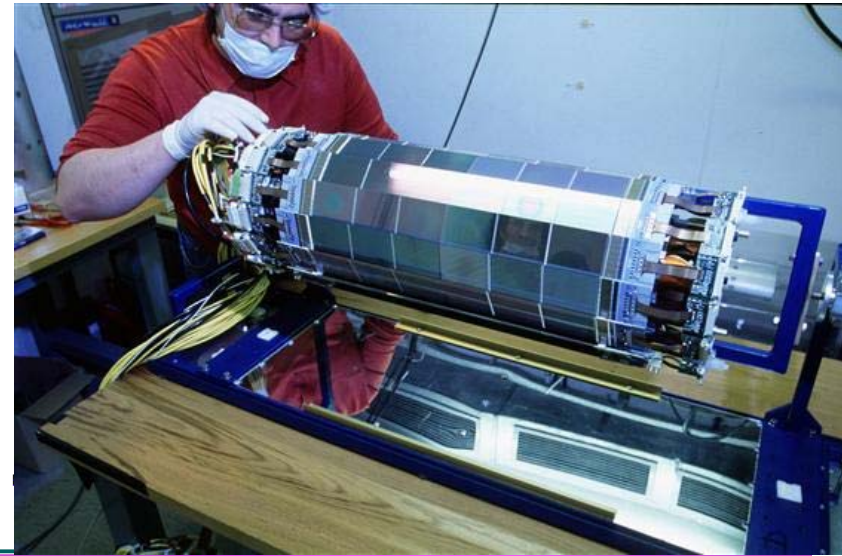
Kolanoski, Wermes 2015

# Silicon Vertex Detectors

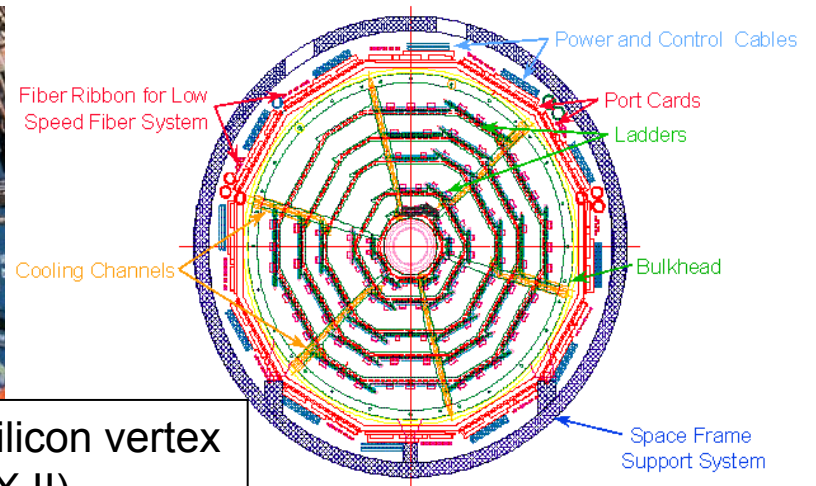
The first silicon strip vertex detector at the MARK II experiment at SLAC



The first silicon strip vertex detector at LEP in the ALEPH experiment. Also the first double-sided strip sensors.



Large CDF silicon vertex detector (SVX II)



# Silicon Central Tracking Detectors

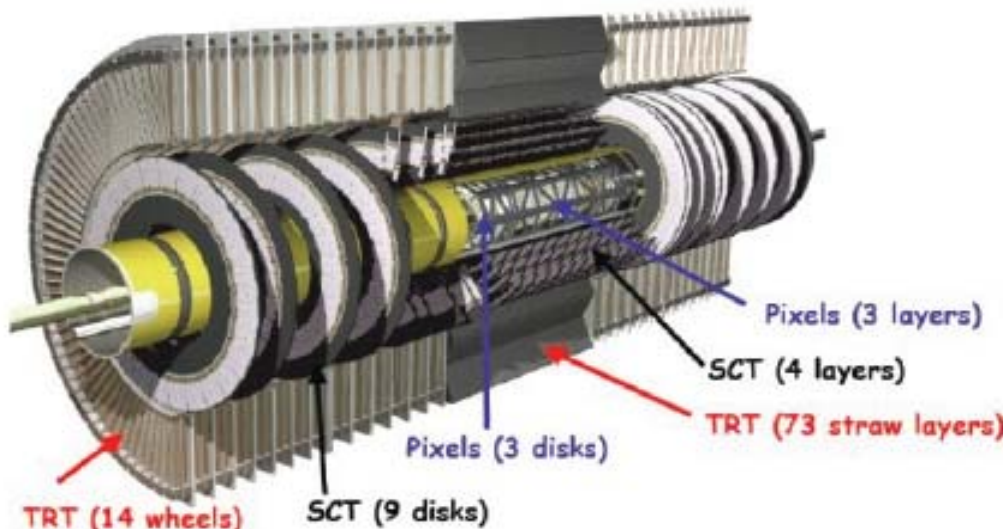
## ATLAS:

60 m<sup>2</sup> strip sensors, 1 m<sup>2</sup> pixel sensors,

1750 pixel sensors,

4100 strip modules with 16400 sensors, single-sided, glued back-to-back with stereo angle,

6 million strips, 80 million pixels

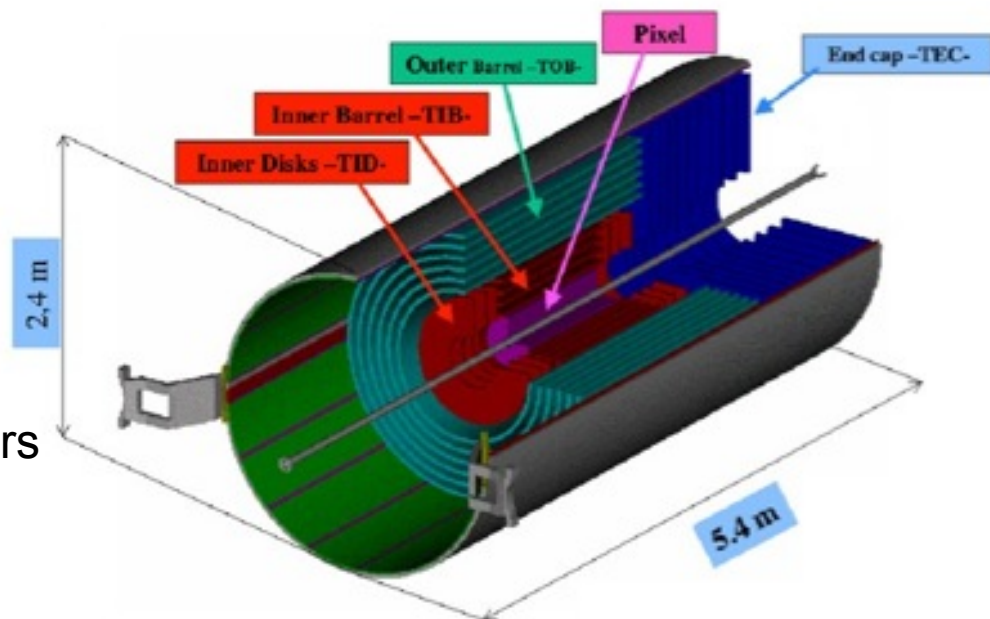


## CMS:

The first and only all-silicon collider central tracker, and the world's largest silicon detector

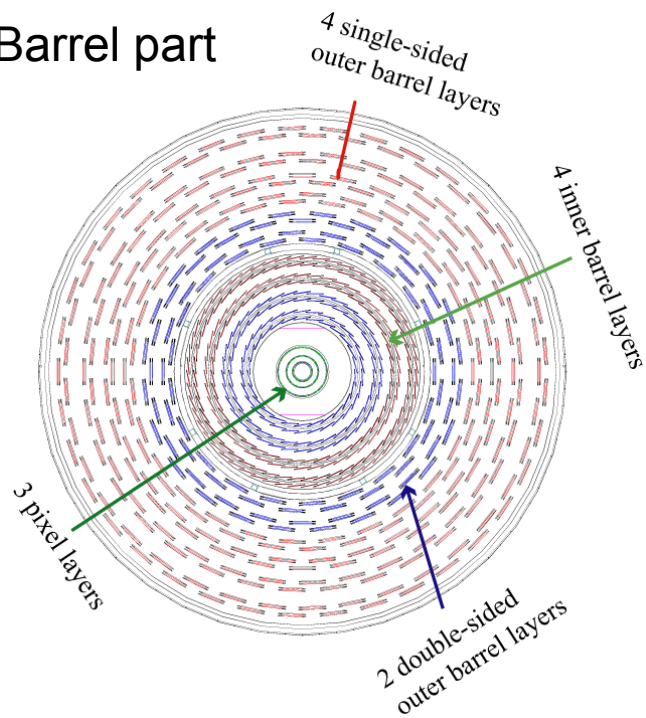
200 m<sup>2</sup> silicon sensors, 1 m<sup>2</sup> pixel sensors

11 million strips, 60 million pixels

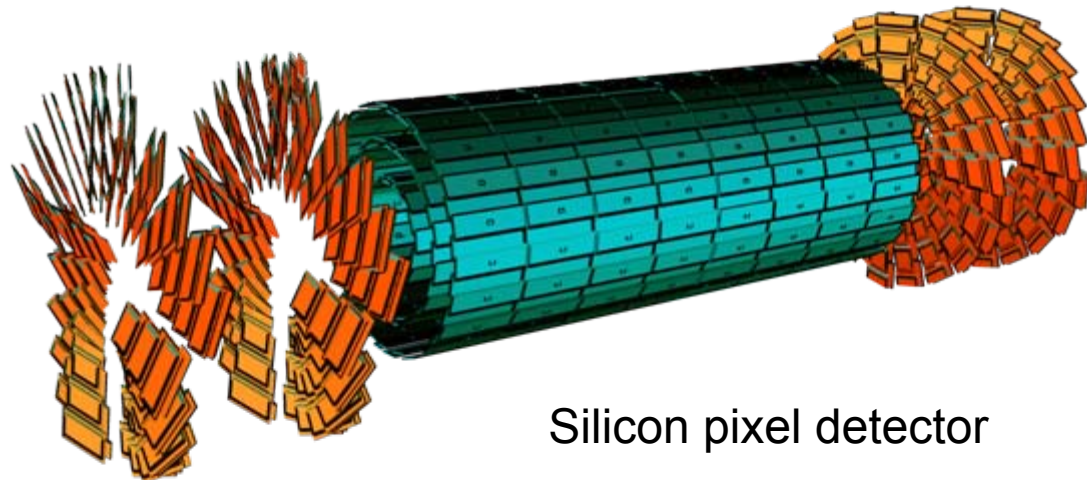
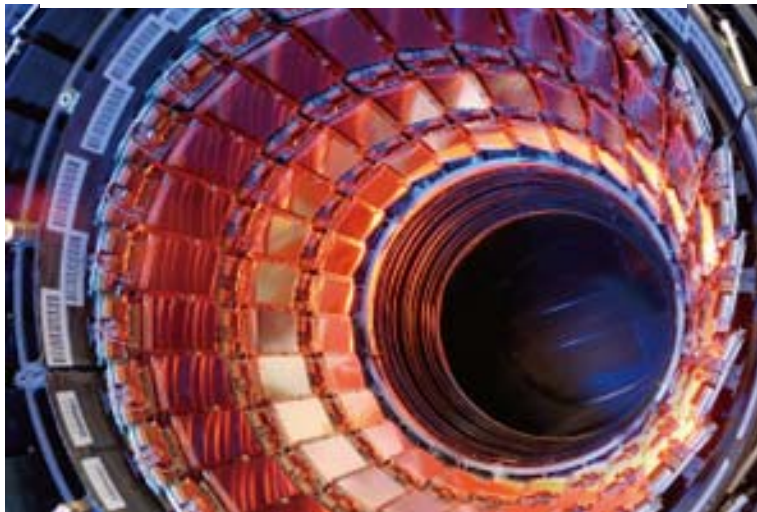
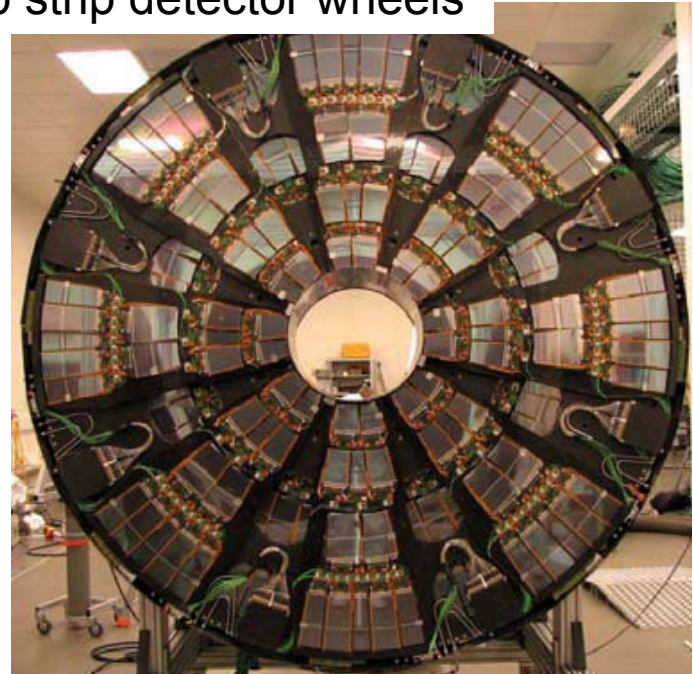


# The CMS Silicon Inner Tracker

Barrel part

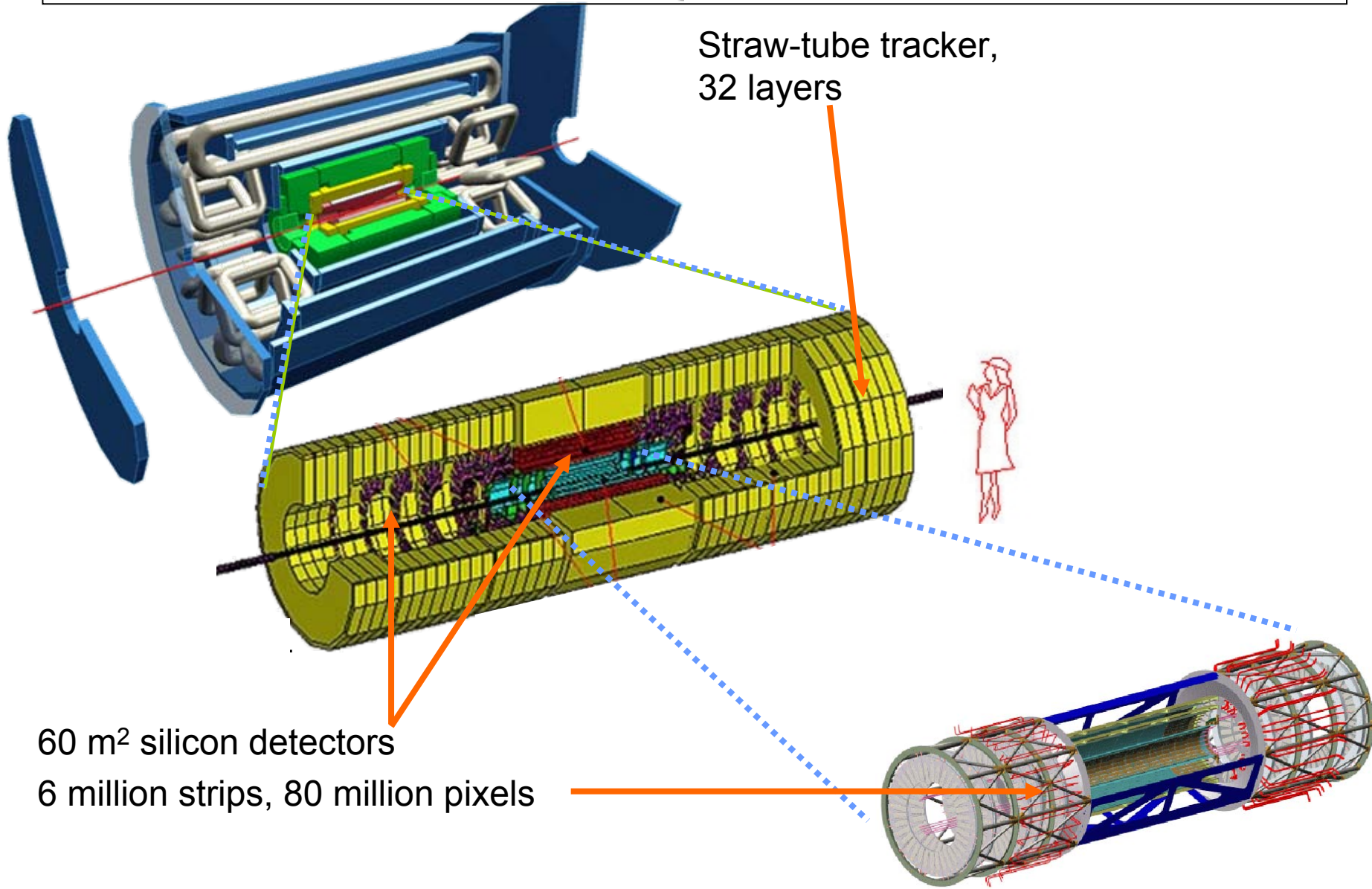


Endcap strip detector wheels

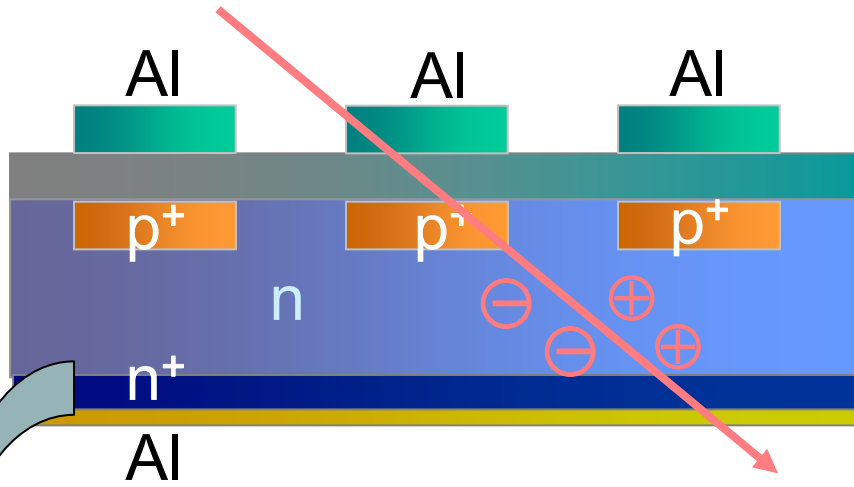


Silicon pixel detector

# The ATLAS Inner Tracking Detector



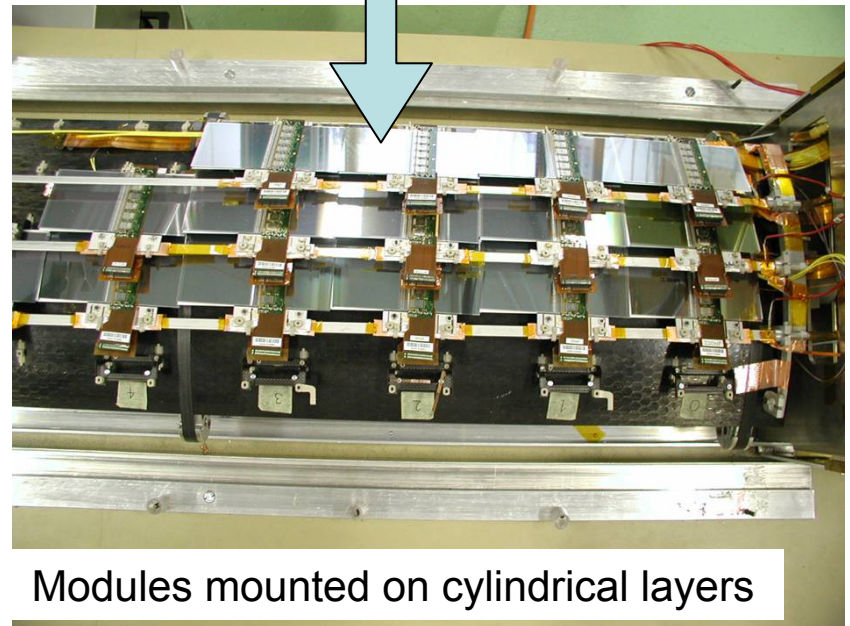
# ATLAS Silicon Strip Tracker



Strip detector module consisting of 4 sensors

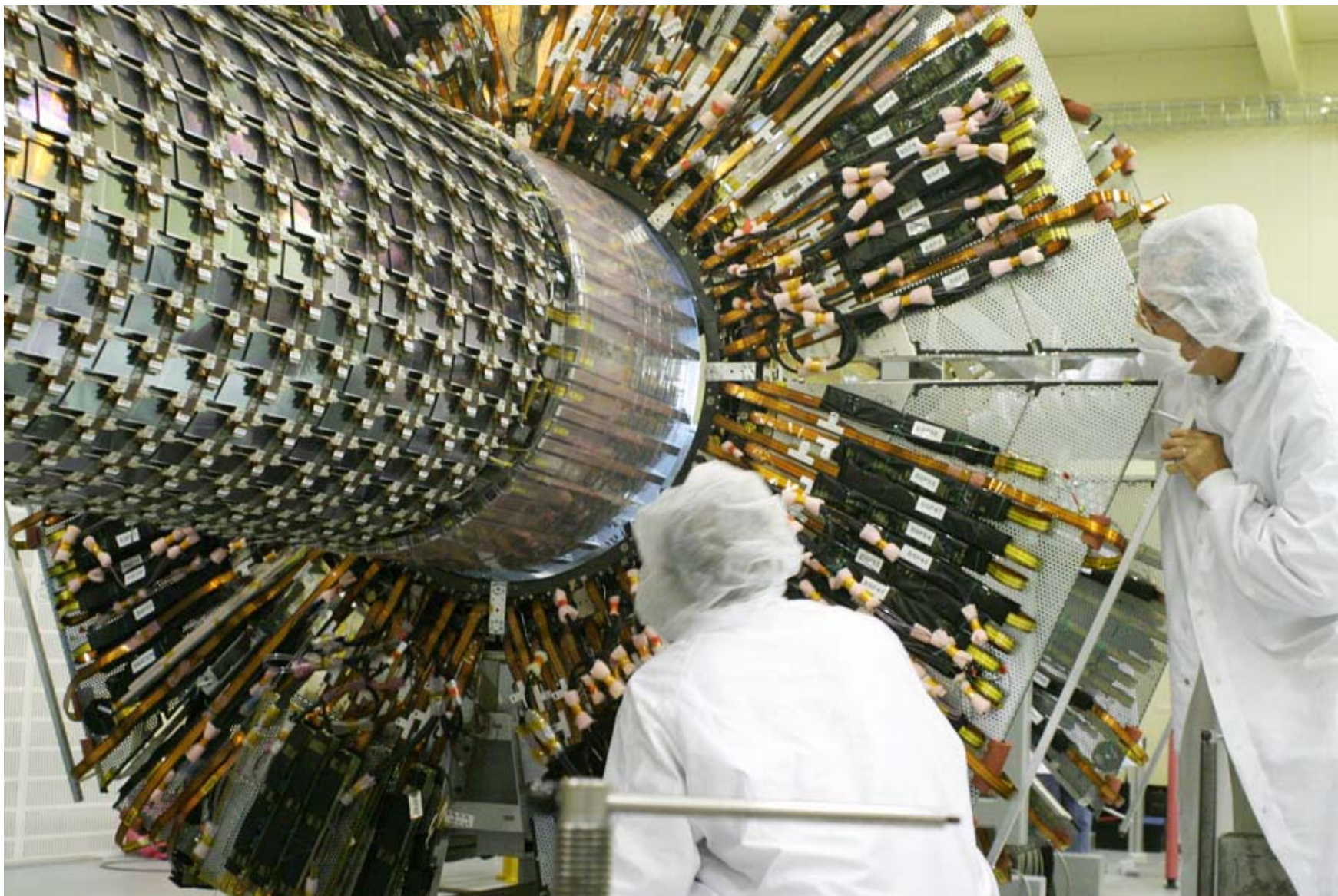


Carbon fiber support structure

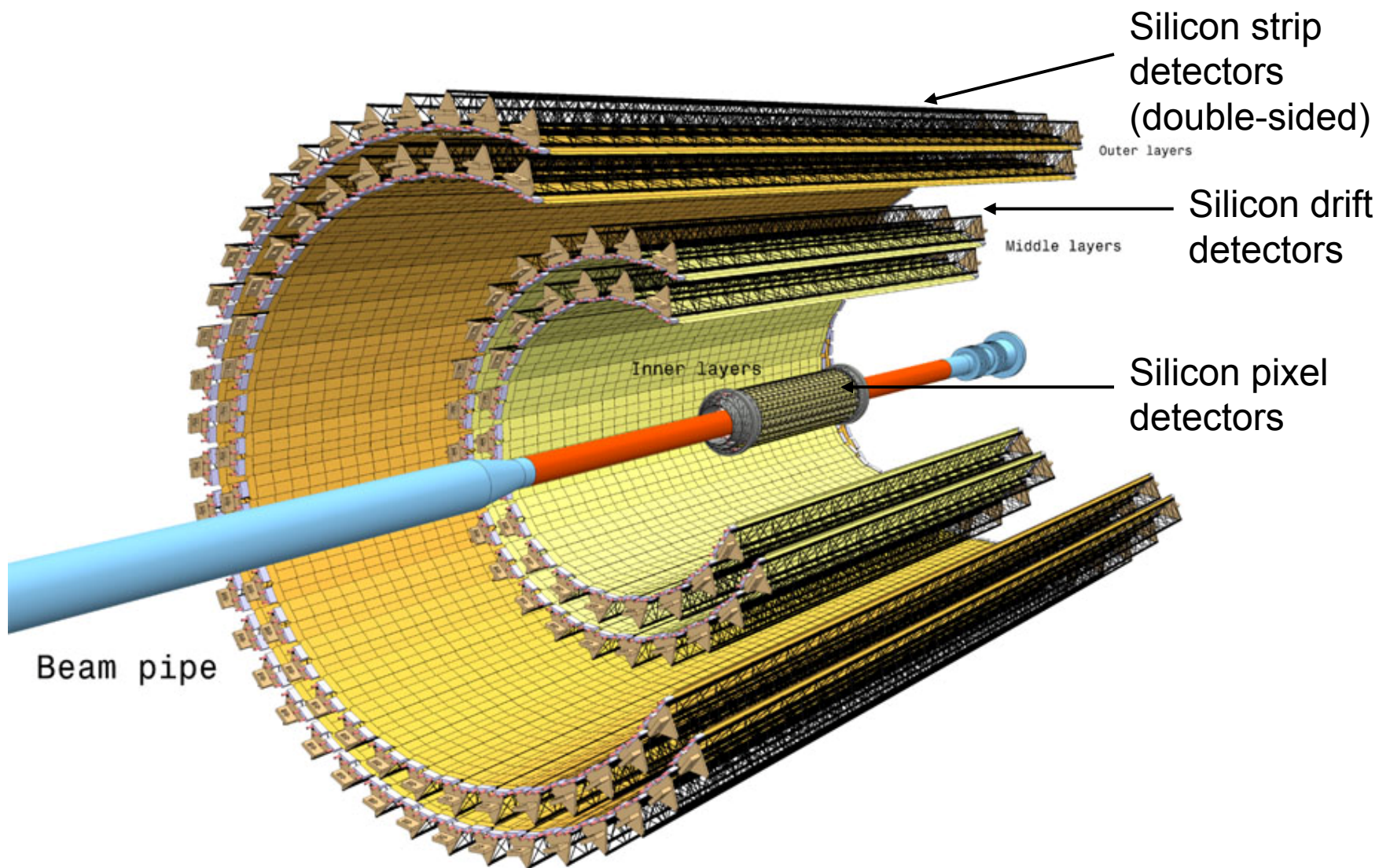


Modules mounted on cylindrical layers

# ATLAS Barrel Silicon Strip Tracker Readout cable fan-out at the ends



# ALICE Inner Silicon Tracker



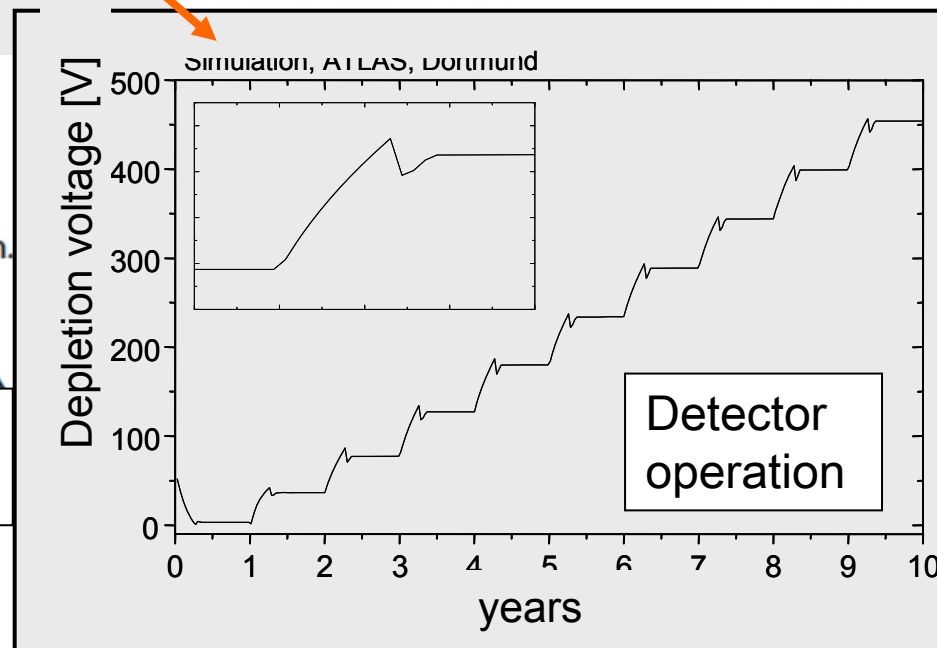
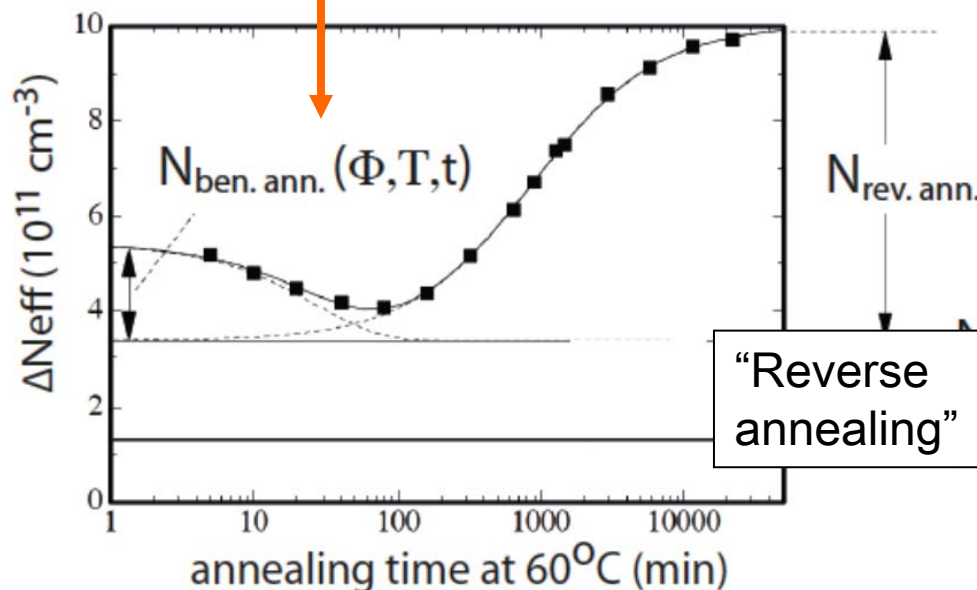
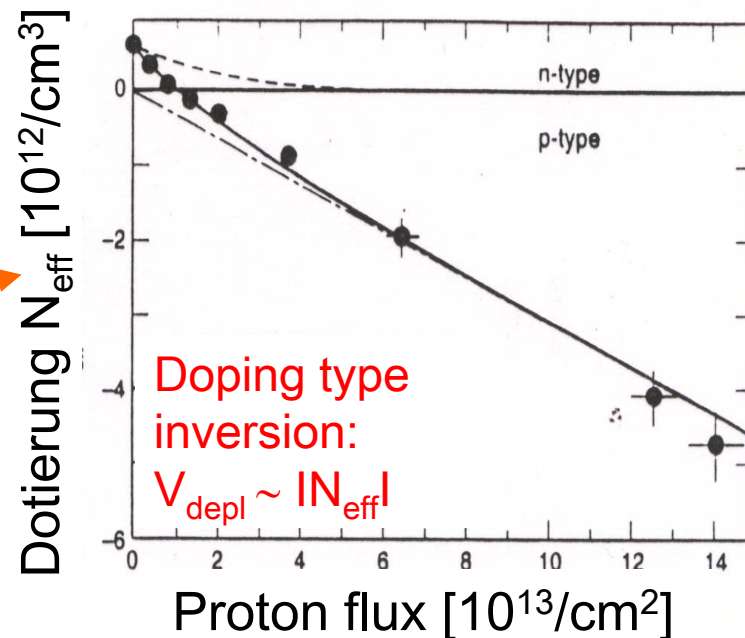


# Radiation Hardness of Tracking Detectors

- Radiation hardness of silicon sensors and their readout ASIC chips became a serious issue first for the LHC experiments.
  - Silicon sensors are the only technology which can cope on a large scale with the high radiation levels at LHC. Intense dedicated R&D program in the 1990s.
- Radiation hardness is still more critical for the new all-silicon central detectors of ATLAS and CMS at high-luminosity LHC (HL-LHC).
  - More refined silicon sensor design and material selection, thinned sensors, ... R&D started before LHC data taking.
- At  $e^+e^-$  colliders less critical, although non negligible.
- New damage of crystal lattice by hadron irradiation (non-ionising energy loss NIEL).
- Ionising energy loss affects sensors and electronics (Si SiO<sub>2</sub> interface=).
- Radiation hard integrated electronics processes from military applications for LHC.
- Increased ASIC radiation hardness is now a by-product of ever smaller feature sizes of modern chip technologies.

# Radiation Hardness of Silicon Sensors

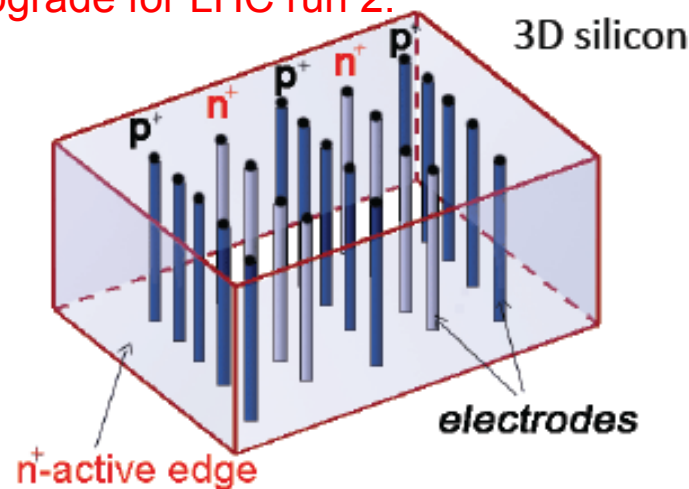
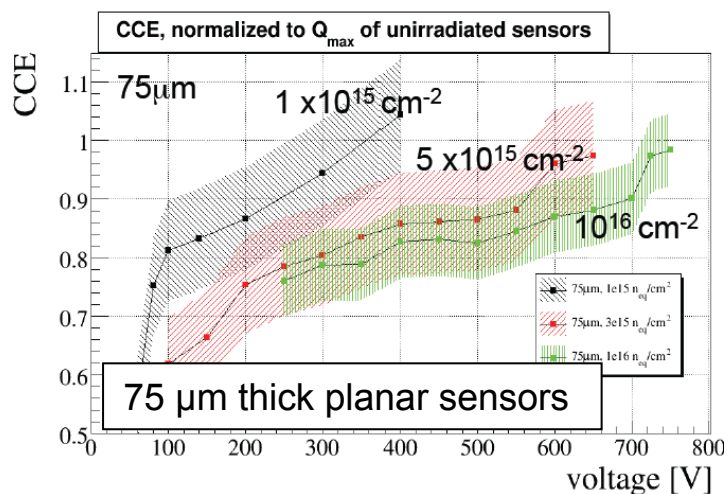
- Irradiation dose in 10 years of LHC operation at design luminosity:  
 $>10$  MRad und  $> 10^{14}$  protons/cm<sup>2</sup>
- Bulk radiation damage of crystalline silicon lattice: effective change of the doping concentration with  $n \rightarrow p$  transition (depletion from backside  $n^+$  electrode).  
 $\rightarrow$  increase depletion voltage  $|N_{\text{eff}}| \sim V_{\text{depletion}}$
- Effect enhanced by higher temperatures in the long run: defects activated.  
 Detector operation at  $< 0^\circ \text{C}$  in dry  $\text{N}_2$  atm.



# Radiation Hardness of Silicon Sensors – Further Developments

- **Even more radiation hardness needed for silicon sensors at HL-LHC:**  
 $10^{15}$  protons/cm<sup>2</sup> for strip sensors,  $10^{16}$  protons/cm<sup>2</sup> for pixel sensors (advantage: smaller pixels)
- **Thin planar sensors: increased charge collection efficiency (CCE) at high damage.**  
 Short distances, high depl. Voltage. Thinning by etching of back-side of wafer.  
 Also: **less scattering material** (esp. for future e<sup>+</sup>e<sup>-</sup> collider detectors).
- **n<sup>+</sup> pixels in p or n bulk:** still work without complete depletion from n<sup>+</sup> pixel side.  
**LHC pixel sensors n<sup>+</sup>-in-n, HL-LHC strip and pixel sensors n<sup>+</sup>-in-p (or n<sup>+</sup>-in-n).**
- **3D pixel sensors:** p<sup>+</sup> and n<sup>+</sup> doped holes etched into n doped bulk (50 μm pitch).  
 → Sideways depletion and charge collection over short distances: much improved.

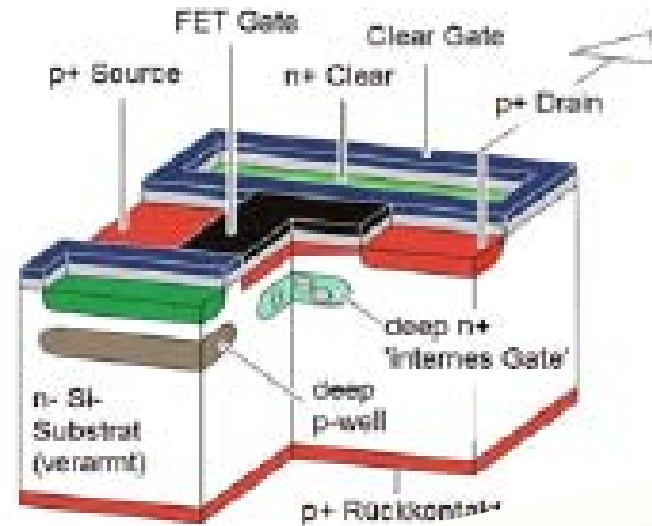
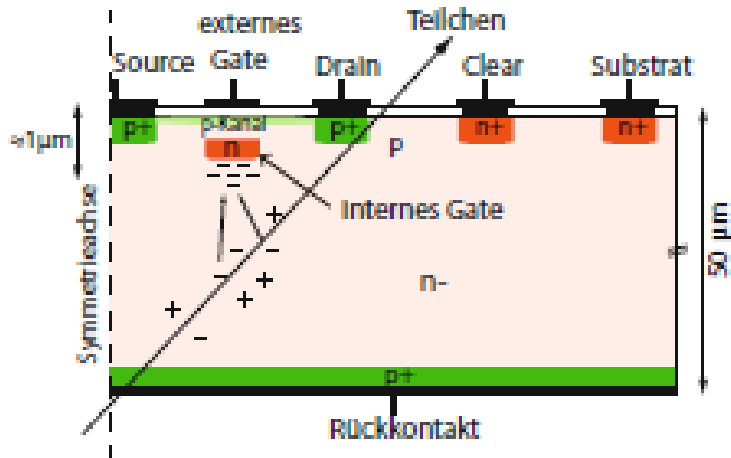
Industrial production. **Used in ATLAS inner pixel layer upgrade for LHC run 2.**



# Silicon Pixel Sensors for Future Collider Experiments

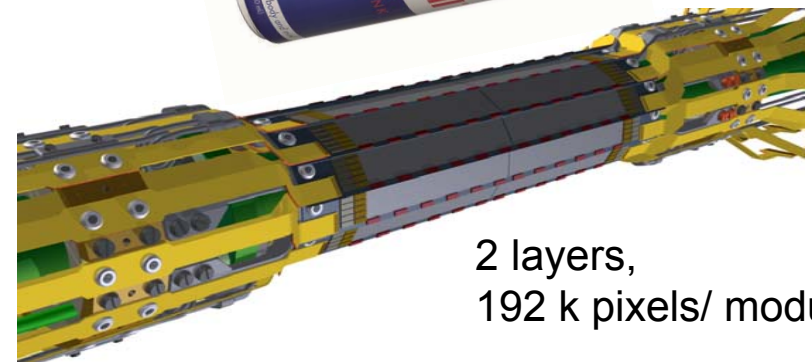
## DEPFET Pixel Sensors:

Fully depleted active pixels consisting of FETs for amplification of collected ionisation electrons. Limited radiation hardness.



Can currently only be fabricated at the MPI Semiconductor Laboratory where they have been invented.

Sensors thinned to  $75 \mu\text{m}$  will be used for the pixel vertex detector of the Belle II experiment.



2 layers,  
192 k pixels/ module

# Silicon Pixel Sensors for Future Collider Experiments

**Monolithic active pixel sensors (MAPS)** with integrated readout electronics using standard CMOS process (like for digital cameras), **very small pixels.**

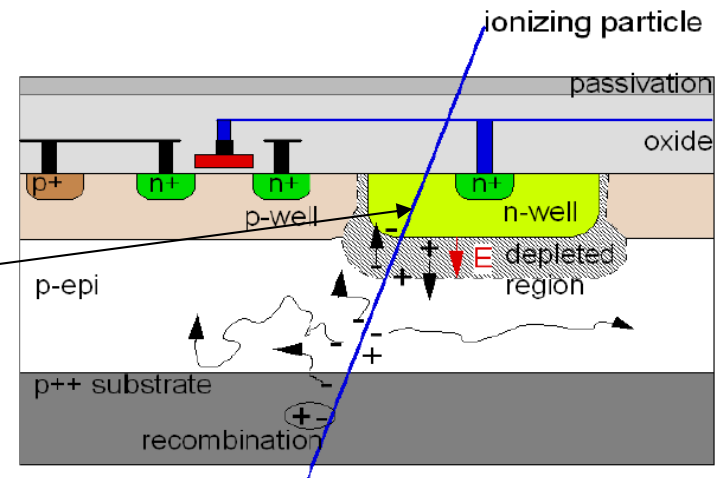
Thin active layer near surface, not fully depleted:

Can be thinned.

Limited radiation hardness.

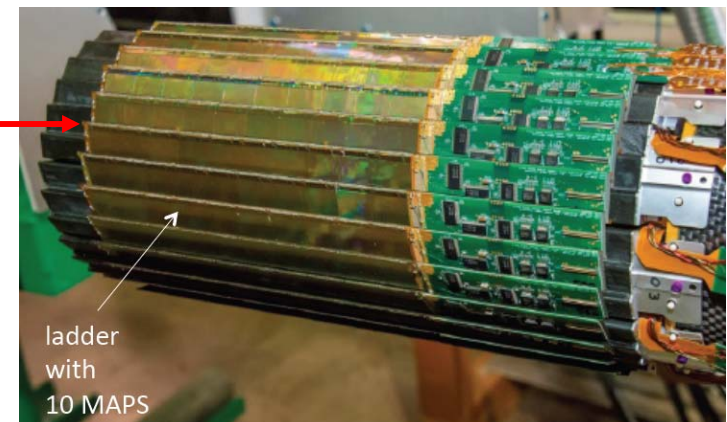
Slow charge collection.

Charge collection and amplification ( $n^+$  in p)



→ Developed for future  $e^+e^-$  colliders like ILC.

→ **Used in the STAR experiment at RHIC since 2014.**



→ **Planned for new ALICE inner tracker after 2019/20 LHC shutdown: 10 m<sup>2</sup>.**

# Silicon Pixel Sensors for Future Collider Experiments

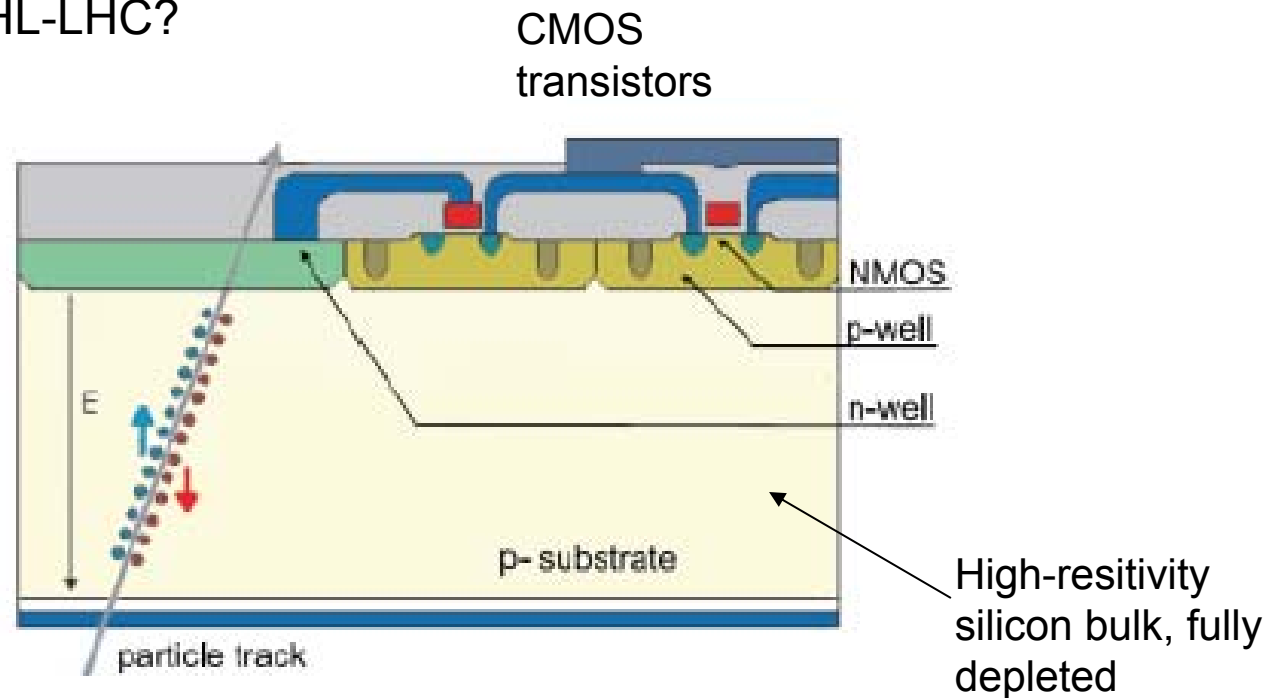
Recent (common) developments for ATLAS and CMS trackers at HL-LHC:

## Depleted HR/ HV-CMOS MAPS:

hope for a low cost and low material solution for large areas.

Radiation hardness to be verified.

For outer pixel layers at HL-LHC?



# Muon Detectors

- The outermost detectors.  
All other particles than muons are absorbed in the calorimeters.
  - Large detection areas.
  - Gas detectors.

## Tasks:

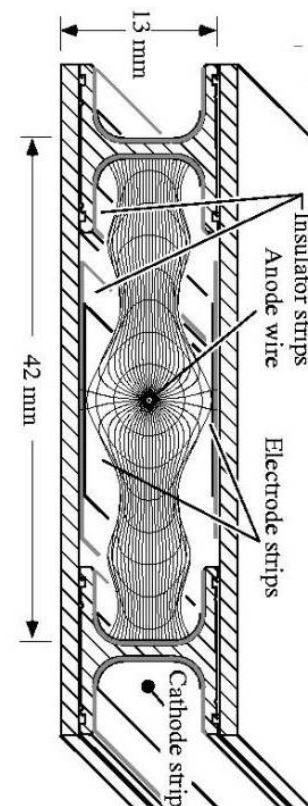
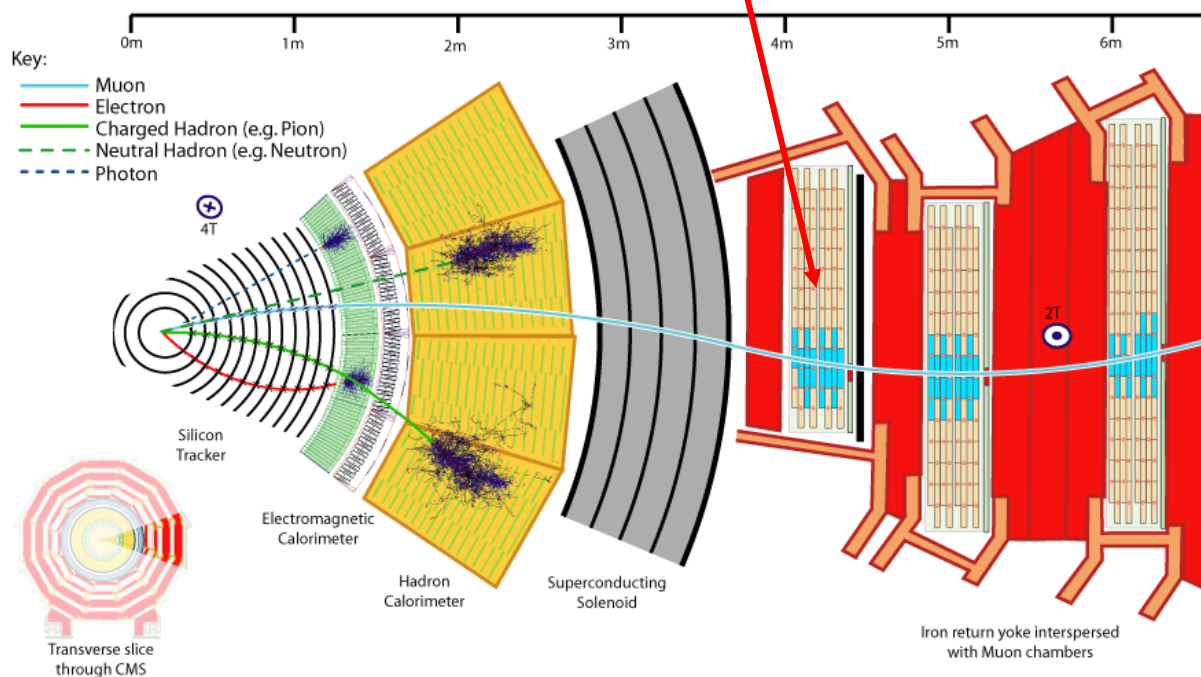
- Muon identification.
- Fast muon trigger detectors for first-level muon trigger and bunch crossing identification.
- Muon track reconstruction and momentum measurement in a magnetic field.
- Most challenging muon detector: **the ATLAS Muon Spectrometer**

Normally, muon chambers embedded in iron absorber, the magnetic flux return yoke of the inner detector solenoidal magnetic field, like in the **CMS Detector at the LHC**.

Spatial resolution limited by multiple scattering in the iron.  
 Drift chambers with few hundred micron resolution sufficient for muon identification.

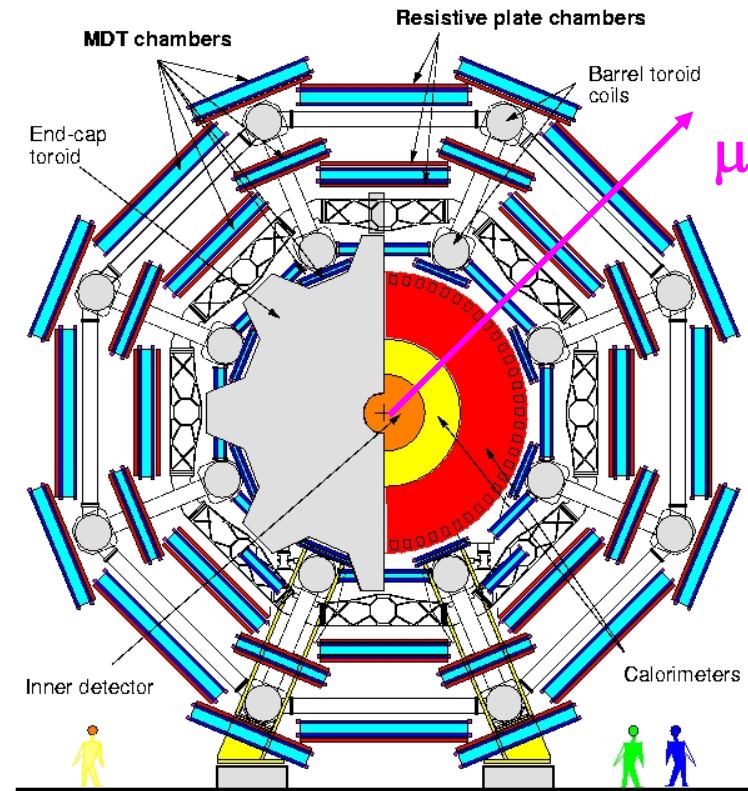
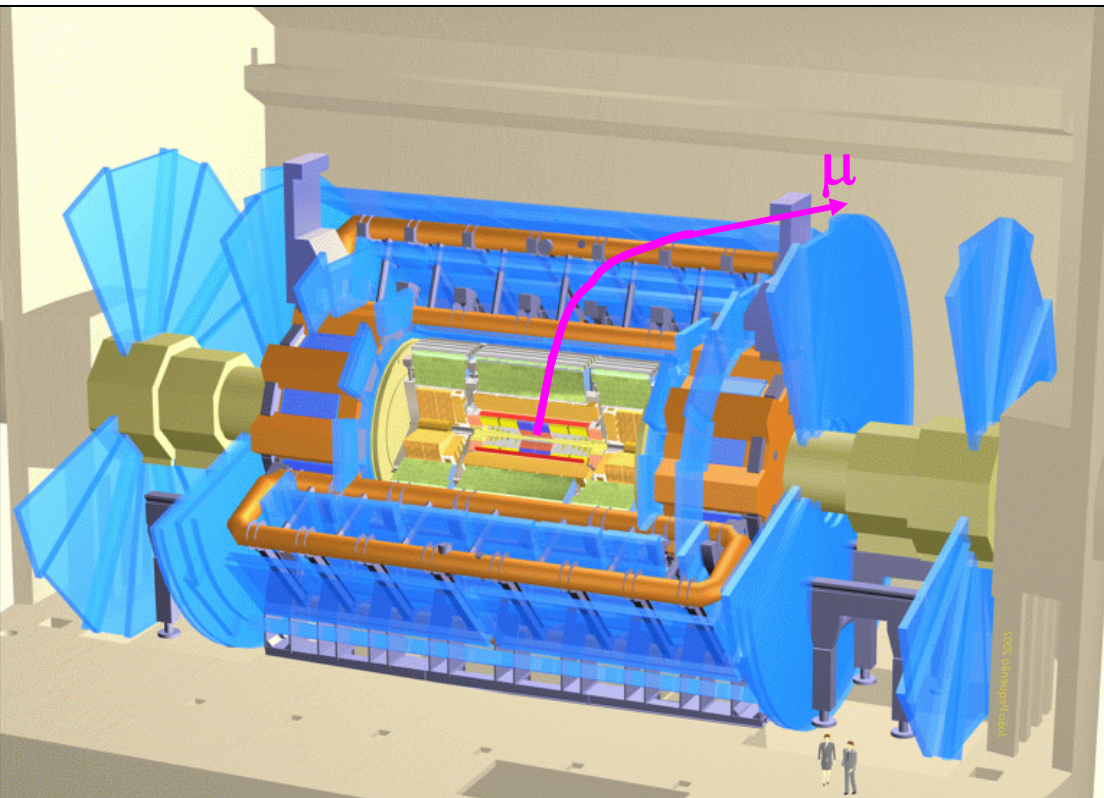
Precise momentum measurement in combination with the inner tracker.

Many layers of crossed drift tube detectors for 2D track reconstruction





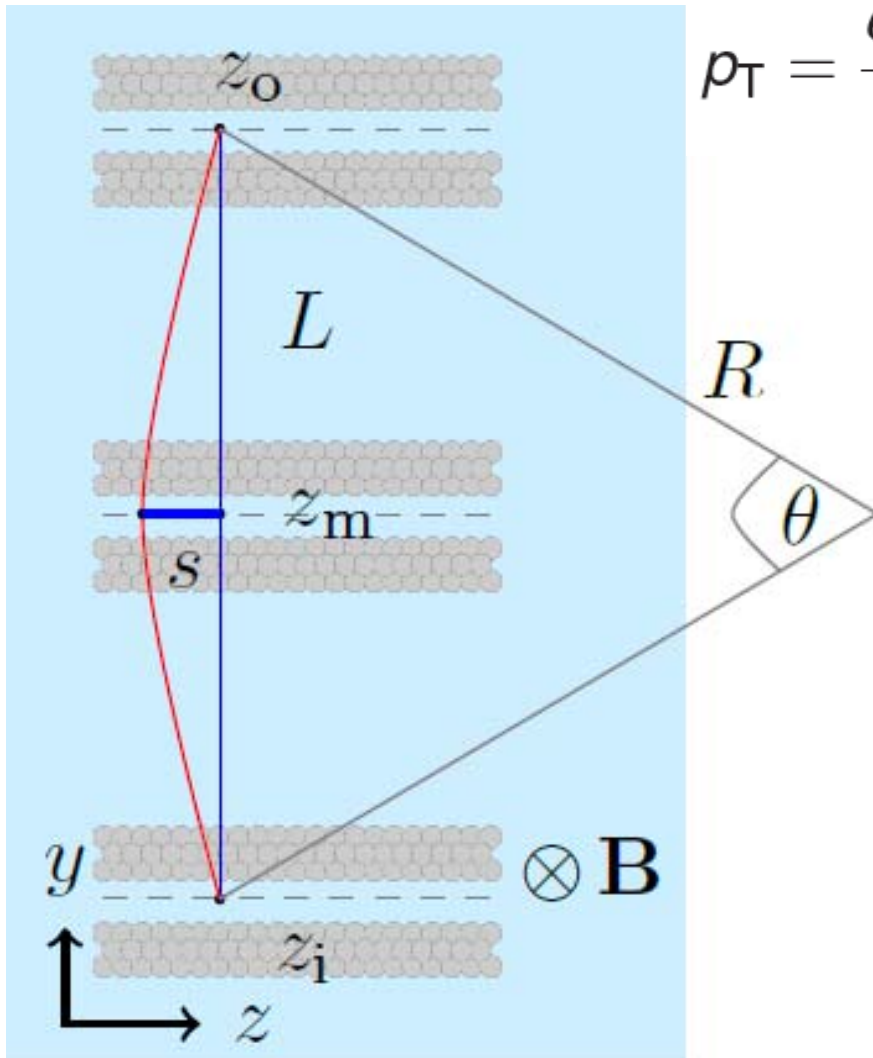
# ATLAS Muon Spectrometer



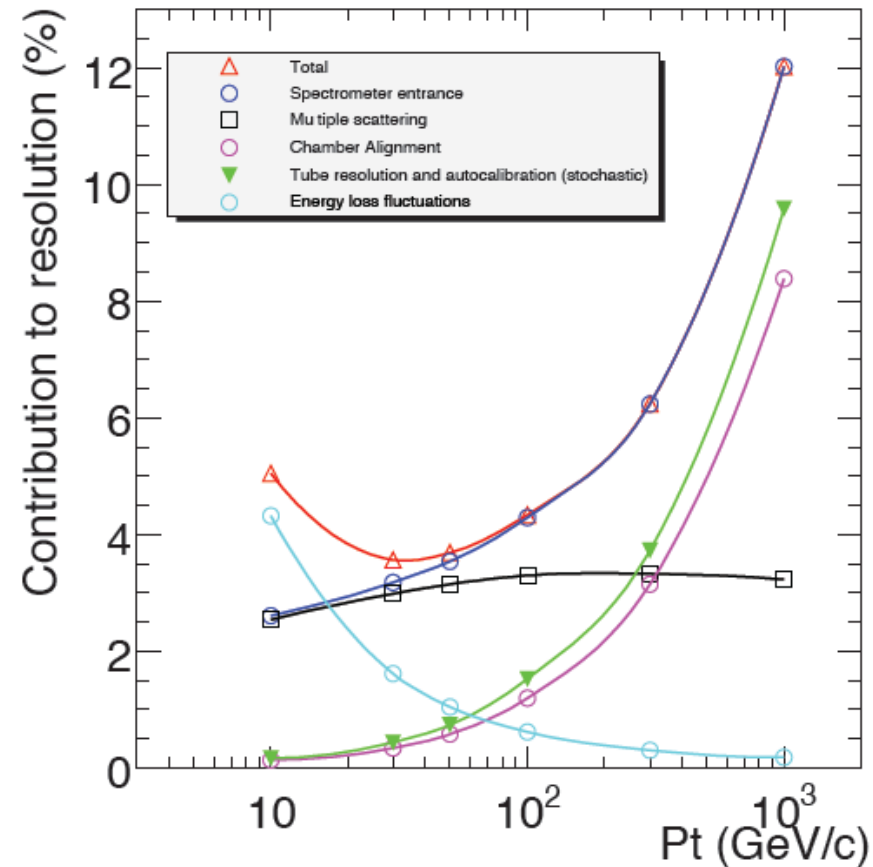
- Toroidal magnetic field of superconducting **air-core magnet coils**, the world's largest:  
**multiple scattering minimised!**
- **Stand-alone momentum resolution of 3-10 % for muon momenta of 10-1000 GeV.**
- High-precision muon tracking detectors, unprecedented in a collider experiment.
- Optical alignment monitoring system.

# Momentum determination with 3-point track-sagitta measurement

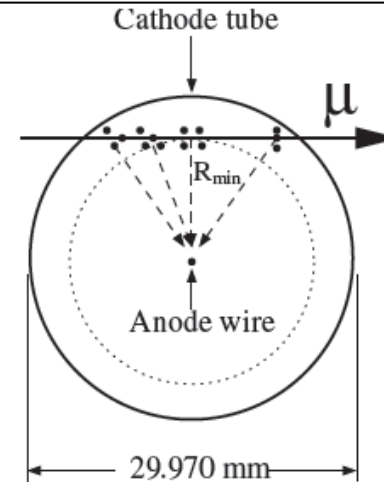
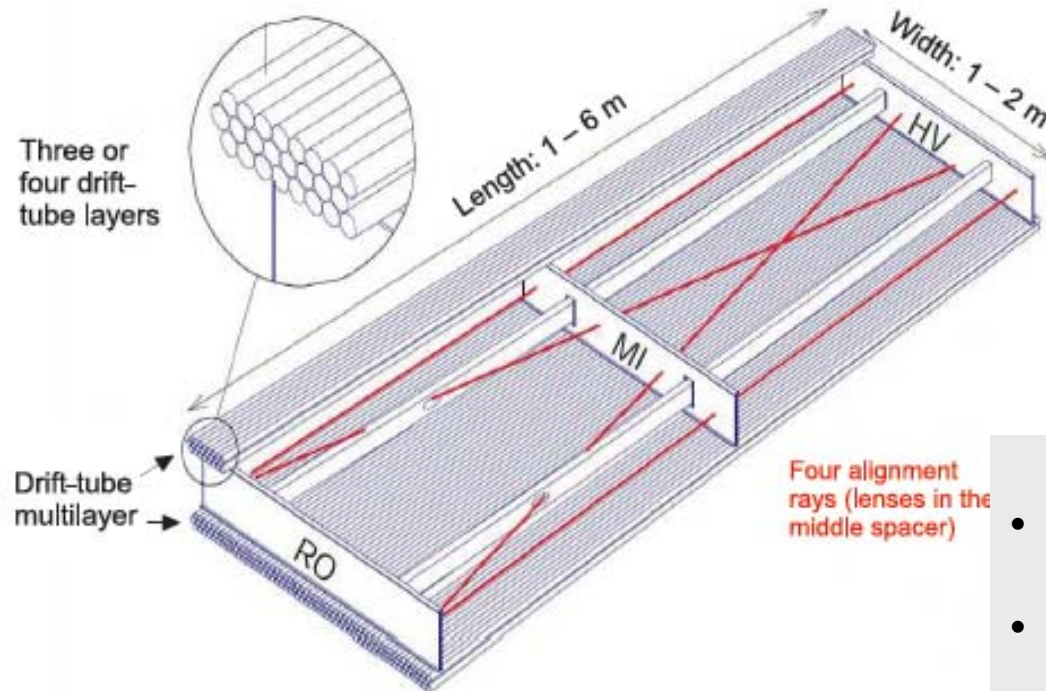
- Track sagitta of 1 TeV muon is 0.5 mm. Multiple scattering uncertainty small.
- ⇒ Sagitta has to be measured with 50  $\mu\text{m}$  accuracy for 10% momentum resol.



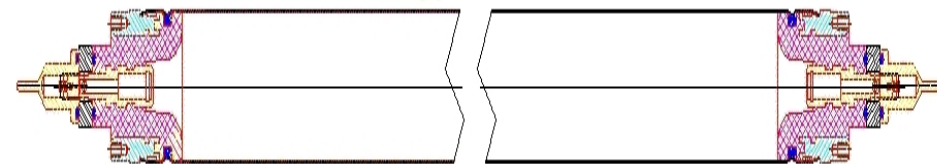
$$\rho_T = \frac{eL^2 \cdot B(\phi, \eta)}{8s} \quad \text{in the bending plane perpendicular to the B field}$$



# Precision Muon Tracking Detectors: the Monitored Drift-Tube (MDT) Chambers



- 6-8 layers of 30 mm  $\varnothing$  aluminum drift tubes with 400  $\mu\text{m}$  wall thickness
- filled with Ar:CO<sub>2</sub> (93:7) gas **at 3 bar pressure**
- Tube spatial resolution **80  $\mu\text{m}$**
- Sense wire pos. accuracy **20  $\mu\text{m}$**
- Chamber spatial resolution **35  $\mu\text{m}$**
- Maximum drift time **700 ns**



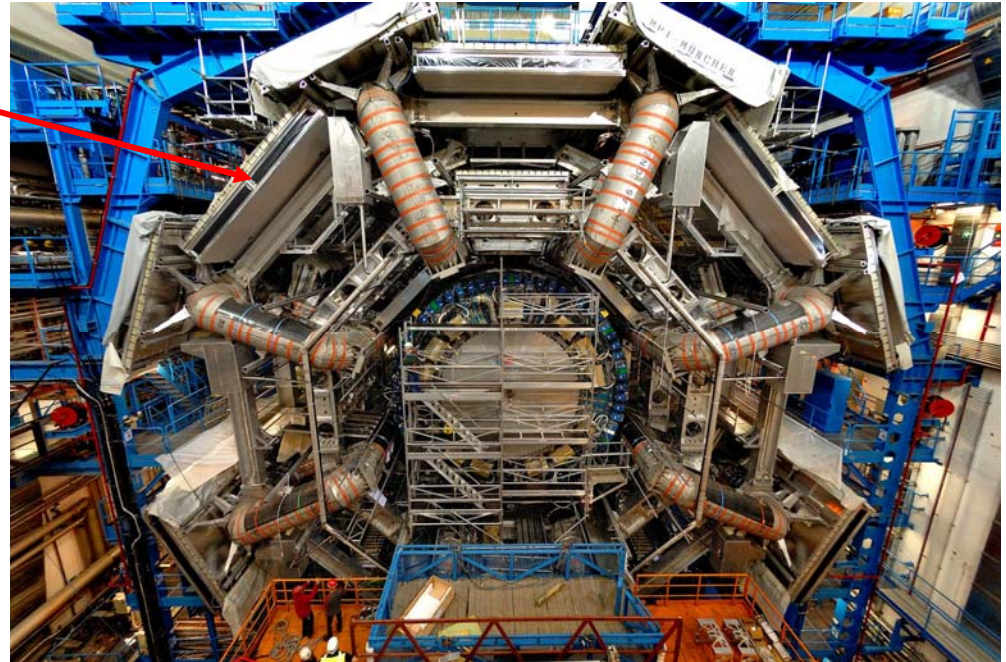
Anode wire precisely centered in the endplugs

1200 chambers with 370000 drift tubes (1000 km total length), 5000 m<sup>2</sup> detector area

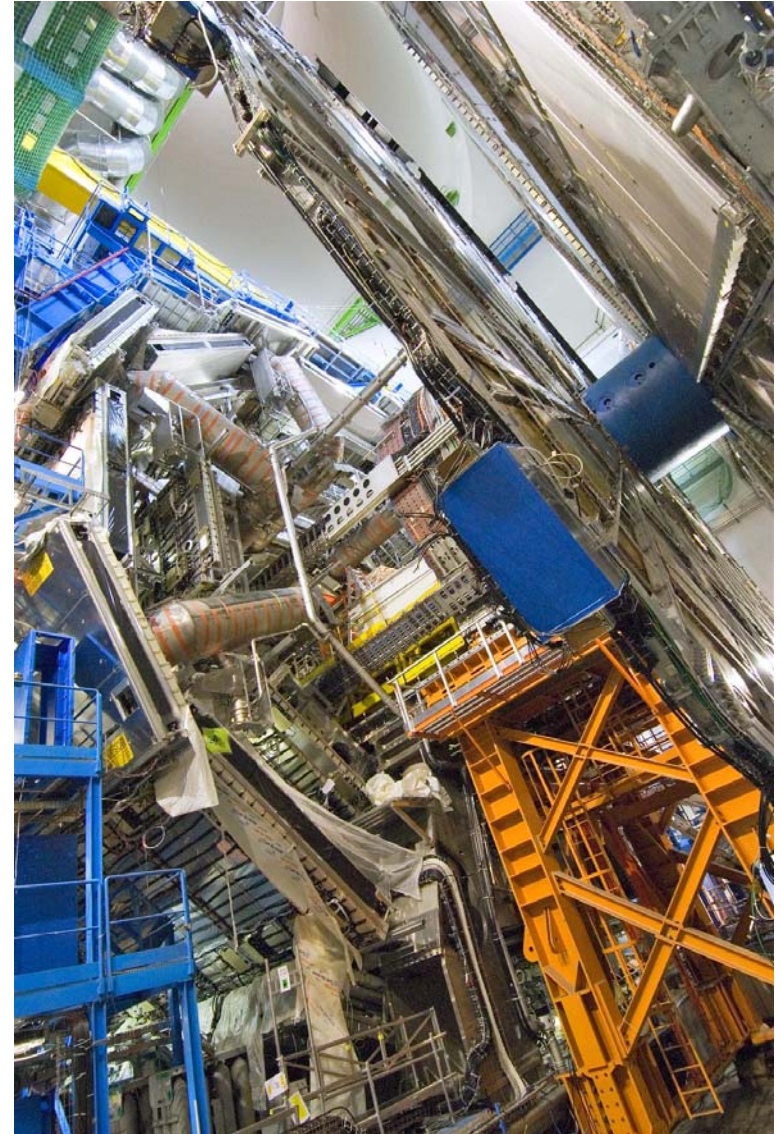
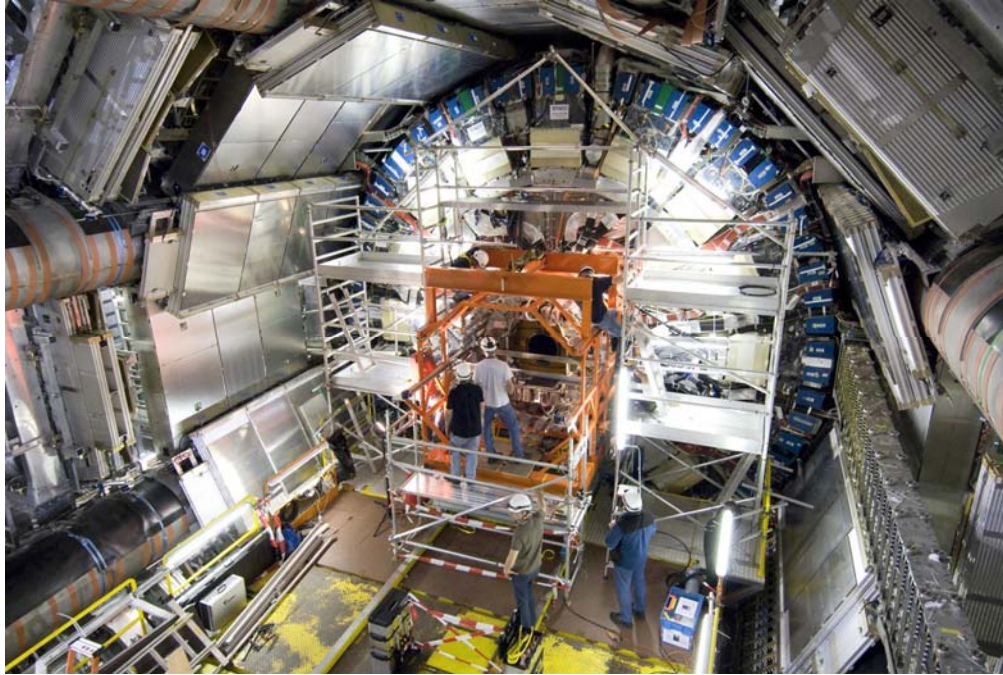
# MDT Precision Tracking Chambers



430 drift tubes per chamber,  
up to 6 m long



# MDT Precision Tracking Chambers in ATLAS

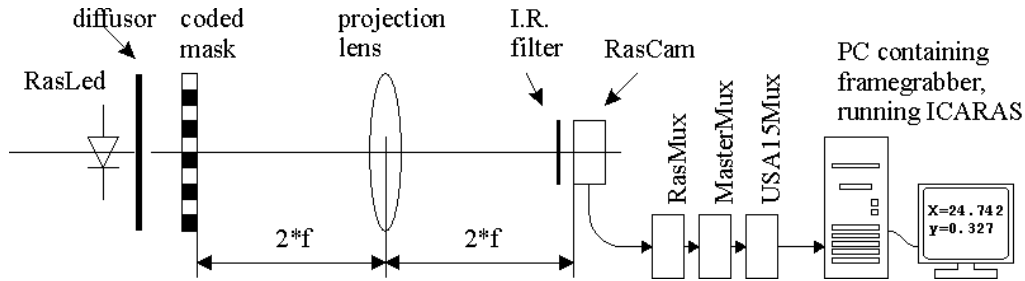


# Precision Optical Alignment Monitoring System

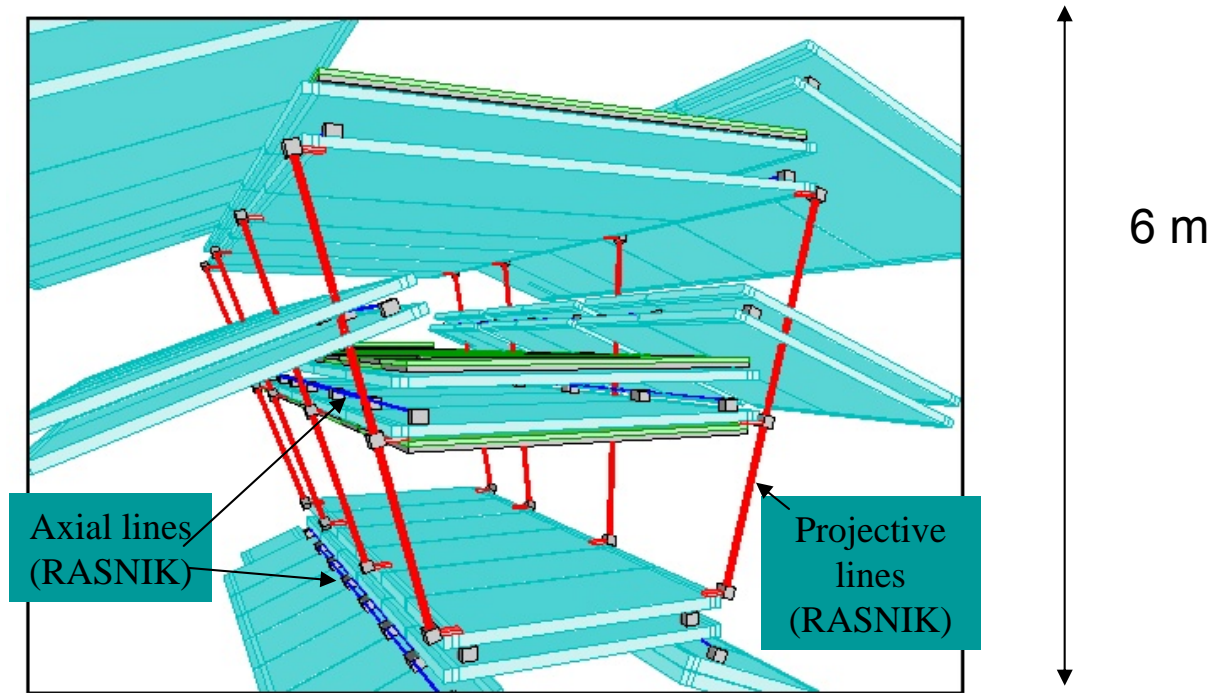
Continuous monitoring of the relative chamber positions

with few micron precision using optical straightness sensors (RASNIK).

→ Corrections on the track sagitta with 30  $\mu\text{m}$  accuracy.



Upgraded system from the one used in the L3 muon detector at LEP



# Muon Trigger Detectors

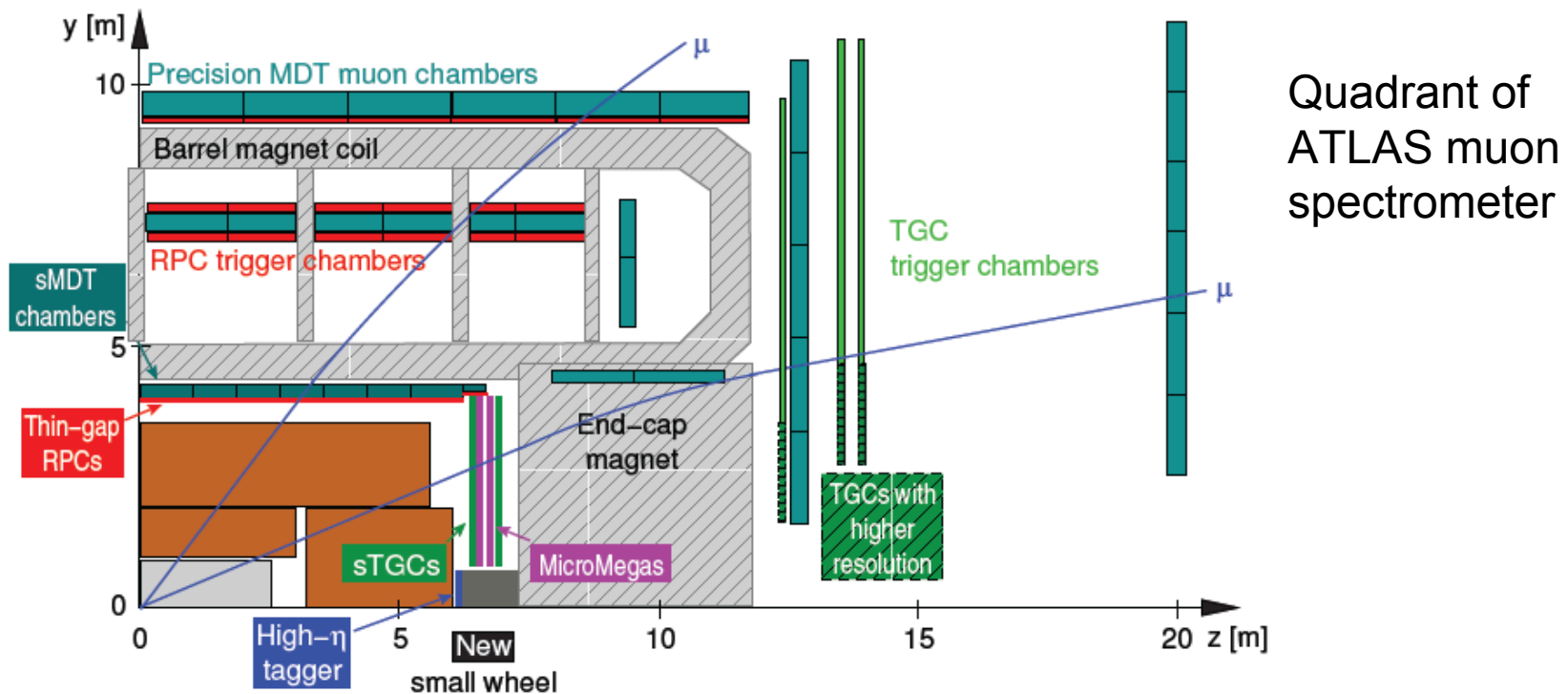
- First-level muon trigger crucial for collider, especially hadron collider experiments
- **Dedicated fast muon trigger detectors in ATLAS and CMS**

with few ns time resolution for LHC p bunch crossing identification and

for less precise 2<sup>nd</sup> coordinate information along the drift tubes:

**Resistive Plate chambers (RPC) and Thin Gap MWPC (TGC)** in present detectors

(also large-area GEM detectors (CMS) and Micromegas (ATLAS) for future upgrades)



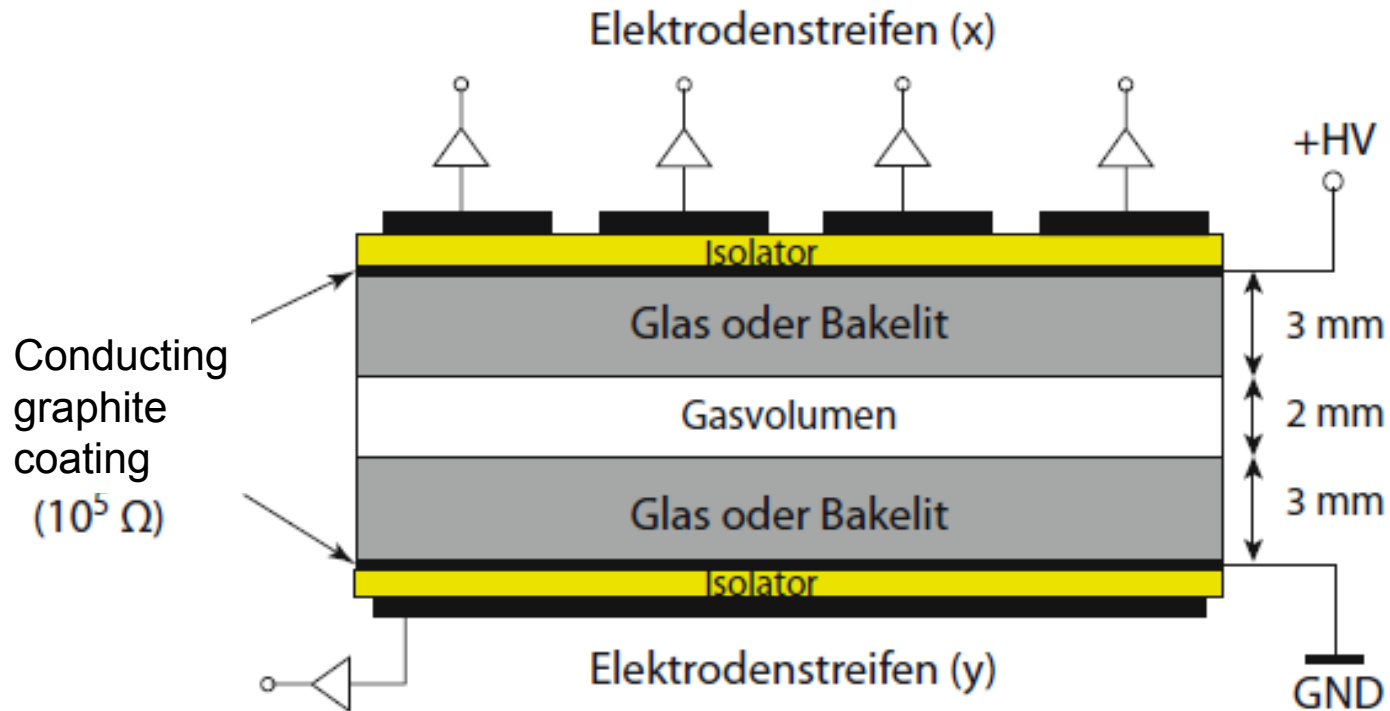
# Resistive Plate Chambers (RPC)

**Gas chambers without sense wires.** Technology for large areas.

High voltage of  $\sim 14$  kV applied between bakelite or glass panels over thin gas gap.

Ionisation by traversing charged particles causes **localised sparks** which create signals in crossed pick-up electrodes for 2D position information.

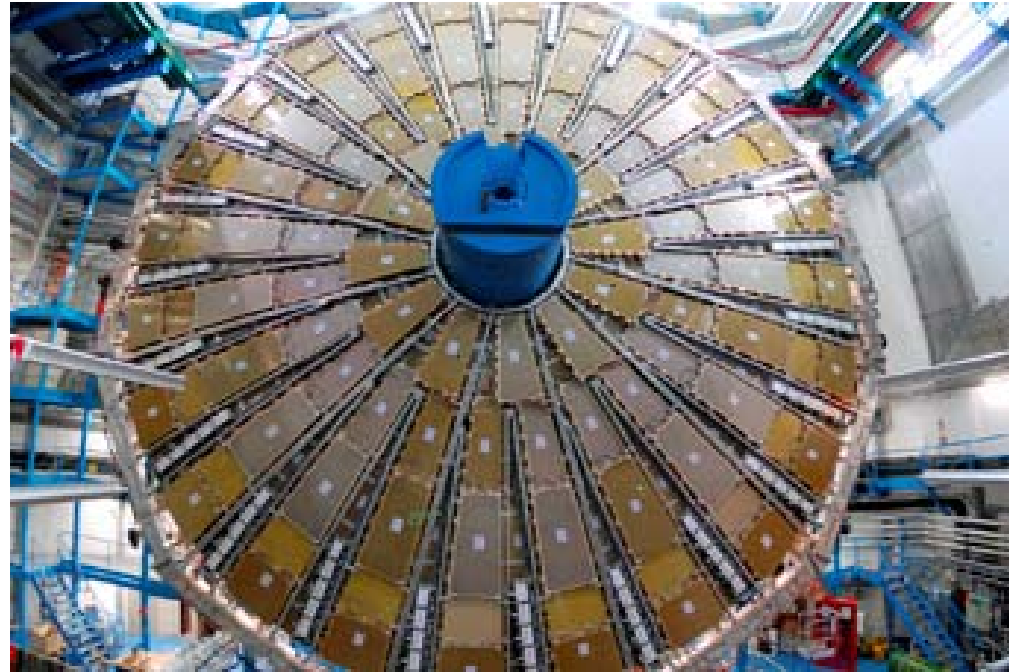
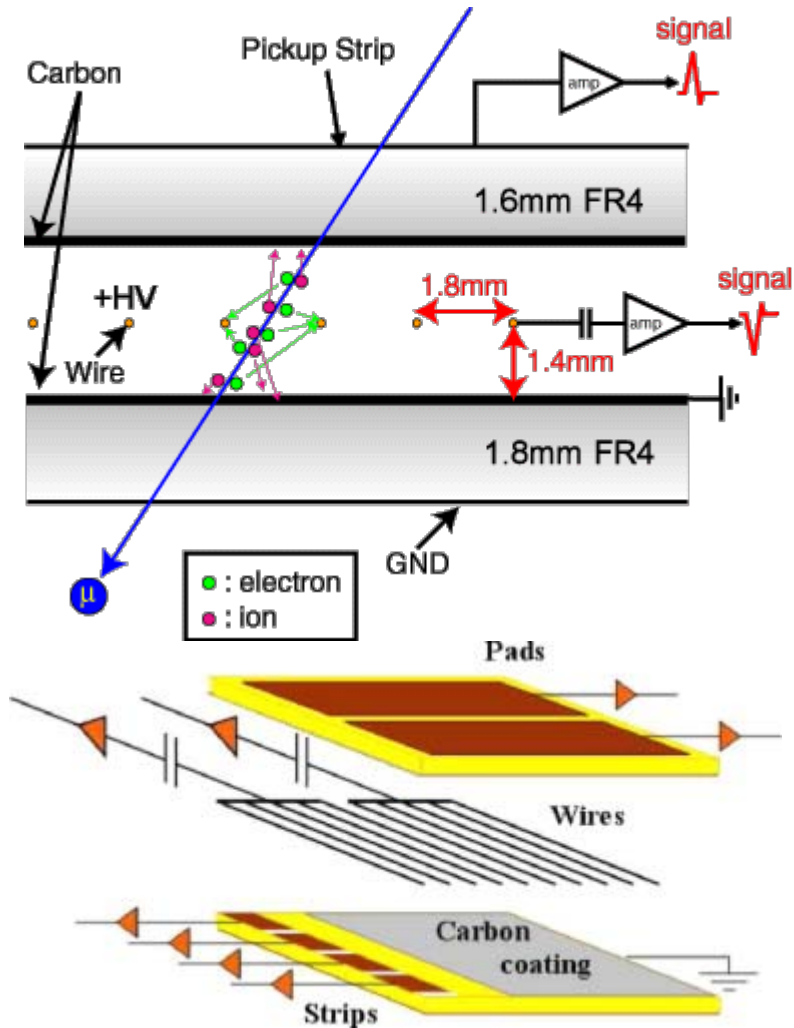
Rate capability and time resolution depend on the conductivity of the panels and their graphite coating.





# Thin Gap Chambers (TGC)

MWPC with single thin gas gap for fast response  
and with signal pick-up strips and/or pads for 2D position information.



ATLAS big endcap muon detector wheel

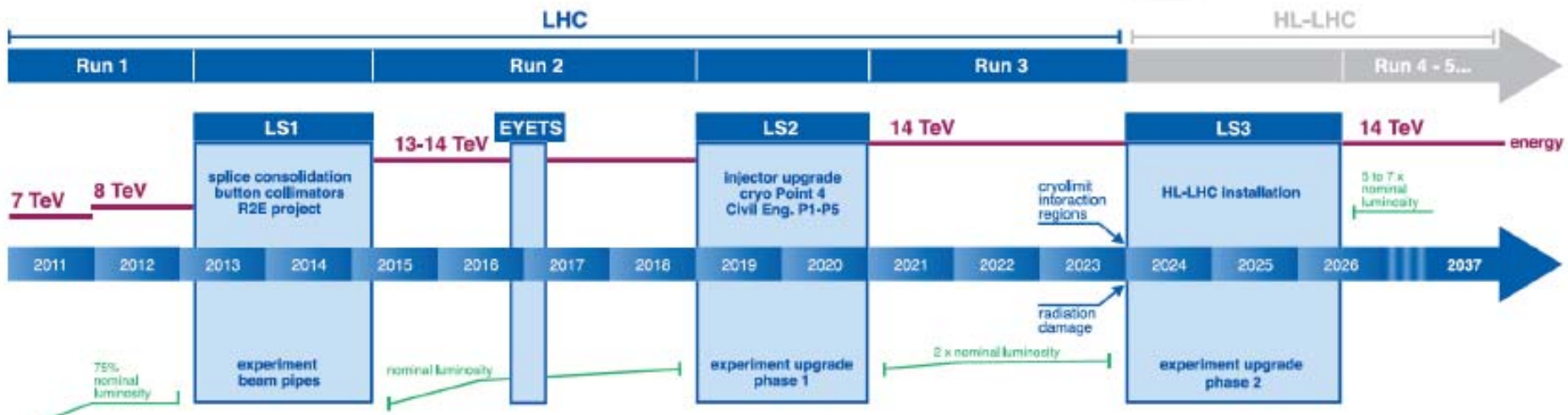
# Challenges at Future Colliders

Next highest energy hadron collider: **HL-LHC with 7.5 x LHC design luminosity** (just reached in run 2 at 13 TeV this year).

This means ~10 x higher radiation doses in the inner tracker and the calorimeters, average number of pile-up events 170 at 25 ns bunch crossing interval, **10 x higher neutron and  $\gamma$ -ray background rates in the muon chambers.**

**Unprecedentedly high background counting rates up to 2 kHz/cm<sup>2</sup> already in the present ATLAS and CMS muon detectors.**

## LHC / HL-LHC Plan

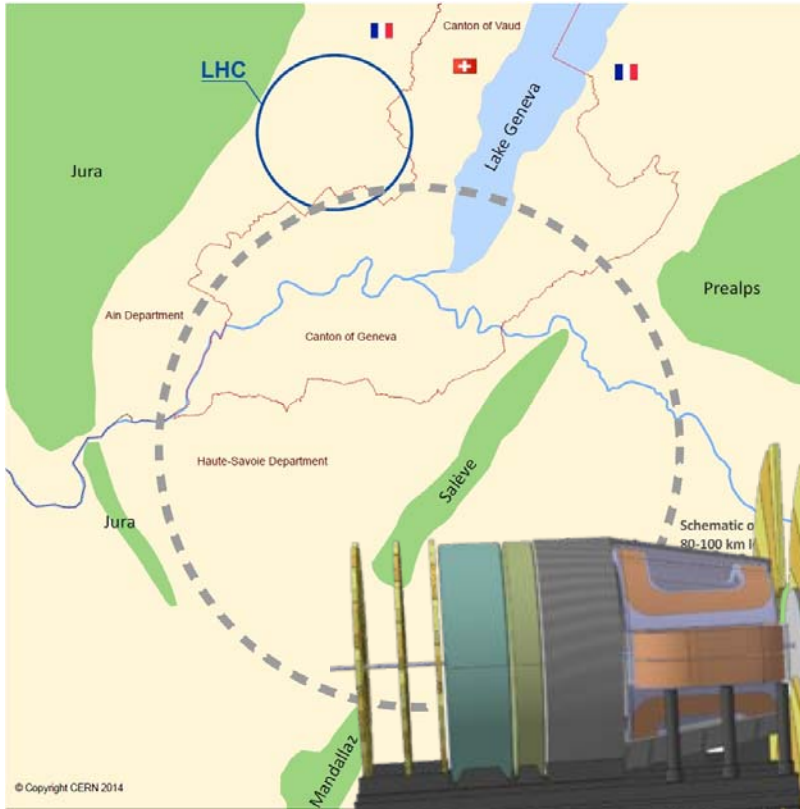


# At a Future Circular 100 TeV Hadron Collider (FCC-hh)

with ~80 km circumference and 30 x LHC design luminosity:

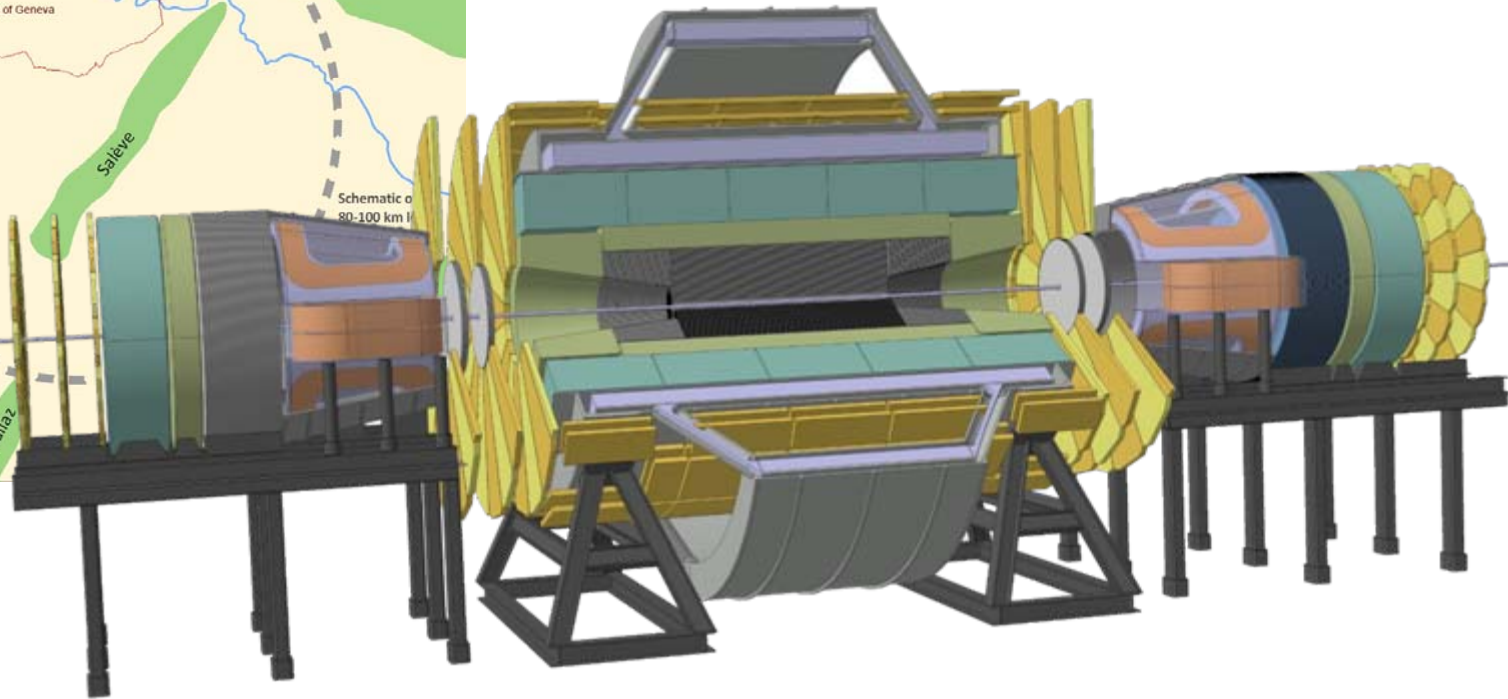
4 x higher background expected than at HL-LHC.

Pile-up up to 1000 (200) events at 25 (5) ns bunch crossing interval.



## FCC-hh Detector Concept

- Very high resolution **silicon inner tracker**
- Very large precision **muon gas detector area**
- High radiation hardness and **rate capability**.

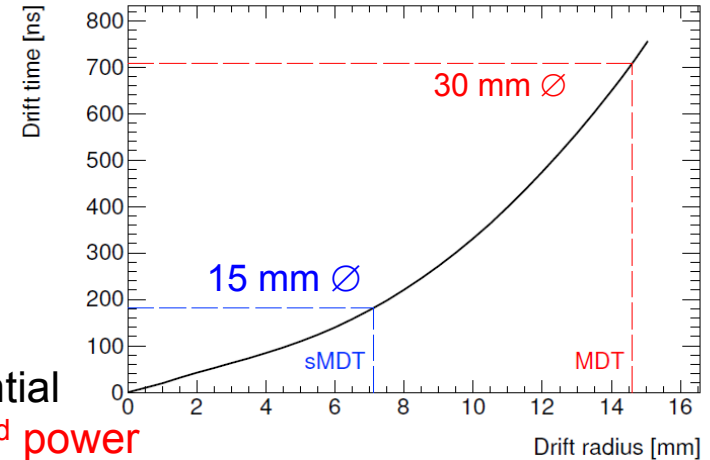


# High Rate Effects in Drift (Tube) Chambers

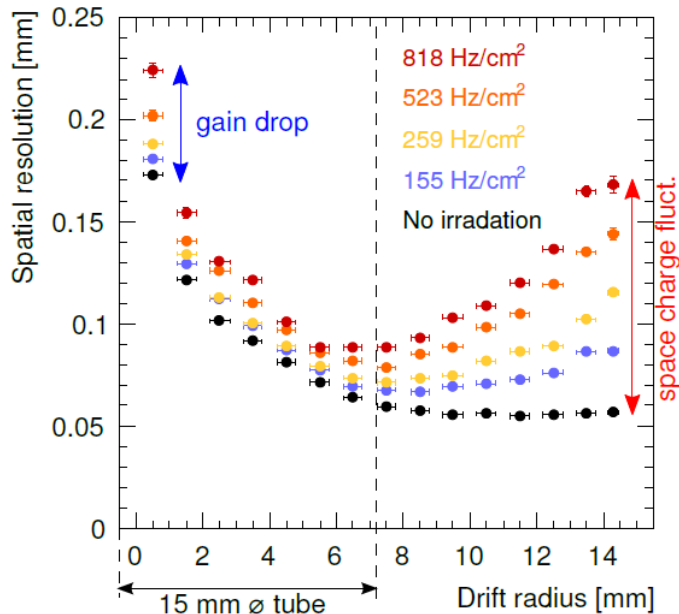
Spatial resolution deteriorated by

- Fluctuations of the space charge of slowly drifting ions caused by the ionising radiation and, therefore, of the drift field and the drift velocity of the electrons in the Ar:CO<sub>2</sub> gas which has good aging properties but non-linear r-t relation.

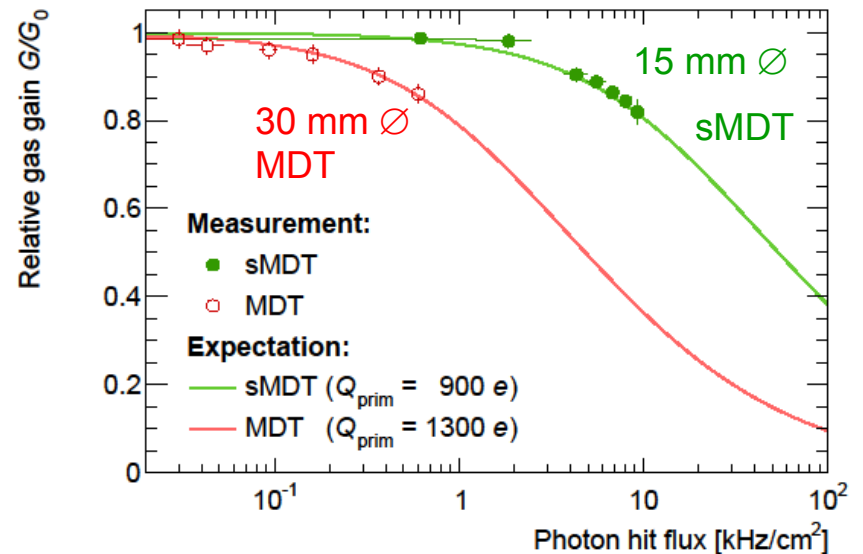
- Loss in gas amplification due to shielding of the wire potential by space charge proportional to drift tube diameter to the 3<sup>rd</sup> power ⇒ reduce the tube diameter: small-diameter MDT (sMDT) chambers



MDT drift tubes, Ar:CO<sub>2</sub> (93:7), 30 mm Ø



Gas gain prediction by Diethorn's formula



# Small-diameter Muon Drift Tube (sMDT) Chambers

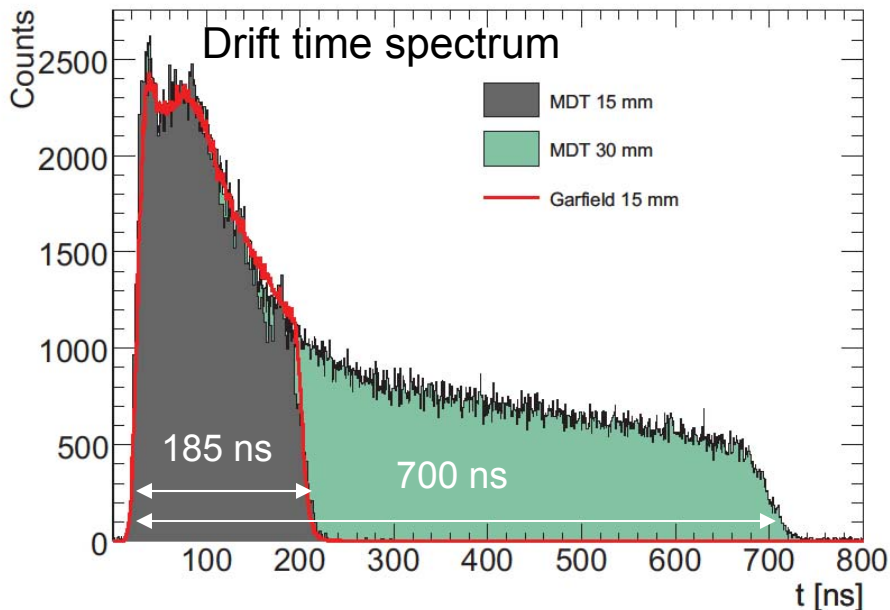
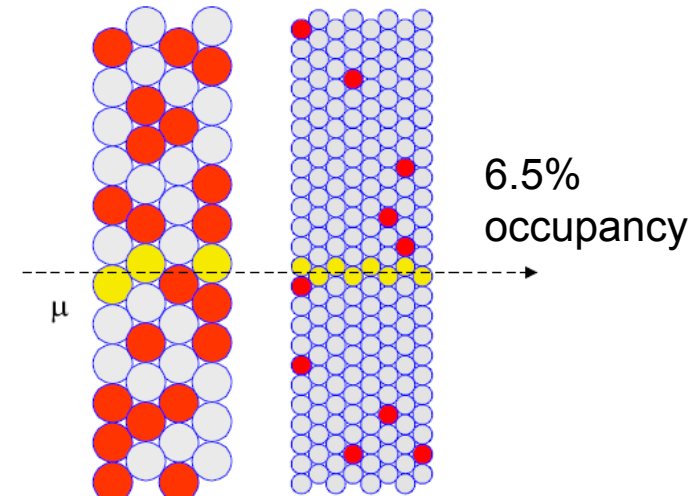
By reducing the drift tube diameter from 30 mm (MDT) to 15 mm (sMDT) at otherwise the unchanged operating conditions:

- 8 x lower background occupancy (4 x shorter maximum drift time, 2 x smaller tube cross section exposed to radiation).
- Electronics deadtime can be reduced.

⇒ increased drift tube and tracking efficiency at high rates



MDT 30 mm  $\varnothing$       sMDT 15 mm  $\varnothing$

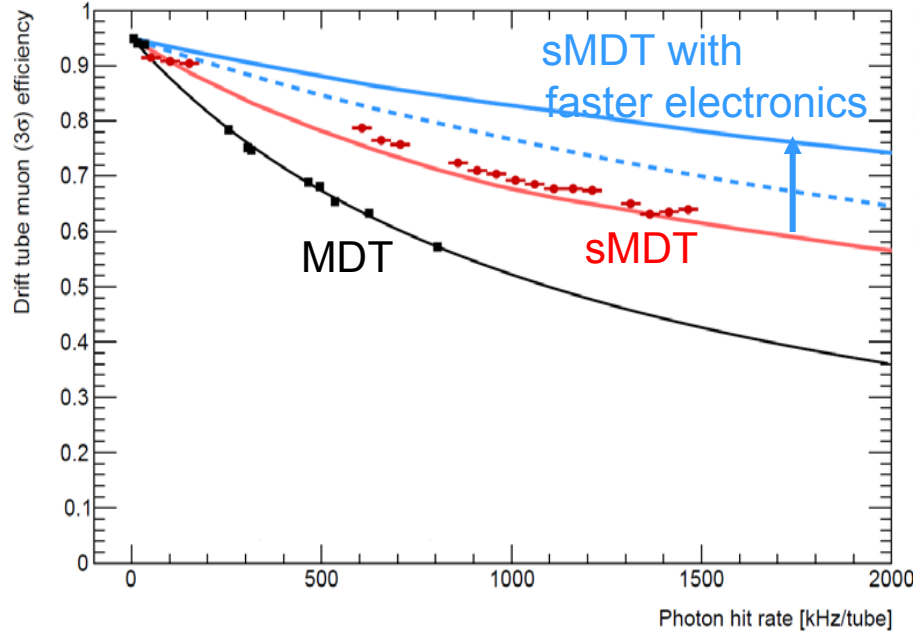


50%  
occupancy

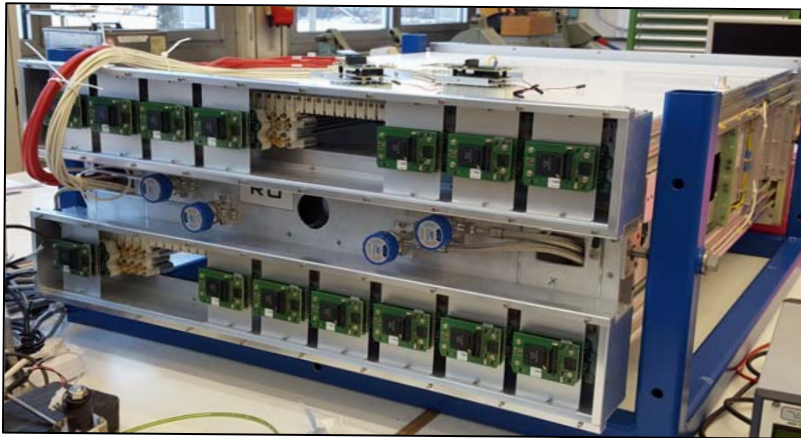
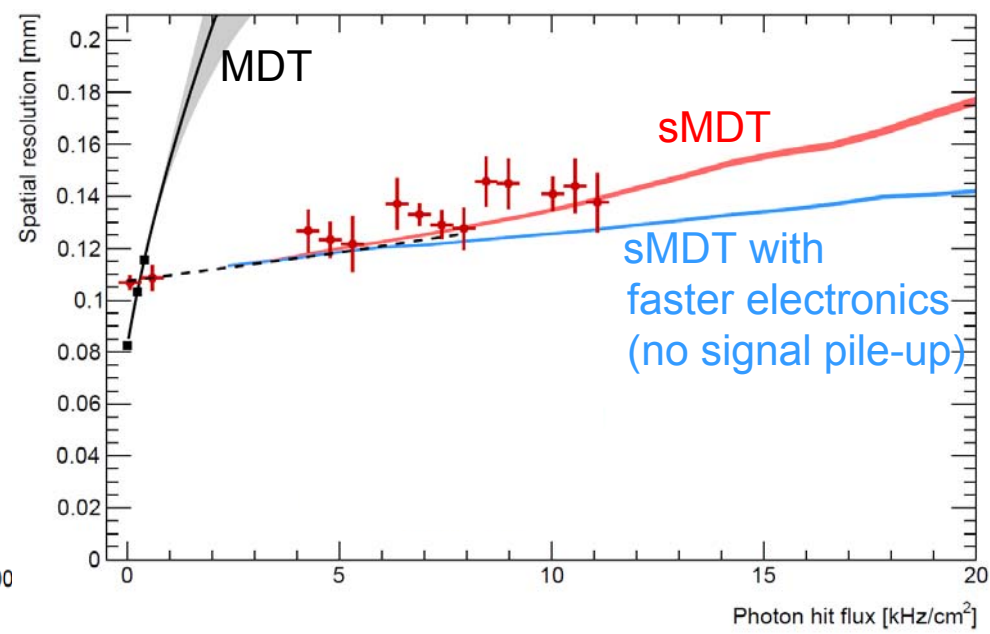
6.5%  
occupancy

# High-Rate Performance of Drift Tubes

## Drift tube muon detection efficiency



## Drift tube spatial resolution

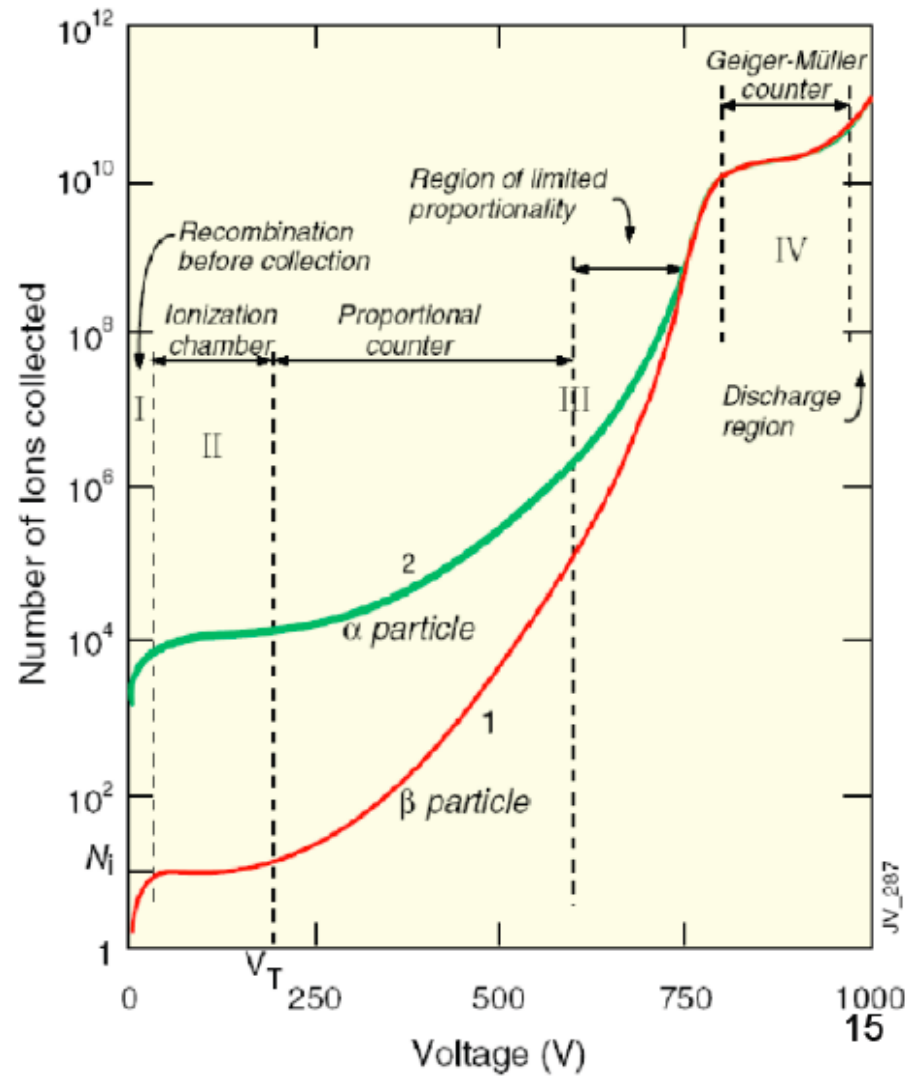


sMDT, thin-gap RPC and sTGC chambers used for ATLAS muon spectrometer upgrades for high luminosities at LHC.

Also suitable detectors for future even higher-energy hadron colliders.

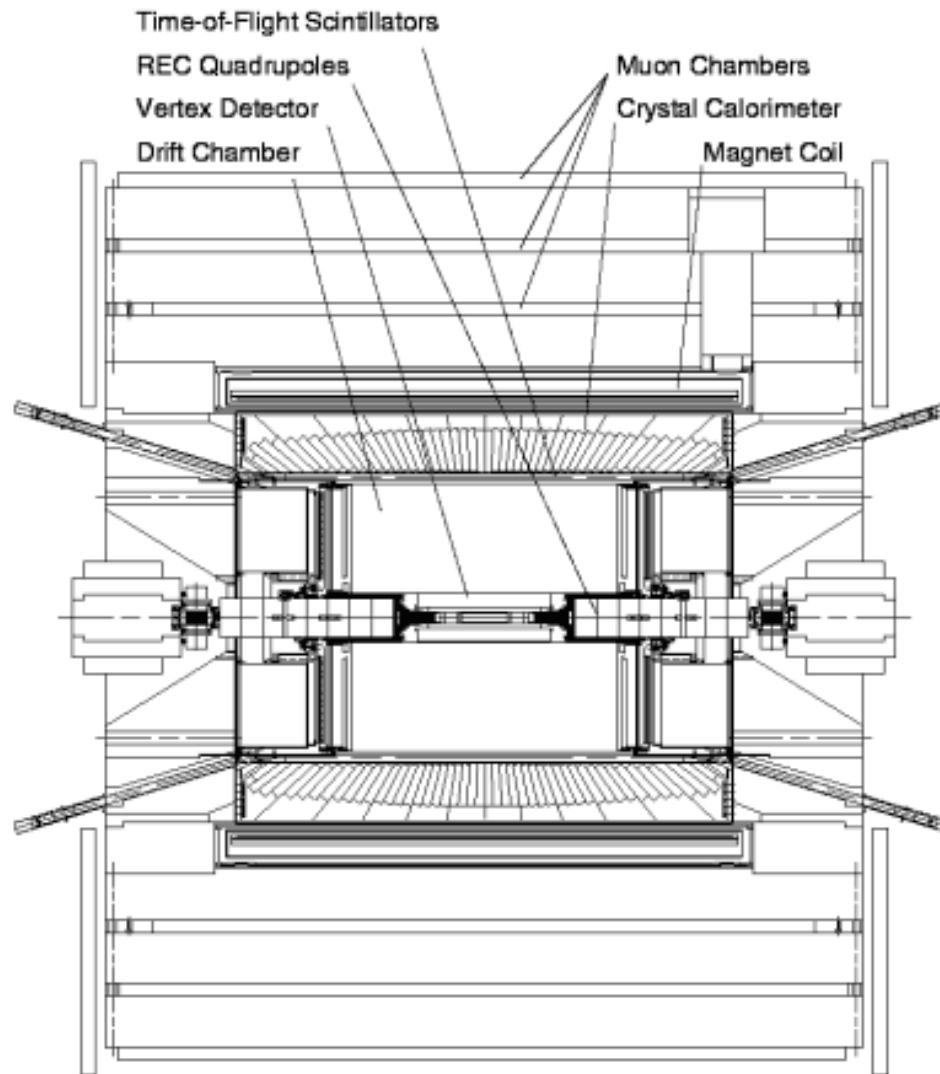
# The End

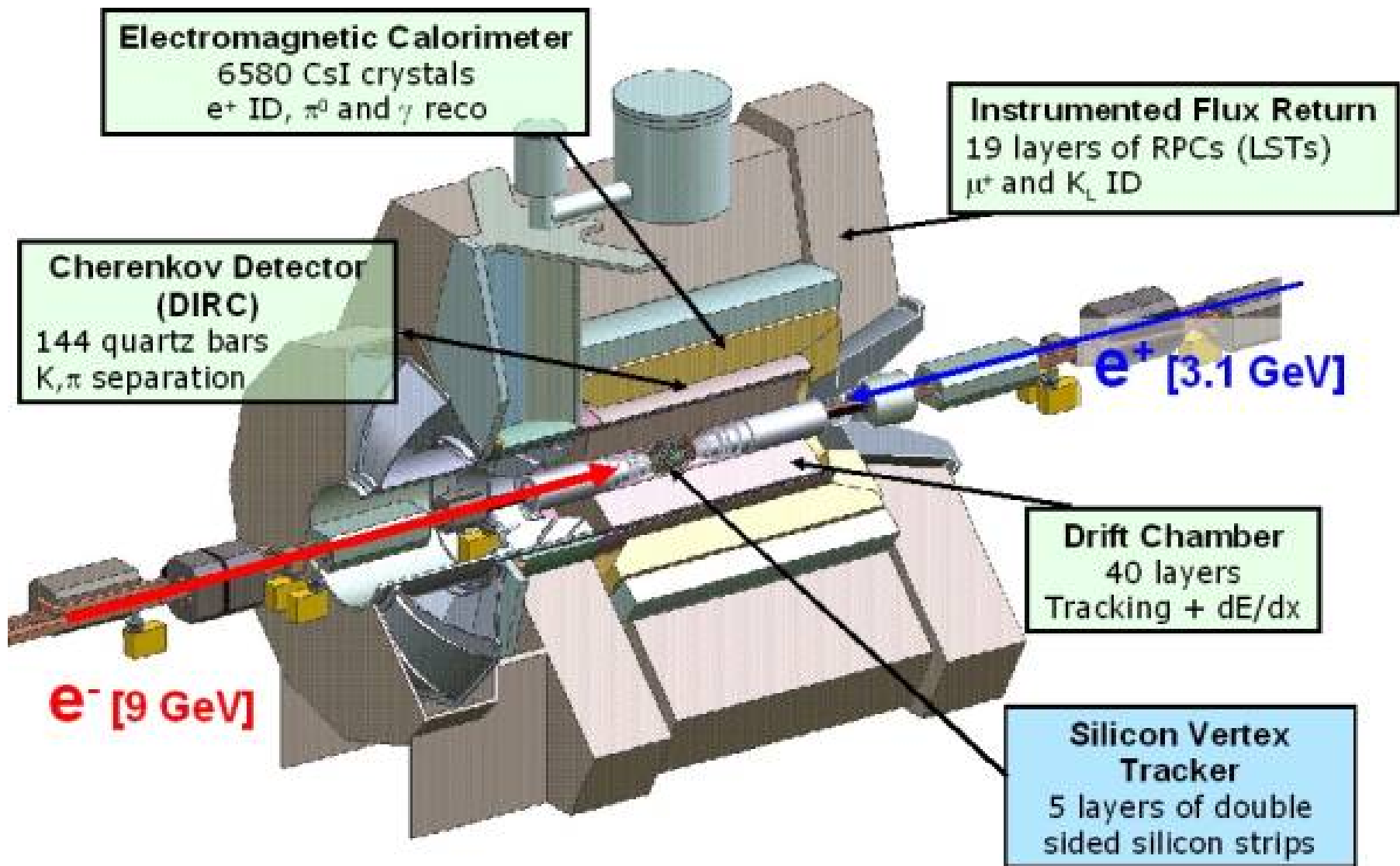
# Multi-wire gas detectors

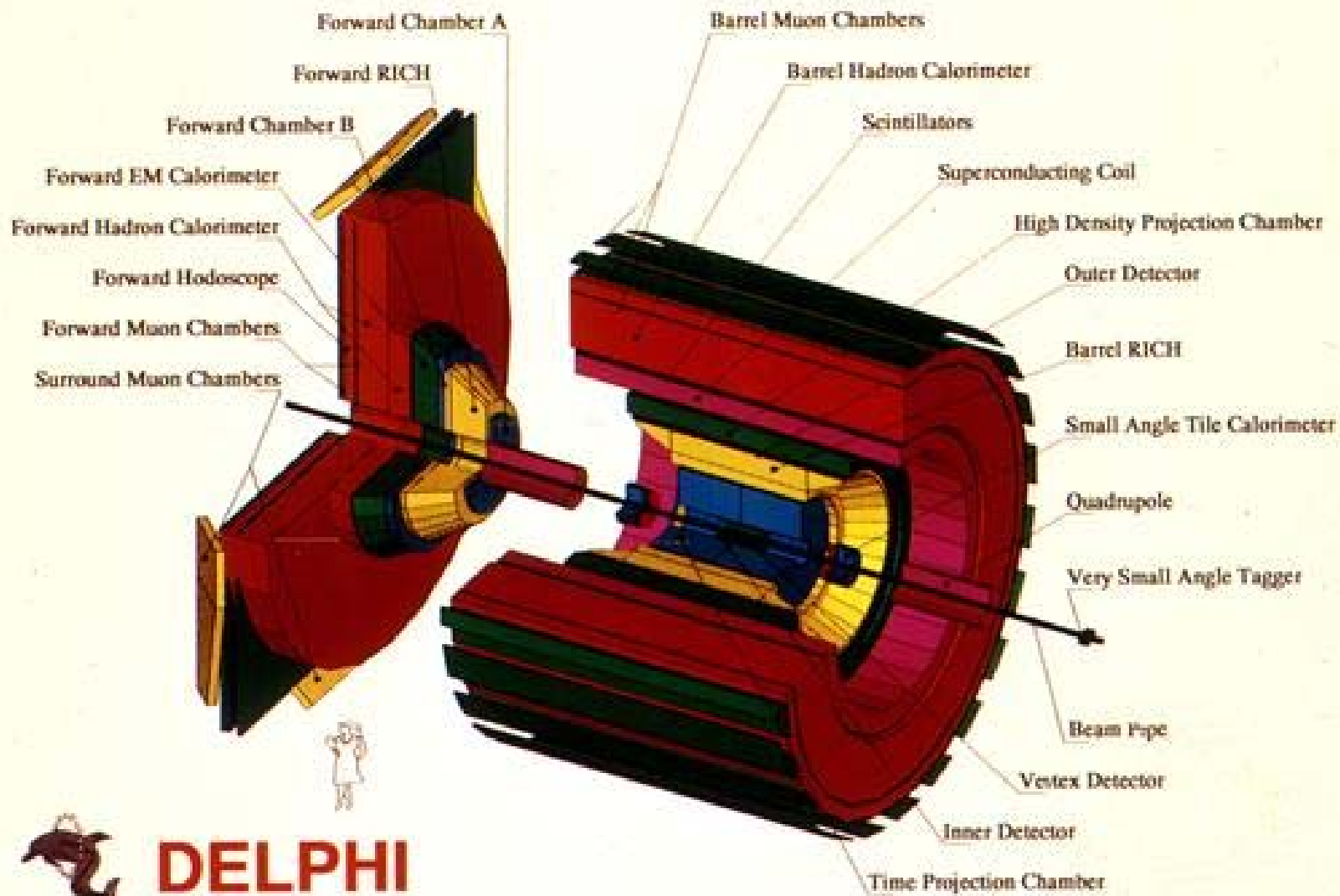


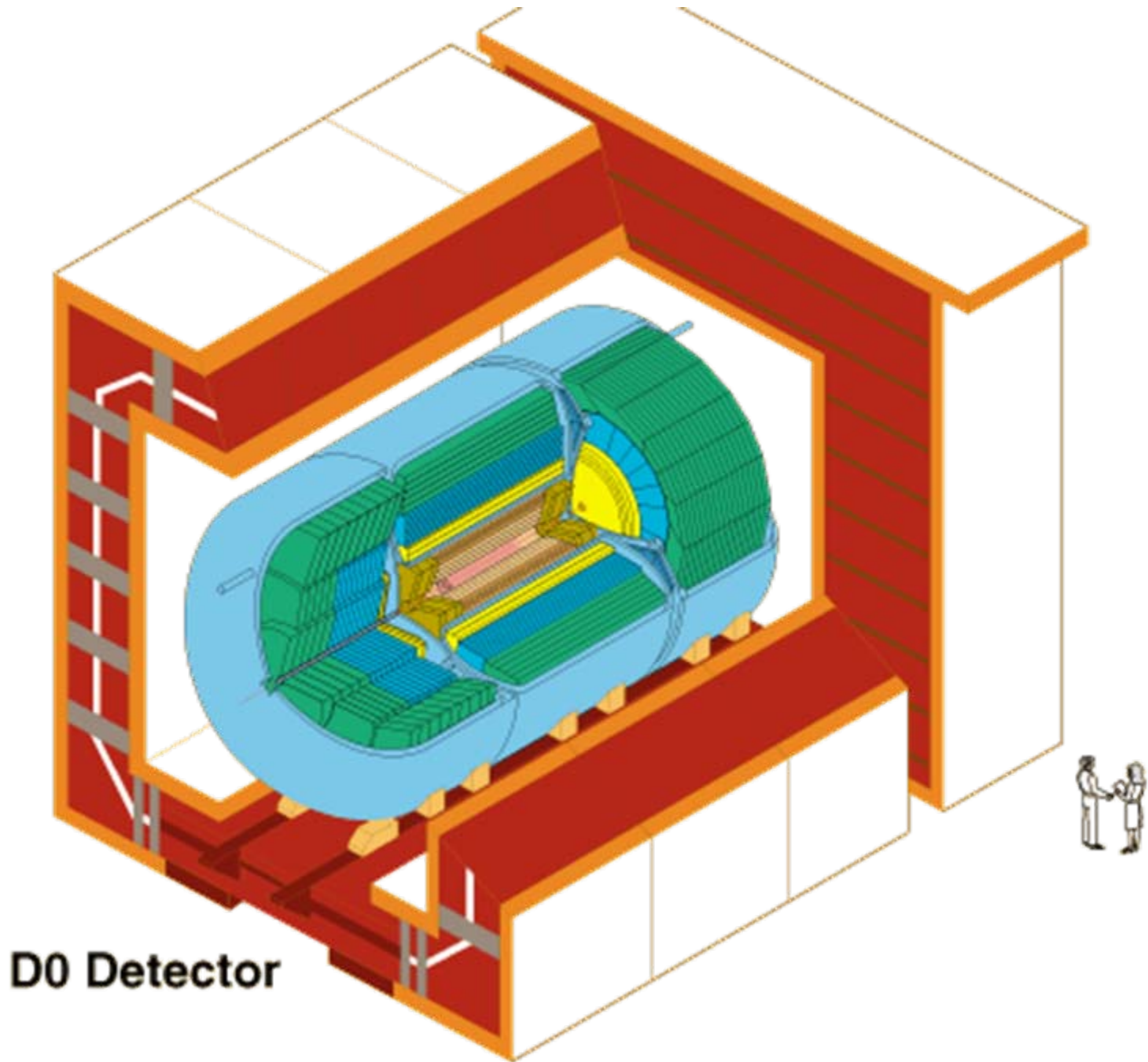


# CLEO II Detector









**D0 Detector**

